

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6149728

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST
CONVEYING PARTY DATA	
Name	Execution Date
ROYAL BANK OF CANADA	06/01/2020
RECEIVING PARTY DATA	
Name:	TESSERA, INC.
Street Address:	3025 ORCHARD PARKWAY
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95134
Name:	INVENSAS BONDING TECHNOLOGIES, INC. (F/K/A ZIPTRONIX, INC.)
Street Address:	3025 ORCHARD PARKWAY
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95134
Name:	FOTONATION CORPORATION (F/K/A DIGITALOPTICS CORPORATION AND F/K/A DIGITALOPTICS CORPORATION MEMS)
Street Address:	3025 ORCHARD PARKWAY
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95134
Name:	INVENSAS CORPORATION
Street Address:	3025 ORCHARD PARKWAY
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95134
Name:	TESSERA ADVANCED TECHNOLOGIES, INC
Street Address:	3025 ORCHARD PARKWAY
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95134
Name:	DTS, INC.
Street Address:	5220 LAS VIRGENES ROAD

City:	CALABASAS
State/Country:	CALIFORNIA
Postal Code:	91302
Name:	DTS LLC
Street Address:	5220 LAS VIRGENES ROAD
City:	CALABASAS
State/Country:	CALIFORNIA
Postal Code:	91302
Name:	PHORUS, INC.
Street Address:	16255 VENTURA BLVD.
Internal Address:	SUITE 310
City:	ENCINO
State/Country:	CALIFORNIA
Postal Code:	91436
Name:	IBIQUITY DIGITAL CORPORATION
Street Address:	6711 COLUMBIA GATEWAY
Internal Address:	SUITE 500
City:	COLUMBIA
State/Country:	MARYLAND
Postal Code:	21046

PROPERTY NUMBERS Total: 2087

Property Type	Number
Application Number:	09920499
Application Number:	10560717
Application Number:	11958783
Application Number:	12287380
Application Number:	12842612
Application Number:	13183920
Application Number:	13449640
Application Number:	13452494
Application Number:	13592182
Application Number:	13606918
Application Number:	13795756
Application Number:	13838697
Application Number:	13862036
Application Number:	13867770
Application Number:	13961217
Application Number:	13962332

Property Type	Number
Application Number:	13962349
Application Number:	14010405
Application Number:	14026984
Application Number:	14027571
Application Number:	14036684
Application Number:	14050215
Application Number:	14053481
Application Number:	14089539
Application Number:	14096387
Application Number:	14096906
Application Number:	14101287
Application Number:	14145288
Application Number:	14157790
Application Number:	14168386
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Application Number:	14201655
Application Number:	14206756
Application Number:	14206868
Application Number:	14214365
Application Number:	14245882
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Application Number:	14266907
Application Number:	14271959
Application Number:	14275519
Application Number:	14286159
Application Number:	14289483
Application Number:	14289860
Application Number:	14309703
Application Number:	14327490
Application Number:	14338327
Application Number:	14466992
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Application Number:	14474501
Application Number:	14480373
Application Number:	14482981
Application Number:	14488187
Application Number:	14492964
Application Number:	14496159

Property Type	Number
Application Number:	14500858
Application Number:	14500874
Application Number:	14506187
Application Number:	14507722
Application Number:	14523245
Application Number:	14524280
Application Number:	14529279
Application Number:	14532396
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Application Number:	14639789
Application Number:	14639942
Application Number:	14645811
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Property Type	Number
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Application Number:	14718719
Application Number:	14720605
Application Number:	14725975
Application Number:	14727810
Application Number:	14729729
Application Number:	14733269
Application Number:	14733780
Application Number:	14740184
Application Number:	14746425
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Application Number:	15066983
Application Number:	15069131
Application Number:	15075899
Application Number:	15076383
Application Number:	15076467
Application Number:	15078945
Application Number:	15082951
Application Number:	15086693
Application Number:	15094087
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Application Number:	15143077
Application Number:	15144108
Application Number:	15149458
Application Number:	15150295
Application Number:	15151176
Application Number:	15153188
Application Number:	15156667
Application Number:	15158963
Application Number:	15159287
Application Number:	15165323
Application Number:	15165837
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Application Number:	15166920
Application Number:	15168789
Application Number:	15171604
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Application Number:	15174983
Application Number:	15181861
Application Number:	15181872
Application Number:	15236416
Application Number:	15242141
Application Number:	15242396

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Application Number:	15253646
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Application Number:	15290392
Application Number:	62290394
Application Number:	62332872
Application Number:	62351585
Application Number:	62381479
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Patent Number:	5903049
Patent Number:	5912976
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Patent Number:	5940851
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Patent Number:	5980663
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Patent Number:	5987574
Patent Number:	5989936
Patent Number:	5989939
Patent Number:	5994222
Patent Number:	5994726
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Patent Number:	6031271
Patent Number:	6031288
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Patent Number:	6043699
Patent Number:	6046076
Patent Number:	6049972
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Patent Number:	6054337
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Patent Number:	6083837
Patent Number:	6084310
Patent Number:	6086386
Patent Number:	6090661
Patent Number:	6095582
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Patent Number:	6128334
Patent Number:	6128350
Patent Number:	6130115
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Patent Number:	6130449
Patent Number:	6130476
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Patent Number:	6133072
Patent Number:	6133136
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Patent Number:	6172384
Patent Number:	6177295
Patent Number:	6177699
Patent Number:	6177707
Patent Number:	6178317
Patent Number:	6180020
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Patent Number:	6198117
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Patent Number:	6200143
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Patent Number:	6201301
Patent Number:	6202298
Patent Number:	6203684
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Patent Number:	6207595
Patent Number:	6208020
Patent Number:	6208024
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Patent Number:	6208546
Patent Number:	6210555
Patent Number:	6211003
Patent Number:	6211690
Patent Number:	6217972
Patent Number:	6218213
Patent Number:	6218215

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Patent Number:	6221750
Patent Number:	6222269
Patent Number:	6222785
Patent Number:	6225657
Patent Number:	6225833
Patent Number:	6226616
Patent Number:	6227637
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Patent Number:	6229100
Patent Number:	6229379
Patent Number:	6232152
Patent Number:	6232231
Patent Number:	6239384
Patent Number:	6242794
Patent Number:	6243424
Patent Number:	6247228
Patent Number:	6248656
Patent Number:	6251766
Patent Number:	6253992
Patent Number:	6255723
Patent Number:	6255738
Patent Number:	6256702
Patent Number:	6259651
Patent Number:	6259893
Patent Number:	6261375
Patent Number:	6261863
Patent Number:	6261939
Patent Number:	6266872
Patent Number:	6266874
Patent Number:	6268658
Patent Number:	6271541
Patent Number:	6271598
Patent Number:	6274822
Patent Number:	6278653
Patent Number:	6281026
Patent Number:	6281581

Property Type	Number
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Patent Number:	6285767
Patent Number:	6287976
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Patent Number:	6291352
Patent Number:	6291776
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Patent Number:	6295317
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Patent Number:	6300231
Patent Number:	6300254
Patent Number:	6300833
Patent Number:	6301176
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Patent Number:	6306752
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Patent Number:	6307260
Patent Number:	6309528
Patent Number:	6309910
Patent Number:	6309915
Patent Number:	6309937
Patent Number:	6310386
Patent Number:	6313528
Patent Number:	6317007
Patent Number:	6317333
Patent Number:	6317470
Patent Number:	6317974
Patent Number:	6319384
Patent Number:	6319801
Patent Number:	6321993
Patent Number:	6322903
Patent Number:	6323134

Property Type	Number
Patent Number:	6324110
Patent Number:	6324754
Patent Number:	6329224
Patent Number:	6329278
Patent Number:	6329605
Patent Number:	6329680
Patent Number:	6330967
Patent Number:	6332569
Patent Number:	6333207
Patent Number:	6334942
Patent Number:	6335104
Patent Number:	6335222
Patent Number:	6335565
Patent Number:	6335571
Patent Number:	6337509
Patent Number:	6338982
Patent Number:	6338984
Patent Number:	6340632
Patent Number:	6340793
Patent Number:	6341418
Patent Number:	6342434
Patent Number:	6345377
Patent Number:	6347732
Patent Number:	6355298
Patent Number:	6357112
Patent Number:	6358780
Patent Number:	6359335
Patent Number:	6361415
Patent Number:	6361959
Patent Number:	6362520
Patent Number:	6362529
Patent Number:	6362997
Patent Number:	6365452
Patent Number:	6365513
Patent Number:	6365975
Patent Number:	6368930
Patent Number:	6369418
Patent Number:	6370032

Property Type	Number
Patent Number:	6370073
Patent Number:	6372620
Patent Number:	6373096
Patent Number:	6373141
Patent Number:	6374487
Patent Number:	6376304
Patent Number:	6378758
Patent Number:	6380060
Patent Number:	6380567
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Patent Number:	6392942
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Patent Number:	6410981
Patent Number:	6414353
Patent Number:	6414386
Patent Number:	6414897
Patent Number:	6417029
Patent Number:	6417035
Patent Number:	6420209
Patent Number:	6420227

Property Type	Number
Patent Number:	6423148
Patent Number:	6423907
Patent Number:	6423923
Patent Number:	6424028
Patent Number:	6425103
Patent Number:	6428328
Patent Number:	6429112
Patent Number:	6430227
Patent Number:	6432799
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Patent Number:	6433285
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Patent Number:	6465878
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Property Type	Number
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Patent Number:	6486002
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Patent Number:	6488198
Patent Number:	6489571
Patent Number:	6489649
Patent Number:	6489674
Patent Number:	6492201
Patent Number:	6492251
Patent Number:	6492719
Patent Number:	6493932
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Patent Number:	6496404
Patent Number:	6498074
Patent Number:	6498381
Patent Number:	6500694
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Patent Number:	6501115
Patent Number:	6501156
Patent Number:	6503788
Patent Number:	6503803
Patent Number:	6504780
Patent Number:	6509224

Property Type	Number
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Patent Number:	6512176
Patent Number:	6512298
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Patent Number:	6518160
Patent Number:	6518662
Patent Number:	6518677
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Patent Number:	6543131
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Patent Number:	6549483
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Patent Number:	6554469
Patent Number:	6555464

Property Type	Number
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Property Type	Number
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Patent Number:	6625078
Patent Number:	6627039
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Patent Number:	6627531
Patent Number:	6627536
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Property Type	Number
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Patent Number:	6682996
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Patent Number:	6683554
Patent Number:	6686015
Patent Number:	6687133
Patent Number:	6687980
Patent Number:	6688662
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Property Type	Number
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Property Type	Number
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Patent Number:	6848173
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Property Type	Number
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Patent Number:	6992396
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Patent Number:	7196303

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Patent Number:	7465629
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Patent Number:	7473997
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Patent Number:	7521276
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Patent Number:	7521785
Patent Number:	7522456
Patent Number:	7522733
Patent Number:	7528009
Patent Number:	7528036
Patent Number:	7534652
Patent Number:	7535093
Patent Number:	7535109

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Patent Number:	7538416
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Patent Number:	7542517
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Patent Number:	7684229

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Patent Number:	7759166
Patent Number:	7759782
Patent Number:	7763983
Patent Number:	7764802

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Patent Number:	7769281
Patent Number:	7769284
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Patent Number:	7816280
Patent Number:	7825026
Patent Number:	7829438
Patent Number:	7829995
Patent Number:	7832948
Patent Number:	7838322
Patent Number:	7838983
Patent Number:	7839006

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Patent Number:	7851904
Patent Number:	7852672
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Patent Number:	7858444
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Patent Number:	7923828
Patent Number:	7923851
Patent Number:	7929708
Patent Number:	7930184

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Patent Number:	7935569
Patent Number:	7935571
Patent Number:	7936062
Patent Number:	7939918
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Patent Number:	7944195
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Patent Number:	7952133
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Patent Number:	8008966
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Patent Number:	8014662
Patent Number:	8017452
Patent Number:	8019311
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Patent Number:	8022527
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Patent Number:	8093697

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Patent Number:	8099285
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Patent Number:	8110911
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Patent Number:	8269319
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Patent Number:	8279908
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Patent Number:	8325519
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Patent Number:	8337103
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Patent Number:	8338963
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Patent Number:	8351843
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Patent Number:	8395267
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Patent Number:	D716254
Patent Number:	RE44726
Patent Number:	RE45463
Patent Number:	RE45698

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ATTORNEY DOCKET NUMBER:	107980/17
NAME OF SUBMITTER:	WILLIAM J. CASEY
SIGNATURE:	/William J. Casey/
DATE SIGNED:	06/11/2020
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 200

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RELEASE OF SECURITY INTEREST
IN PATENTS

THIS RELEASE OF SECURITY INTEREST IN PATENTS (“*Release*”) is made as of as of June 1, 2020 (the “*Effective Date*”) from ROYAL BANK OF CANADA, as Collateral Agent for the Secured Parties (in such capacity, the “*Agent*”) to TESSERA, INC., INVENSAS BONDING TECHNOLOGIES, INC. (f/k/a Ziptronix, Inc.), FOTONATION CORPORATION (f/k/a DigitalOptics Corporation and f/k/a DigitalOptics Corporation MEMS), INVENSAS CORPORATION, TESSERA ADVANCED TECHNOLOGIES, INC., DTS, INC., DTS LLC, PHORUS, INC. and IBIQUITY DIGITAL CORPORATION (each a “*Grantor*” and collectively, the “*Grantors*”). All capitalized terms used but not defined herein have the meaning ascribed to them in the Patent Security Agreement, dated as of December 1, 2016, by and among Grantors and Agent (the “*Patent Security Agreement*”).

WHEREAS, each Grantor was party to a Security Agreement (as amended, modified or supplemented in accordance with its terms, the “*Security Agreement*”) dated as of December 1, 2016 in favor of the Agent and for the benefit of the Secured Parties;

WHEREAS, pursuant to the Security Agreement, the Grantor and the Agent entered into the Patent Security Agreement;

WHEREAS, as of the Effective Date, all amounts owing and due under the Security Agreement were repaid, and upon such payment all security interests granted to Agent under the Security Agreement were released and terminated and Agent wishes to further evidence such release;

WHEREAS, pursuant to the Patent Security Agreement, as collateral security for the payment and performance in full of all Secured Obligations, each Grantor pledged and granted to the Agent, for the benefit of the Secured Parties, a lien on and security interest in all of the right, title and interest of such Grantor in, to and under the following property, wherever located, and whether now existing or thereafter arising or acquired from time to time (collectively, the “*Patent Collateral*”): (a) all patents and all patent applications (whether issued, allowed or filed in the United States or any other country or any trans-national patent registry) of such Grantor then or thereafter, owned, filed or acquired by, or assigned to, such Grantor, including the patents and patent applications listed on Exhibit A attached hereto, together with any and all (i) rights and privileges arising under applicable law with respect to the foregoing and all rights corresponding thereto throughout the world, (ii) inventions, discoveries, designs and improvements described or claimed therein, (iii) reissues, divisions, continuations, reexaminations, extensions and continuations-in-part thereof and amendments thereto and (iv) rights to sue for past, present and future infringements thereof; and (b) all Proceeds of any and all of the foregoing; and

WHEREAS, the Patent Security Agreement was recorded with the United States Patent and Trademark Office on December 2, 2016, at Reel 040797, Frame 0001.

NOW, THEREFORE, for good and valuable consideration, receipt and sufficiency of which is hereby acknowledged:

1. Release of Security Interest. The Agent, on behalf of itself, its successors, legal representatives, assigns and the Secured Parties, without recourse, representation or warranty of any kind, express or implied, free and clear of any claims by the Agent, (a) hereby irrevocably and forever terminates, releases and discharges fully its lien on and security interest in all of the right, title and interest in, to and under the Patent Collateral; and (b) terminates the Patent Security Agreement in its entirety.
2. Governing Law. This Release and the rights and obligations of the parties hereunder shall be construed in accordance with and be governed by the law of the State of New York.
3. Recordation of Release. The Agent understands and agrees that this Release may be recorded by or for each Grantor with the U.S. Patent and Trademark Office.
4. Further Actions. The Agent further agrees to execute any other documents and take any further action reasonably necessary in any state, country or jurisdiction that each Grantor may reasonably require to effect the intent and purpose of this Release.

[remainder intentionally left blank]

IN WITNESS WHEREOF, the Agent has executed this Release of Security Interest in Patents as of the Effective Date.

ROYAL BANK OF CANADA, as Agent

By:  _____

Name: Susan Khokher

Title: Manager, Agency

[Signature Page to Release of Security Interests in Patents]

PATENT
REEL: 052920 FRAME: 0065

EXHIBIT A
PATENTS

[see attached]

Owner	Patent Description	Patent Number	Issue Date
DigitalOptics Corporation	Method and system for super resolution	7003177	21-Feb-2006
DigitalOptics Corporation	Method for processing a digital image	7065256	20-Jun-2006
DigitalOptics Corporation	Camera with image enhancement functions	7627193	01-Dec-2009
DigitalOptics Corporation	Thin color camera having sub-pixel resolution	7773143	10-Aug-2010
DigitalOptics Corporation	Processing of mosaic images	7907791	15-Mar-2011
DigitalOptics Corporation	Optical alignment of cameras with extended depth of field	7999851	16-Aug-2011
DigitalOptics Corporation	Image enhancement in the mosaic domain	8115840	14-Feb-2012
DigitalOptics Corporation	Camera with image enhancement functions	8126287	28-Feb-2012
DigitalOptics Corporation	Image enhancement using hardware-based deconvolution	8154636	10-Apr-2012
DigitalOptics Corporation	Image restoration with enhanced filtering	8537234	17-Sep-2013
DigitalOptics Corporation	Dual sensor camera	8542287	24-Sep-2013
DigitalOptics Corporation	Non-linear transformations for enhancement of images	8547444	01-Oct-2013
DigitalOptics Corporation	Dual lens digital zoom	8553106	08-Oct-2013
DigitalOptics Corporation	Camera module with mems actuator and method for driving the same	8553342	08-Oct-2013
DigitalOptics Corporation	Camera module	8651755	18-Feb-2014

Digitaloptics Corporation	Mems actuator mounted camera module having sag compensation and sag compensation method using the same	8878981	04-Nov-2014
Digitaloptics Corporation	Dual sensor camera	8913145	16-Dec-2014
Digitaloptics Corporation	Auto-focus camera module with mems closed loop compensator	8988586	24-Mar-2015
Digitaloptics Corporation	Auto-focus camera module with mems distance measurement	9055207	09-Jun-2015
Digitaloptics Corporation	Auto-focus camera module with mems capacitance estimator	9081264	14-Jul-2015
Digitaloptics Corporation	Dual sensor camera	9118826	25-Aug-2015
Digitaloptics Corporation	Camera orientation sensing using camera module with MEMS AF actuator	9258473	09-Feb-2016
Digitaloptics Corporation	Dual lens digital zoom	9282252	08-Mar-2016
Digitaloptics Corporation	Miniature camera module with mems-actuated autofocus	9285654	15-Mar-2016
Digitaloptics Corporation	MEMS auto focus miniature camera module with fixed and movable lens groups	9294667	22-Mar-2016
Digitaloptics Corporation	Dual sensor camera	9420190	16-Aug-2016
Digitaloptics Corporation	Dual sensor camera	9438810	06-Sep-2016
Digitaloptics Corporation MEMS	Kinematic and non-kinematic passive alignment assemblies and methods of making the same	6661955	09-Dec-2003

Digitaloptics Corporation MEMS	Optical element support structure and methods of using and making the same	6661962	09-Dec-2003
Digitaloptics Corporation MEMS	Flexure assemblies and methods of making the same	6674585	06-Jan-2004
Digitaloptics Corporation MEMS	Base, payload and connecting structure and methods of making the same	6850675	01-Feb-2005
Digitaloptics Corporation MEMS	Base, payload and connecting structure and methods of making the same	7113688	26-Sep-2006
Digitaloptics Corporation MEMS	Motion control stages and methods of making the same	7266272	04-Sep-2007
Digitaloptics Corporation MEMS	Lens barrel	7345827	18-Mar-2008
Digitaloptics Corporation MEMS	Lens mount and alignment method	7359130	15-Apr-2008
Digitaloptics Corporation MEMS	Lens positioning systems and methods	7359131	15-Apr-2008
Digitaloptics Corporation MEMS	Lens assembly	7403344	22-Jul-2008
Digitaloptics Corporation MEMS	Range and speed finder	7477400	13-Jan-2009
Digitaloptics Corporation MEMS	Miniature camera	7477842	13-Jan-2009
Digitaloptics Corporation MEMS	Zoom lens assembly	7495852	24-Feb-2009
Digitaloptics Corporation MEMS	Lens positioning systems and methods	7515362	07-Apr-2009
Digitaloptics Corporation MEMS	Uniform wall thickness lens barrel	7545591	09-Jun-2009
Digitaloptics Corporation MEMS	Axial snubbers for camera	7555210	30-Jun-2009
Digitaloptics Corporation MEMS	Telephone vibrator	7565070	21-Jul-2009
Digitaloptics Corporation MEMS	Shutter for miniature camera	7570882	04-Aug-2009
Digitaloptics Corporation MEMS	Mems digital linear actuator	7583006	01-Sep-2009
Digitaloptics Corporation MEMS	Camera snubber assembly	7646969	12-Jan-2010
Digitaloptics Corporation MEMS	Lens barrel	7660056	09-Feb-2010
Digitaloptics Corporation MEMS	Centipede actuator motion stage	7663289	16-Feb-2010

Digitaloptics Corporation MEMS	Optical system with plano convex lens	7663817	16-Feb-2010
Digitaloptics Corporation MEMS	Camera with multiple focus captures	7693408	06-Apr-2010
Digitaloptics Corporation MEMS	Electronic damping for stage positioning	7697829	13-Apr-2010
Digitaloptics Corporation MEMS	Auto-focus with lens vibration	7697831	13-Apr-2010
Digitaloptics Corporation MEMS	Hidden autofocus	7697834	13-Apr-2010
Digitaloptics Corporation MEMS	Board mounted hermetically sealed optical device enclosure and manufacturing methods therefor	7702226	20-Apr-2010
Digitaloptics Corporation MEMS	Shutter for autofocus	7729601	01-Jun-2010
Digitaloptics Corporation MEMS	Resolution adjustment for miniature camera	7729603	01-Jun-2010
Digitaloptics Corporation MEMS	Zoom lens assembly	7747155	29-Jun-2010
Digitaloptics Corporation MEMS	Stage with built-in damping	7769281	03-Aug-2010
Digitaloptics Corporation MEMS	Lens barrel assembly	7769284	03-Aug-2010
Digitaloptics Corporation MEMS	Miniature camera lens system	7785023	31-Aug-2010
Digitaloptics Corporation MEMS	Lens barrel assembly	7787198	31-Aug-2010
Digitaloptics Corporation MEMS	Triaxial snubber assembly	7792421	07-Sep-2010
Digitaloptics Corporation MEMS	Autofocus camera	7813634	12-Oct-2010
Digitaloptics Corporation MEMS	Impulse actuated mems devices	7832948	16-Nov-2010
Digitaloptics Corporation MEMS	Enhanced etch systems	7838322	23-Nov-2010
Digitaloptics Corporation MEMS	Adaptive autofocus lens positioning	7844172	30-Nov-2010
Digitaloptics Corporation MEMS	Adaptive autofocus lens positioning	7869701	11-Jan-2011
Digitaloptics Corporation MEMS	Impulse actuated mems devices	7972070	05-Jul-2011
Digitaloptics Corporation MEMS	Planar flexure system with high pitch stiffness	7990628	02-Aug-2011
Digitaloptics Corporation MEMS	Integrated lens barrel	8004780	23-Aug-2011

Digitaloptics Corporation MEMS	Autofocus camera systems and methods	8014662	06-Sep-2011
Digitaloptics Corporation MEMS	Lens barrel assembly for a camera	8090252	03-Jan-2012
Digitaloptics Corporation MEMS	Lens barrel assembly for a camera	8184967	22-May-2012
Digitaloptics Corporation MEMS	Impulse actuated mems devices	8186895	29-May-2012
Digitaloptics Corporation MEMS	Stage with built-in damping	8238739	07-Aug-2012
Digitaloptics Corporation MEMS	Video mode hidden autofocus	8289377	16-Oct-2012
Digitaloptics Corporation MEMS	Mems deployment flexures	8289614	16-Oct-2012
Digitaloptics Corporation MEMS	Long hinge actuator snubbing	8337103	25-Dec-2012
Digitaloptics Corporation MEMS	Autofocus camera systems and methods	8346074	01-Jan-2013
Digitaloptics Corporation MEMS	Lens barrel with mems actuators	8358925	22-Jan-2013
Digitaloptics Corporation MEMS	Autofocus camera systems and methods	8391700	05-Mar-2013
Digitaloptics Corporation MEMS	Rotationally deployed actuators	8430580	30-Apr-2013
Digitaloptics Corporation MEMS	Planar flexure system with high pitch stiffness	8488260	16-Jul-2013
Digitaloptics Corporation MEMS	Mems actuator alignment	8521017	27-Aug-2013
Digitaloptics Corporation MEMS	Mems device with integrated memory cells	8536664	17-Sep-2013
Digitaloptics Corporation MEMS	Electrical routing	8547627	01-Oct-2013
Digitaloptics Corporation MEMS	Surface mount actuator	8571405	29-Oct-2013
Digitaloptics Corporation MEMS	Video mode hidden autofocus	8581963	12-Nov-2013
Digitaloptics Corporation MEMS	Long hinge actuator snubbing	8602666	10-Dec-2013
Digitaloptics Corporation MEMS	Motion controlled actuator	8604663	10-Dec-2013
Digitaloptics Corporation MEMS	Mounting flexure contacts	8605375	10-Dec-2013

Digitaloptics Corporation MEMS	Capillary actuator deployment	8608393	17-Dec-2013
Digitaloptics Corporation MEMS	Rotationally deployed actuator devices	8616791	31-Dec-2013
Digitaloptics Corporation MEMS	Rotational comb drive z-stage	8619378	31-Dec-2013
Digitaloptics Corporation MEMS	Mems actuator device	8637961	28-Jan-2014
Digitaloptics Corporation MEMS	Mechanical isolation for mems electrical contacts	8674460	18-Mar-2014
Digitaloptics Corporation MEMS	Autofocus camera systems and methods	8682156	25-Mar-2014
Digitaloptics Corporation MEMS	Arcuate motion control in electrostatic actuators	8712229	29-Apr-2014
Digitaloptics Corporation MEMS	Mems deployment flexures	8736950	27-May-2014
Digitaloptics Corporation MEMS	Multiple degree of freedom actuator	8768157	01-Jul-2014
Digitaloptics Corporation MEMS	Mems snubber systems and methods	8786967	22-Jul-2014
Digitaloptics Corporation MEMS	Linearly deployed actuators	8803256	12-Aug-2014
Digitaloptics Corporation MEMS	Electrostatic actuator control	8853975	07-Oct-2014
Digitaloptics Corporation MEMS	Mems-based optical image stabilization	8855476	07-Oct-2014
Digitaloptics Corporation MEMS	Mems actuator/sensor	8869625	28-Oct-2014
Digitaloptics Corporation MEMS	Mounting flexure contacts	8873174	28-Oct-2014
Digitaloptics Corporation MEMS	Guard trench	8884381	11-Nov-2014
Digitaloptics Corporation MEMS	Electrical routing	8922870	30-Dec-2014
Digitaloptics Corporation MEMS	Mems actuator device deployment	8941192	27-Jan-2015
Digitaloptics Corporation MEMS	Miniature mems actuator assemblies	8947797	03-Feb-2015
Digitaloptics Corporation MEMS	Mems actuator alignment	8953934	10-Feb-2015
Digitaloptics Corporation MEMS	Capillary actuator deployment	8998514	07-Apr-2015
Digitaloptics Corporation MEMS	Wafer scale optics	9001257	07-Apr-2015

Digitaloptics Corporation MEMS	Long hinge actuator snubbing	9004787	14-Apr-2015
Digitaloptics Corporation MEMS	Optical image stabilization using tangentially actuated mems devices	9019390	28-Apr-2015
Digitaloptics Corporation MEMS	Actuator inside of motion control	9052567	09-Jun-2015
Digitaloptics Corporation MEMS	Actuator motion control features	9061883	23-Jun-2015
Digitaloptics Corporation MEMS	Miniature mems actuator assemblies	9063278	23-Jun-2015
Digitaloptics Corporation MEMS	Continuous capacitance measurement for mems-actuated movement of an optical component within an auto-focus camera module	9097748	04-Aug-2015
Digitaloptics Corporation MEMS	Integrated lens barrel	9146445	29-Sep-2015
Digitaloptics Corporation MEMS	Linearly deployed actuators	9166463	20-Oct-2015
Digitaloptics Corporation MEMS	Row and column actuator control	9281763	08-Mar-2016
Digitaloptics Corporation MEMS	Autofocus camera systems and methods	9291875	22-Mar-2016
Digitaloptics Corporation MEMS	Cascaded electrostatic actuator	9350271	24-May-2016
Digitaloptics Corporation MEMS	MEMS isolation structures	9352962	31-May-2016
Digitaloptics Corporation MEMS	Mems fast focus camera module	9354486	31-May-2016
Digitaloptics Corporation MEMS	MEMS shock cushion spring systems and methods	9397585	19-Jul-2016
Digitaloptics Corporation MEMS	Surface mount actuator	9414495	09-Aug-2016
Digitaloptics Corporation MEMS	Camera modules with inertial sensors	9426344	23-Aug-2016

Digitaloptics Corporation MEMS	Thermal despace compensation systems and methods	9465187	11-Oct-2016
DTS LLC	5-2-5 MATRIX SYSTEM	5912976	15-Jun-1999
DTS LLC	5-2-5 MATRIX SYSTEM	6198827	6-Mar-01
DTS LLC	SOUND ENHANCEMENT SYSTEM	6281749	28-Aug-01
DTS LLC	LOW-FREQUENCY AUDIO ENHANCEMENT SYSTEM	6285767	4-Sep-01
DTS LLC	APPARATUS AND METHOD FOR SYNTHESIZING PSEUDO-STEREOPHONIC OUTPUTS FROM A MONOPHONIC INPUT	6590983	8-Jul-03
DTS LLC	VOICE INTELLIGIBILITY ENHANCEMENT SYSTEM	6993480	31-Jan-06
DTS LLC	ACOUSTIC CORRECTION APPARATUS	7031474	18-Apr-06
DTS LLC	SYSTEM AND METHOD FOR ENHANCED STREAMING AUDIO	7277767	2-Oct-07
DTS LLC	SYSTEMS AND METHODS OF REMOTELY ENABLING SOUND ENHANCEMENT TECHNIQUES	7451093	11-Nov-08
DTS LLC	SYSTEM AND METHOD FOR ENHANCED STREAMING AUDIO	7467021	16-Dec-08

DTS LLC	SYSTEMS AND METHODS OF SPATIAL IMAGE ENHANCEMENT OF A SOUND SOURCE	7522733	21-Apr-09
DTS LLC	ACOUSTIC CORRECTION APPARATUS	7555130	30-Jun-09
DTS LLC	SYSTEMS AND METHODS FOR MULTI-DIALOG SURROUND AUDIO	7,606,716	20-Oct-09
DTS LLC	SYSTEMS AND METHODS FOR AUDIO PROCESSING	7,720,240	18-May-10
DTS LLC	AUDIO PROCESSING SYSTEMS AND METHODS	7764802	27-Jul-10
DTS LLC	PHASE COMPENSATION TECHNIQUES TO ADJUST FOR SPEAKER DEFICIENCIES	7778427	17-Aug-10
DTS LLC	SYSTEMS AND METHODS OF REMOTELY ENABLING SOUND ENHANCEMENT TECHNIQUES	7801734	21-Sep-10
DTS LLC	ACOUSTIC CORRECTION APPARATUS	7907736	15-Mar-11
DTS LLC	SYSTEMS AND METHODS FOR REDUCING AUDIO NOISE	7912231	22-Mar-11
DTS LLC	SYSTEM AND METHOD FOR ENHANCED STREAMING AUDIO	7987281	26-Jul-11
DTS LLC	SYSTEMS AND METHODS FOR AUDIO PROCESSING	8027477	27-Sep-11

DTS LLC	SYSTEM AND METHOD FOR ENHANCED STREAMING AUDIO	8046093	25-Oct-11
DTS LLC	MULTI-CHANNEL AUDIO ENHANCEMENT SYSTEM	8050434	1-Nov-11
DTS LLC	SYSTEM FOR ADAPTIVE VOICE INTELLIGIBILITY PROCESSING	8,204,742	19-Jun-12
DTS LLC	SYSTEM FOR ADJUSTING PERCEIVED LOUDNESS OF AUDIO SIGNALS	8,315,398	20-Nov-12
DTS LLC	SYSTEM FOR ADAPTIVE VOICE INTELLIGIBILITY PROCESSING	8,386,247	12-Feb-13
DTS LLC	PRODUCTION, TRANSMISSION, STORAGE AND RENDERING SYSTEM FOR MULTI-DIMENSIONAL AUDIO	8,396,575	12-Mar-13
DTS LLC	PRODUCTION, TRANSMISSION, STORAGE AND RENDERING SYSTEM FOR MULTI-DIMENSIONAL AUDIO	8,396,576	12-Mar-13
DTS LLC	PRODUCTION, TRANSMISSION, STORAGE AND RENDERING SYSTEM FOR MULTI-DIMENSIONAL AUDIO	8,396,577	12-Mar-13
DTS LLC	AUDIO PROCESSING SYSTEMS AND METHODS	8,428,276	23-Apr-13

DTS LLC	MULTI-CHANNEL AUDIO ENHANCEMENT SYSTEM FOR USE IN RECORDING PLAYBACK AND METHODS FOR PROVIDING SAME	8472631	25-Jun-2015
DTS LLC	MULTI-CHANNEL AUDIO ENHANCEMENT SYSTEM	8,509,464	13-Aug-13
DTS LLC	SYSTEM FOR INCREASING PERCEIVED LOUDNESS OF SPEAKERS	8,538,042	17-Sep-13
DTS LLC	STEREO IMAGE WIDENING SYSTEM	8,660,271	25-Feb-14
DTS LLC	SYSTEMS AND METHODS FOR AUDIO PROCESSING	8,831,254	9-Sep-14
DTS LLC	SYSTEM FOR DYNAMICALLY CREATING AND RENDERING AUDIO OBJECTS	9,026,450	5-May-15
DTS LLC	IMMERSIVE AUDIO RENDERING SYSTEM	9,088,858	21-Jul-15
DTS LLC	ADAPTIVE VOICE INTELLIGIBILITY PROCESSOR	9,117,455	25-Aug-15
DTS LLC	IMMERSIVE AUDIO RENDERING SYSTEM	9,154,897	6-Oct-15
DTS LLC	AUDIO ADJUSTMENT SYSTEM	9,164,724	20-Oct-15
DTS LLC	SYSTEM FOR DYNAMICALLY CREATING AND RENDERING AUDIO OBJECTS	9,165,558	20-Oct-15

DTS LLC	PRODUCTION, TRANSMISSION, STORAGE AND RENDERING SYSTEM FOR MULTI- DIMENSIONAL AUDIO	9,167,346	20-Oct-15
DTS LLC	OBJECT-BASED AUDIO SYSTEM USING VECTOR BASE AMPLITUDE PANNING	9,197,979	24-Nov-15
DTS LLC	MULTI-MICROPHONE ARRAY PROCESSING	9,232,309	5-Jan-16
DTS LLC	MULTI-CHANNEL AUDIO ENHANCEMENT SYSTEM	9,232,312	5-Jan-16
DTS LLC	SYSTEMS AND METHODS FOR AUDIO PROCESSING	9,232,319	5-Jan-16
DTS LLC	BASS ENHANCEMENT SYSTEM	9,236,842	12-Jan-16
DTS LLC	SYSTEM FOR ADJUSTING PERCEIVED LOUDNESS OF AUDIO SIGNALS	9,264,836	16-Feb-16
DTS LLC	SYSTEMS AND METHODS OF FREQUENCY RESPONSE CORRECTION FOR CONSUMER ELECTRONIC DEVICES	9,307,322	5-Apr-16
DTS LLC	HEAD END LOUDNESS MANAGEMENT SYSTEM	9,312,829	12-Apr-16
DTS LLC	SYSTEMS AND METHODS OF FREQUENCY RESPONSE CORRECTION FOR CONSUMER ELECTRONIC DEVICES	9,319,790	19-Apr-16

DTS LLC	SYSTEMS AND METHODS FOR REDUCING AUDIO NOISE	9,386,162	5-Jul-16
DTS LLC	SYSTEM AND METHOD FOR ENHANCED STREAMING AUDIO	8,751,028 B2	10-Jun-14
DTS, Inc.	SOUND QUALITY OF ESTABLISHED LOW BIT-RATE AUDIO CODING SYSTEMS WITHOUT LOSS OF DECODER COMPATIBILITY	6,226,616	1-May-01
DTS, Inc.	SYSTEM AND METHOD FOR PROVIDING INTERACTIVE AUDIO IN A MULTI-CHANNEL AUDIO ENVIRONMENT	6,931,370	16-Aug-05
DTS, Inc.	METHOD OF DECODING TWO-CHANNEL MATRIX ENCODED AUDIO TO RECONSTRUCT MULTICHANNEL AUDIO	7,003,467	21-Feb-06
DTS, INC.	DIGITAL INTERMEDIATE (DI) PROCESSING AND DISTRIBUTION WITH SCALABLE COMPRESSION IN THE POST-PRODUCTION OF MOTION PICTURES	7110605	19-Sep-2006
DTS, Inc.	HEARING AJUSTMENT APPLICANCE FOR ELECTRONIC AUDIO EQUIPMENT	7,190,795	13-Mar-07
DTS, Inc.	DISCRETE MULTI-CHANNEL AUDIO WITH A BACKWARDS COMPATIBLE MIX	7,212,872	1-May-07

DTS, Inc.	SCALABLE LOSSLESS AUDIO CODEC AND AUTHORING TOOL	7,272,567	18-Sep-07
DTS, Inc.	METHOD OF MIXING AUDIO CHANNELS USING CORRELATED OUTPUTS	7,283,634	16-Oct-07
DTS, Inc.	MODULAR SCALABLE COMPRESSED AUDIO DATA STREAM	7,333,929	19-Feb-08
DTS, Inc.	LOSSLESS MULTI-CHANNEL AUDIO CODEC	7,392,195	24-Jun-08
DTS, Inc.	SCALABLE COMPRESSED AUDIO BIT STREAM AND CODEC USING A HIERARCHICAL FILTERBANK AND MULTICHANNEL JOINT CODING	7,548,853	16-Jun-09
DTS, Inc.	LISTENER SPECIFIC AUDIO REPRODUCTION SYSTEM	7,564,979	21-Jul-2009
DTS, Inc.	NEURAL NETWORK FILTERING TECHNIQUES FOR COMPENSATING LINEAR AND NON-LINEAR DISTORTION OF AN AUDIO TRANSDUCER	7,593,535	22-Sep-09
DTS, Inc.	RATE CONTROL OF SCALABLY CODED IMAGES	7,668,380	23-Feb-10
DTS, Inc.	SCALABLE LOSSLESS AUDIO CODEC AND AUTHORING TOOL	7,668,723	23-Feb-10

DTS, Inc.	DIGITAL INTERMEDIATE (DI) PROCESSING AND DISTRIBUTION WITH SCALABLE COMPRESSION IN THE POST-PRODUCTION OF MOTION PICTURES	7,724,964	25-May-10
DTS, Inc.	2-TO-N-RENDERING	7,853,022	14-Dec-10
DTS, Inc.	SYSTEM AND METHOD FOR GENERATING MULTIMEDIA ACCOMPANIMENTS TO BROADCAST DATA	7,908,172	15-Mar-11
DTS, Inc.	2-TO-N-RENDERING	7,929,708	19-Apr-11
DTS, Inc.	LOSSLESS MULTI-CHANNEL AUDIO CODEC	7,930,184	19-Apr-11
DTS, Inc.	VIRTUAL AUDIO PROCESSING FOR LOUDSPEAKER OR HEADPHONE PLAYBACK	8,000,485	16-Aug-11
DTS, Inc.	BASS ENHANCEMENT FOR AUDIO	8,005,233	23-Aug-11
DTS, Inc.	TEMPORALLY-ACCURATE WATERMARK SYSTEM AND METHOD OF OPERATION	8,099,285	17-Jan-12
DTS, Inc.	INTERAURAL TIME DELAY RESTORATION SYSTEM AND METHOD	8233629	31-Jul-12
DTS, Inc.	LOSSLESS MULTI-CHANNEL AUDIO CODEC	8,239,210	7-Aug-12

DTS, Inc.	SYSTEM AND METHOD FOR GENERATING MULTIMEDIA ACCOMPANIMENTS TO BROADCAST DATA	8,255,276	28-Aug-12
DTS, Inc.	SYSTEM AND METHOD FOR GENERATING MULTIMEDIA ACCOMPANIMENTS TO BROADCAST DATA	8,255,277	28-Aug-12
DTS, Inc.	COMPRESSION OF AUDIO SCALE-FACTORS BY TWO-DIMENSIONAL TRANSFORMATION	8,290,782	16-Oct-12
DTS, Inc.	SCALABLE LOSSLESS AUDIO CODEC AND AUTHORIZING TOOL	8,374,858	12-Feb-13
DTS, Inc.	PARAMETRIC STEREO CONVERSION SYSTEM AND METHOD	8,385,556	26-Feb-13
DTS, Inc.	SYSTEM AND METHOD FOR TRANSMITTING DIGITAL MULTIMEDIA DATA WITH ANALOG BROADCAST DATA	8,396,100	12-Mar-13
DTS, Inc.	ADAPTIVE DYNAMIC RANGE ENHANCEMENT OF AUDIO RECORDINGS	8,879,750	4-Nov-14
DTS, Inc.	SPATIAL AUDIO ENCODING AND REPRODUCTION	8,908,874	9-Dec-14
DTS, INC.	SPATIAL AUDIO ENCODING AND REPRODUCTION	8908874	9-Dec-2014
DTS, Inc.	ROOM CHARACTERIZATION AND CORRECTION FOR MULTI-CHANNEL AUDIO	9,031,268	12-May-15

DTS, Inc.	SPATIAL AUDIO ENCODING AND REPRODUCTION	9,042,565	26-May-15
DTS, Inc.	SYSTEM AND METHOD FOR TRANSMITTING DIGITAL MULTIMEDIA DATA WITH ANALOG BROADCAST DATA	9,094,186	28-Jul-15
DTS, Inc.	DIRECT/DIFFUSE DECOMPOSITION	9,253,574	2-Feb-16
DTS, Inc.	VARIABLE DECORRELATION	9,264,838	16-Feb-16
DTS, Inc.	AUDIO DEPTH DYNAMIC RANGE ENHANCEMENT	9,332,373	3-May-16
DTS, Inc.	SYSTEM AND METHOD FOR GENERATING MULTIMEDIA ACCOMPANIMENTS TO BROADCAST DATA	9,337,791	10-May-16
DTS, Inc.	MATRIX DECODER WITH CONSTANT-POWER PAIRWISE PANNING	9,338,573	10-May-16
DTS, Inc.	RECONSTRUCTION OF A HIGH FREQUENCY RANGE IN LOW BIT-RATE AUDIO CODING USING PREDICTIVE PATTERN ANALYSIS	9,373,337	21-Jun-16
DTS, Inc.	REVERBERATION TIME ESTIMATION BASED ON MULTIDELAY ACOUSTIC ECHO CANCELLATION	9,386,373	5-Jul-16
DTS, Inc.	DYNAMIC COMPENSATION OF AUDIO SIGNALS FOR IMPROVED PERCEIVED SPECTRAL IMBALANCES	9,391,579	12-Jul-16

DTS, Inc.	DIRECTIONAL BASED AUDIO RESPONSE TO AN EXTERNAL ENVIRONMENT EMERGENCY SIGNAL	9,397,630	19-Jul-16
DTS, Inc.	SYSTEM AND METHOD FOR SPATIAL RECALIBRATION OF A MULTICHANNEL LOUDSPEAKER SYSTEM	9,426,598	23-Aug-16
DTS, Inc.	METHOD AND APPARATUS FOR PERSONALIZED AUDIO VIRTUALIZATION	9,426,599	23-Aug-16
DTS, Inc.	METHOD AND APPARATUS FOR EMBEDDING DIGITAL WATERMARKING INTO COMPRESSED MULTIMEDIA SIGNALS	7,114,071 B1	26-Sep-06
DTS, Inc.	DIGITAL INTERMEDIATE (DI) PROCESSING AND DISTRIBUTION WITH SCALABLE COMPRESSION IN THE POST-PRODUCTION OF MOTION PICTURES	7110605B2	19-Sep-06
DTS, Inc.	SYSTEM AND METHOD FOR COMPENSATING MEMORYLESS NON- LINEAR DISTORTION OF AN AUDIO TRANSDUCER	8,300,837 B2	30-Oct-12
Ibiquity Digital Corporation	COHERENT SIGNAL DETECTOR FOR AM- COMPATIBLE DIGITAL AUDIO BROADCAST WAVEFORM RECOVERY (58,636)	5,878,089	2-Mar-99

Ibiquity Digital Corporation	DIGITAL AUDIO BROADCASTING METHOD USING PUNCTURABLE CONVOLUTIONAL CODE (WWS 97001)	6,108,810	22-Aug-00
Ibiquity Digital Corporation	RECEIVER ADDRESSABLE AM COMPATIBLE DIGITAL BROADCAST SYSTEM (57,659)	6,128,334	3-Oct-00
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR REDUCING PEAK TO AVERAGE POWER RATIO IN DIGITAL BROADCASTING SYSTEMS (USADR 99001)	6,128,350	3-Oct-00
Ibiquity Digital Corporation	METHOD FOR DATA TRANSMISSION IN A DIGITAL AUDIO BROADCASTING SYSTEM (WWS97005)	6,148,007	14-Nov-00
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR TRANSMITTING AND RECEIVING LARGE OBJECTS VIA DIGITAL RADIO BROADCAST	8,595,748	26-Nov-13
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR A MULTIPORT SYNCHRONOUS-ASYNCHRONOUS CLIENT FOR SCHEDULING AND DELIVERING CONTENT FOR DIGITAL RADIO BROADCAST TRANSMISSION	8,660,128	25-Feb-14

Ibiquity Digital Corporation	DIGITAL RADIO BROADCAST RECEIVER, BROADCASTING METHODS AND METHODS FOR TAGGING CONTENT OF INTEREST	8,660,479	25-Feb-14
Ibiquity Digital Corporation	DIGITAL RADIO BROADCAST RECEIVER, BROADCASTING METHODS AND METHODS FOR TAGGING CONTENT OF INTEREST	8,676,114	18-Mar-14
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR TRANSMITTING MEDIA CONTENT VIA DIGITAL RADIO BROADCAST TRANSMISSION FOR SYNCHRONIZED RENDERING BY A RECEIVER	8,804,037	12-Aug-14
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR COMMUNICATING AND RENDERING ELECTRONIC PROGRAM GUIDE INFORMATION VIA DIGITAL RADIO BROADCAST TRANSMISSION	8,983,365	17-Mar-15
Ibiquity Digital Corporation	LOOK AHEAD METRICS TO IMPROVE BLENDING DECISION	9,094,139	28-Jul-15
Ibiquity Digital Corporation	SIGNAL ARTIFACT DETECTION AND ELIMINATION FOR AUDIO OUTPUT	9,129,592	8-Sep-15

Ibiquity Digital Corporation	METHODS FOR RECEIVER MEMORY AND POWER REDUCTION	9,203,668	1-Dec-15
Ibiquity Digital Corporation	SYSTEM AND METHOD FOR RECOVERING AUDIO PDU TRANSPORT ELEMENTS IN DIGITAL RADIO BROADCAST RECEIVER	9,219,573	22-Dec-15
Ibiquity Digital Corporation	ADAPTIVE BANDWIDTH MANAGEMENT OF IBOC AUDIO SIGNALS DURING BLENDING	9,252,899	2-Feb-16
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR TRANSMITTING AND RECEIVING LARGE OBJECTS VIA DIGITAL RADIO BROADCAST	9,350,471	24-May-16
Ibiquity Digital Corporation	SYSTEM AND METHOD FOR INCREASING THROUGHPUT IN DIGITAL RADIO BROADCAST RECEIVER	9,379,918	28-Jun-16
Ibiquity Digital Corporation	APPARATUS AND METHOD FOR TRANSLATING AN IBOC RADIO SIGNAL (IDC 14-003)	9,407,383	2-Aug-16
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR DIGITAL RADIO BROADCAST WITH CROSS PLATFORM RECEPTION	9,467,255	11-Oct-16

Ibiquity Digital Corporation	METHOD AND APPARATUS FOR IN-BAND ON-CHANNEL TRANSMISSION AND RECEPTION USING LOW DENSITY PARITY CHECK CODES (IDC 13- 001)	9,479,197	25-Oct-16
Ibiquity Digital Corporation	SYSTEM AND METHOD FOR MITIGATING INTERMITTENT INTERRUPTIONS IN AN AUDIO RADIO BROADCAST SYSTEM (WWS 96011)	6,178,317 B1	23-Jan-01
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR AM DIGITAL BROADCASTING (WWS 98001)	6,243,424 B1	5-Jun-01
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR REDUCTION OF FM INTERFERENCE FOR FM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING SYSTEM (WWS 98014)	6,259,893 B1	10-Jul-01
Ibiquity Digital Corporation	METHOD FOR EQUALIZATION OF COMPLEMENTARY CARRIERS IN AN AM COMPATIBLE DIGITAL AUDIO BROADCAST SYSTEM (WWS 98009X)	6,292,511 B1	18-Sep-01
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR DEMODULATING AND EQUALIZING AN AM COMPATIBLE DIGITAL AUDIO BROADCAST SIGNAL (WWS98013X)	6,295,317 B1	25-Sep-01

Ibiquity Digital Corporation	ADAPTIVE WEIGHTING METHOD FOR ORTHOGONAL FREQUENCY DIVISION MULTIPLEXED SOFT SYMBOLS USING CHANNEL STATE INFORMATION ESTIMATES (WWS 97006)	6,317,470 B1	13-Nov-01
Ibiquity Digital Corporation	DIGITAL AUDIO BROADCASTING METHOD USING PUNCTURABLE CONVOLUTIONAL CODE (WWS 97001)	6,345,377 B1	5-Feb-02
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR TRAINING SEQUENCE IDENTIFICATION IN AN AM COMPATIBLE DIGITAL AUDIO BROADCASTING SYSTEM (WWS98012X)	6,400,758 B1	4-Jun-02
Ibiquity Digital Corporation	FM IN-BAND-ON-CHANNEL DIGITAL AUDIO BROADCASTING METHOD AND SYSTEM (WWS97008)	6,430,227 B1	6-Aug-02
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR AM COMPATIBLE DIGITAL BROADCASTING (WWS 98003X)	6,452,977 B1	17-Sep-02
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR DEMODULATING AND EQUALIZING AN AM COMPATIBLE DIGITAL AUDIO BROADCAST SIGNAL (WWS98013X)	6,480,536 B2	12-Nov-02

Ibiquity Digital Corporation	METHOD AND APPARATUS FOR AM DIGITAL BROADCASTING (WWS 98001)	6,487,256 B2	26-Nov-02
Ibiquity Digital Corporation	IN-BAND ON-CHANNEL DIGITAL BROADCASTING (TT850)	6,510,175 B1	21-Jan-03
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR FORWARD ERROR CORRECTION CODING FOR AN AM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING SYSTEM (USADR 99004)	6,523,147 B1	18-Feb-03
Ibiquity Digital Corporation	METHOD FOR ESTIMATING SIGNAL-TO-NOISE RATIO OF DIGITAL CARRIERS IN AN AM COMPATIBLE DIGITAL AUDIO BROADCASTING SYSTEM (WWS98011X)	6,532,258 B1	11-Mar-03
Ibiquity Digital Corporation	SYSTEM AND METHOD FOR RECOVERING SYMBOL TIMING OFFSET AND CARRIER FREQUENCY ERROR IN AN OFDM DIGITAL AUDIO BROADCAST SYSTEM (WWS 97004)	6,539,063 B1	25-Mar-03
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR TRANSMISSION AND RECEPTION OF FM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING (USADR99007)	6,549,544 B1	15-Apr-03

Ibiquity Digital Corporation	METHOD AND APPARATUS FOR DETERMINING TRANSMISSION MODE AND SYNCHRONIZATION FOR A DIGITAL AUDIO BROADCASTING SIGNAL (WWS 98010X)	6,556,639 B1	29-Apr-03
Ibiquity Digital Corporation	METHOD FOR EQUALIZATION OF COMPLEMENTARY CARRIERS IN AN AM COMPATIBLE DIGITAL AUDIO BROADCAST SYSTEM (WWS 98009X)	6,570,943 B2	27-May-03
Ibiquity Digital Corporation	AUDIO BLEND METHOD AND APPARATUS FOR AM AND FM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING (WWS 97009)	6,590,944 B1	8-Jul-03
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR REDUCTION OF FM INTERFERENCE FOR FM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING SYSTEM (WWS 98014)	6,622,008 B2	16-Sep-03
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR PULSE OVERLAP PRE-COMPENSATION IN DIGITALLY MODULATED SIGNALS (IDC 01002)	6,639,949 B2	28-Oct-03

Ibiquity Digital Corporation	METHOD AND APPARATUS FOR REDUCTION OF INTERFERENCE IN FM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING RECEIVERS (USADR 99009)	6,671,340 B1	30-Dec-03
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR TRANSMISSION AND RECEPTION OF COMPRESSED AUDIO FRAMES WITH PRIORITIZED MESSAGES FOR DIGITAL AUDIO BROADCASTING (WWS 98015)	6,721,337 B1	13-Apr-04
Ibiquity Digital Corporation	AUDIO BLEND METHOD AND APPARATUS FOR AM AND FM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING (WWS 97009)	6,735,257 B2	11-May-04
Ibiquity Digital Corporation	HYBRID AM DIGITAL BROADCASTING SYSTEM WITH ANALOG PRECOMPENSATION (IDC01001)	6,798,849 B2	28-Sep-04
Ibiquity Digital Corporation	SYSTEM AND METHOD FOR A PUSH-PULL GATEWAY-DIRECTED DIGITAL RECEIVER (708034-605-002)	6,845,230 B2	18-Jan-05

Ibiquity Digital Corporation	SYSTEM AND METHOD FOR RECOVERING SYMBOL TIMING OFFSET AND CARRIER FREQUENCY ERROR IN AN OFDM DIGITAL AUDIO BROADCAST SYSTEM (WWS 97004)	6,891,898 B2	10-May-05
Ibiquity Digital Corporation	ADAPTIVE WEIGHTING METHOD FOR ORTHOGONAL FREQUENCY DIVISION MULTIPLEXED SOFT SYMBOLS USING CHANNEL STATE INFORMATION ESTIMATES (WWS 97006)	6,895,060 B2	17-May-05
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR DIGITAL AUDIO BROADCASTING WITH AMPLITUDE SCALED SUB-CARRIERS (IDC02006)	6,898,249 B2	24-May-05
Ibiquity Digital Corporation	SYSTEM AND METHOD FOR MITIGATING INTERMITTENT INTERRUPTIONS IN AN AUDIO RADIO BROADCAST SYSTEM (WWS 96011)	6,901,242 B2	31-May-05
Ibiquity Digital Corporation	DYNAMIC FILTER SELECTION IN IBOC DAB RECEIVERS (IDC03002)	6,970,685 B2	29-Nov-05

Ibiquity Digital Corporation	METHOD AND APPARATUS FOR TRANSMISSION AND RECEPTION OF FM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING (USADR99007)	6,982,948 B2	3-Jan-06
Ibiquity Digital Corporation	METHOD FOR ENCODING A DIGITAL SIGNAL USING COMPLEMENTARY PATTERN-MAPPED CONVOLUTIONAL CODES (IDC 01003)	7,043,681 B2	9-May-06
Ibiquity Digital Corporation	COHERENT AM DEMODULATOR USING A WEIGHTED LSB/USB SUM FOR INTERFERENCE MITIGATION (IDC 03001)	7,127,008 B2	24-Oct-06
Ibiquity Digital Corporation	EFFICIENT CODING OF HIGH FREQUENCY SIGNAL INFORMATION IN A SIGNAL USING A LINEAR/NON-LINEAR PREDICTION MODEL BASED ON A LOW PASS BASEBAND (708034-605-009)	7,191,136 B2	13-Mar-07
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR RECEIVING A DIGITAL AUDIO BROADCASTING SIGNAL (IDC 01004)	7,221,688 B2	22-May-07
Ibiquity Digital Corporation	METHOD FOR MITIGATING ADJACENT CHANNEL INTERFERENCE IN FM DIGITAL BROADCASTING RECEIVERS (IDC01005)	7,221,917 B2	22-May-07

Ibiquity Digital Corporation	METHOD AND APPARATUS FOR DIGITAL AUDIO BROADCASTING TRANSMISSION AND RECEPTION (IDC 02004) **and** METHOD AND APPARATUS FOR DIGITAL AUDIO BROADCASTING TRANSMISSION AND RECEPTION USING SPREAD HEADER TRANSFER FRAMES (IDC 02004)	7,305,043 B2	4-Dec-07
Ibiquity Digital Corporation	COHERENT TRACKING FOR FM IN-BAND ON-CHANNEL RECEIVERS (IDC 03004)	7,305,056 B2	4-Dec-07
Ibiquity Digital Corporation	FORWARD ERROR CORRECTION CODING FOR HYBRID AM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING SYSTEMS (IDC 03-003)	7,340,010 B2	4-Mar-08
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR TRANSMITTING IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING SIGNALS (IDC 02005)	7,352,817 B2	1-Apr-08

Ibiquity Digital Corporation	METHOD AND APPARATUS FOR FORWARD ERROR CORRECTION CODING FOR AN AM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING SYSTEM (USADR 99004)	7,464,324 B2	9-Dec-08
Ibiquity Digital Corporation	BANDWIDTH REDUCTION OF AN FM BROADCAST SIGNAL USING A BASEBAND PRECOMPENSATION TECHNIQUE (IDC 04002)	7,474,707 B2	6-Jan-09
Ibiquity Digital Corporation	METHOD FOR SYNCHRONIZING EXPORTER AND EXCITER CLOCKS (IDC 04004)	7,512,175 B2	31-Mar-09
Ibiquity Digital Corporation	PEAK-TO-AVERAGE POWER REDUCTION FOR FM OFDM TRANSMISSION (IDC 03005)	7,542,517 B2	2-Jun-09
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR BLENDING AN AUDIO SIGNAL IN AN IN-BAND ON-CHANNEL RADIO SYSTEM (IDC 04001)	7,546,088 B2	9-Jun-09
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR SYNCHRONIZED TRANSMISSION AND RECEPTION OF DATA IN A DIGITAL AUDIO BROADCASTING SYSTEM (IDC 02002)	7,551,675 B2	23-Jun-09

Ibiquity Digital Corporation	FORWARD ERROR CORRECTION CODING FOR HYBRID AM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING SYSTEMS (IDC 03-003)	7,680,201 B2	16-Mar-10
Ibiquity Digital Corporation	EQUALIZER FOR AM IN-BAND ON-CHANNEL RADIO RECEIVERS (IDC 05005)	7,697,620 B2	13-Apr-10
Ibiquity Digital Corporation	FORWARD ERROR CORRECTION CODING FOR HYBRID AM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING SYSTEMS (IDC 03-003)	7,706,468 B2	27-Apr-10
Ibiquity Digital Corporation	CARRIER TRACKING FOR AM IN-BAND ON-CHANNEL RADIO RECEIVERS (IDC 05003)	7,706,474 B2	27-Apr-10
Ibiquity Digital Corporation	SYSTEM AND METHOD FOR PROVIDING A PUSH OF BACKGROUND DATA (708034-605-003)	7,721,337 B2	18-May-10
Ibiquity Digital Corporation	COHERENT TRACKING FOR FM IN-BAND ON-CHANNEL RECEIVERS (IDC 03004)	7,724,850 B2	25-May-10
Ibiquity Digital Corporation	SYMBOL TRACKING FOR AM IN-BAND ON-CHANNEL RADIO RECEIVERS (IDC 05004)	7,733,983 B2	8-Jun-10

Ibiquity Digital Corporation	FORWARD ERROR CORRECTION CODING FOR HYBRID AM IN-BAND ON-CHANNEL DIGITAL AUDIO BROADCASTING SYSTEMS (IDC 03-003)	7,873,120 B2	18-Jan-11
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR IMPLEMENTING SEEK AND SCAN FUNCTIONS FOR AN FM DIGITAL RADIO SIGNAL (IDC 07001)	7,933,367 B2	26-Apr-11
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR IMPLEMENTING A DIGITAL SIGNAL QUALITY METRIC (IDC 07005)	7,933,368 B2	26-Apr-11
Ibiquity Digital Corporation	RADIO SIGNAL GENERATOR (IDC 07006)	7,957,478 B2	7-Jun-11
Ibiquity Digital Corporation	ANTENNA DESIGN FOR FM RADIO RECEIVERS (IDC 07009)	7,982,683 B2	19-Jul-11
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR STORE AND REPLAY FUNCTIONS IN A DIGITAL RADIO BROADCASTING RECEIVER (IDC 06001)	8,014,446 B2	6-Sep-11
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR DC COMPONENT RECOVERY IN A ZERO-IF RADIO RECEIVER (708034-999020)	8,019,311 B2	13-Sep-11

Ibiquity Digital Corporation	METHOD FOR ALIGNMENT OF ANALOG AND DIGITAL AUDIO IN A HYBRID RADIO WAVEFORM (IDC 05001)	8,027,419 B2	27-Sep-11
Ibiquity Digital Corporation	SYSTEM AND METHOD FOR SAMPLING RATE ADJUSTMENT OF DIGITAL RADIO RECEIVER (708034-999015)	8,040,989 B2	18-Oct-11
Ibiquity Digital Corporation	NETWORK RADIO RECEIVER (IDC06002)	8,041,292 B2	18-Oct-11
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR FREQUENCY OFFSET CORRECTION IN A DIGITAL RADIO BROADCAST RECEIVER (708034-999021)	8,068,563 B2	29-Nov-11
Ibiquity Digital Corporation	ADAPTIVE IMPEDANCE MATCHING (AIM) FOR ELECTRICALLY SMALL RADIO RECEIVER ANTENNAS (IDC 08002)	8,068,800 B2	29-Nov-11
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR FORMATTING DATA SIGNALS IN A DIGITAL AUDIO BROADCASTING SYSTEM (IDC 07-008)	8,111,716 B2	7-Feb-12

Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR RENDERING ALERT INFORMATION FOR DIGITAL RADIO BROADCAST, AND ACTIVE DIGITAL RADIO BROADCAST RECEIVER (708034-999012)	8,138,915 B2	20-Mar-12
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR TRANSMITTING MEDIA CONTENT VIA DIGITAL RADIO BROADCAST TRANSMISSION FOR SYNCHRONIZED RENDERING BY A RECEIVER (708034-999025)	8,144,612 B2	27-Mar-12
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR FINE ALIGNMENT OF ANALOG AND DIGITAL SIGNAL PATHWAYS (708034-999019)	8,180,470 B2	15-May-12
Ibiquity Digital Corporation	SYNCHRONIZATION OF SEPARATED PLATFORMS IN AN HD RADIO BROADCAST SINGLE FREQUENCY NETWORK (IDC 08-003)	8,279,908 B2	2-Oct-12
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR FAST SEEK AND SCAN FUNCTIONS IN A DIGITAL RADIO BROADCAST RECEIVER (708034-999023)	8,335,872 B2	18-Dec-12

Ibiquity Digital Corporation	DIGITAL RADIO BROADCAST RECEIVER, BROADCASTING METHODS AND METHODS FOR TAGGING CONTENT OF INTEREST (708034-999010)	8,351,843 B2	8-Jan-13
Ibiquity Digital Corporation	EQUALIZER FOR AM IN-BAND ON-CHANNEL RADIO RECEIVERS (IDC 05005)	8,442,170 B2	14-May-13
Ibiquity Digital Corporation	SYSTEMS AND METHODS FOR TRANSMITTING MEDIA CONTENT VIA DIGITAL RADIO BROADCAST TRANSMISSION FOR SYNCHRONIZED RENDERING BY A RECEIVER (708034-999025)	8,451,868 B2	28-May-13
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR STORE AND REPLAY FUNCTIONS IN A DIGITAL RADIO BROADCASTING RECEIVER (IDC 06001)	8,520,852 B2	27-Aug-13
Ibiquity Digital Corporation	RADIO SERVICE REGISTRY (IDC 07-003)	8,521,079 B2	27-Aug-13
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR STORE AND REPLAY FUNCTIONS IN A DIGITAL RADIO BROADCASTING RECEIVER (IDC 06001)	8,576,949 B2	5-Nov-13

Ibiquity Digital Corporation	PEAK-TO-AVERAGE POWER RATIO REDUCTION FOR HYBRID FM HD RADIO TRANSMISSION (IDC 10-003)	8,798,196 B2	5-Aug-14
Ibiquity Digital Corporation	DIGITAL RADIO ANTENNA DIVERSITY (IDC 11-001)	8,817,917 B2	26-Aug-14
Ibiquity Digital Corporation	MAXIMUM RATIO COMBINING ANTENNA DIVERSITY FOR FM IN-BAND ON-CHANNEL DIGITAL SIGNALS (IDC 11-003)	8,831,546 B2	9-Sep-14
Ibiquity Digital Corporation	EQUALIZER FOR AM IN-BAND ON-CHANNEL RADIO RECEIVERS (IDC 05005)	8,923,378 B2	30-Dec-14
Ibiquity Digital Corporation	MAXIMUM RATIO COMBINING ANTENNA DIVERSITY FOR FM IN-BAND ON-CHANNEL DIGITAL SIGNALS (IDC 11-003)	9,037,103 B2	19-May-15
Ibiquity Digital Corporation	CHANNEL STATE INFORMATION (CSI) AND APPLICATIONS FOR HD RADIO(TM) RECEIVERS (IDC 14-002)	9,106,472 B1	11-Aug-15
Ibiquity Digital Corporation	METHOD AND APPARATUS FOR STORE AND REPLAY FUNCTIONS IN A DIGITAL RADIO BROADCASTING RECEIVER (IDC 06001)	9,118,427 B2	25-Aug-15
Ibiquity Digital Corporation	BROADCAST EQUIPMENT COMMUNICATION PROTOCOL (IDC 08-001)	9,118,430 B2	25-Aug-15

Ibiquity Digital Corporation	METHOD AND APPARATUS FOR IN-BAND ON-CHANNEL TRANSMISSION AND RECEPTION USING LOW DENSITY PARITY CHECK CODES (IDC 13- 001)	9,136,874 B2	15-Sep-15
Ibiquity Digital Corporation	FIRST ADJACENT CANCELLER (FAC) WITH IMPROVED BLENDING USING A PARAMETRIC FILTER (IDC 14-001)	9,178,548 B1	3-Nov-15
Ibiquity Digital Corporation	PAR REDUCTION FOR QAM MODULATION WITH HD RADIO SIGNALS (IDC 14-004)	9,178,740 B1	3-Nov-15
Ibiquity Digital Corporation	DIGITAL RADIO ANTENNA DIVERSITY (IDC 11-001)	9,184,804 B2	10-Nov-15
Ibiquity Digital Corporation	FM ANALOG DEMODULATOR COMPATIBLE WITH IBOC SIGNALS (IDC 11-002)	9,184,961 B2	10-Nov-15
Invensas Corporation	Method and structure for controlling internal operations of a dram array	5708624	13-Jan-1998
Invensas Corporation	PROCESS FOR MANUFACTURING SOLDER LEADS ON A SEMICONDUCTOR DEVICE PACKAGE	5731227	24-Mar-1998
Invensas Corporation	Method of manufacturing a hybrid integrated circuit	5736452	07-Apr-1998
Invensas Corporation	Bare die multiple dies for direct attach	5790384	04-Aug-1998
Invensas Corporation	Chip stacking by edge metallization	5818107	06-Oct-1998

Invensas Corporation	ELECTRONIC PACKAGE WITH ENHANCED PAD DESIGN	5825628	20-Oct-1998
Invensas Corporation	Semiconductor body with a substrate glued to a support body	5828122	27-Oct-1998
Invensas Corporation	Reflow ball grid array assembly	5859474	12-Jan-1999
Invensas Corporation	Thin power tape ball grid array package	5869889	09-Feb-1999
Invensas Corporation	Method and apparatus for dram refresh using master, slave and self-refresh modes	5940851	17-Aug-1999
Invensas Corporation	Interposer for ball grid array (bga) package	5972734	26-Oct-1999
Invensas Corporation	BONDING MACHINE	5980663	9-Nov-1999
Invensas Corporation	Integrated circuit package having signal traces interposed between power and ground conductors in order to form stripline transmission lines	6008534	28-Dec-1999
Invensas Corporation	Electrically imprinting a semiconductor die with identifying information	6018686	25-Jan-2000
Invensas Corporation	Method and apparatus for 1-t sram compatible memory	6028804	22-Feb-2000
Invensas Corporation	Method of manufacturing an electronic device	6054336	25-Apr-2000
Invensas Corporation	Semiconductor device assemblies and circuits	6055148	25-Apr-2000
Invensas Corporation	Face on face flip chip integration	6057598	02-May-2000

Invensas Corporation	Method for establishing electrical communication between a first object having a solder ball and a second object	6059172	09-May-2000
Invensas Corporation	Cycle time reduction using an early precharge	6072738	06-Jun-2000
Invensas Corporation	Method and structure for controlling operation of a dram array	6078547	20-Jun-2000
Invensas Corporation	Formation of novel dram cell capacitors by integration of capacitors with isolation trench sidewalls	6090661	18-Jul-2000
Invensas Corporation	Article holders and holding methods	6095582	01-Aug-2000
Invensas Corporation	Semiconductor device having magnetic shield layer circumscribing the device	6097080	01-Aug-2000
Invensas Corporation	Semiconductor flip-chip package and method for the fabrication thereof	6121689	19-Sep-2000
Invensas Corporation	Single reference plane plastic ball grid array package	6127728	03-Oct-2000
Invensas Corporation	Nickel alloy films for reduced intermetallic formation in solder	6130479	10-Oct-2000
Invensas Corporation	Robust interconnect structure	6133136	17-Oct-2000
Invensas Corporation	Plasma processing methods and apparatus	6139678	31-Oct-2000

Invensas Corporation	Employing deionized water and an abrasive surface to polish a semiconductor topography	6143663	07-Nov-2000
Invensas Corporation	Clock phase generator for controlling operation of a dram array	6147535	14-Nov-2000
Invensas Corporation	On-chip word line voltage generation for dram embedded in logic process	6147914	14-Nov-2000
Invensas Corporation	Apparatus for recording and/or reading program history	6148279	14-Nov-2000
Invensas Corporation	Method of manufacturing semiconductor devices with "chip size package"	6177295	23-Jan-2001
Invensas Corporation	Dram cell having a vertical transistor and a capacitor formed on the sidewalls of a trench isolation	6177699	23-Jan-2001
Invensas Corporation	Semiconductor device comprising a glass supporting body onto which a substrate with semiconductor elements and a metallization is attached by means of an adhesive	6177707	23-Jan-2001
Invensas Corporation	Integrated circuits and methods for their fabrication	6184060	06-Feb-2001
Invensas Corporation	Full additive process with filled plated through holes	6195883	06-Mar-2001

Invensas Corporation	Cmos waveshaping buffer	6198306	06-Mar-2001
Invensas Corporation	Employing an acidic liquid and an abrasive surface to polish a semiconductor topography	6200896	13-Mar-2001
Invensas Corporation	Semiconductor device with diffusion barrier included in electrical insulating layer	6201291	13-Mar-2001
Invensas Corporation	Low cost thermally enhanced flip chip bga	6201301	13-Mar-2001
Invensas Corporation	Pulse reverse electrodeposition for metallization and planarization of a semiconductor substrates	6203684	20-Mar-2001
Invensas Corporation	Laminate and method of manufacture thereof	6207595	27-Mar-2001
Invensas Corporation	Memory module	6208546	27-Mar-2001
Invensas Corporation	Electrodeposition of metals in small recesses for manufacture of high density interconnects using reverse pulse plating	6210555	03-Apr-2001
Invensas Corporation	Method for eliminating stress induced dislocation in cmos devices	6221735	24-Apr-2001
Invensas Corporation	Method and apparatus for refreshing a semiconductor memory using idle memory cycles	6222785	24-Apr-2001
Invensas Corporation	Differential sense amplifier with voltage margin enhancement	6225833	01-May-2001

Invensas Corporation	Circuit and method for encoding and retrieving a bit of information	6227637	08-May-2001
Invensas Corporation	Planarized semiconductor interconnect topography and method for polishing a metal layer to form interconnect	6232231	15-May-2001
Invensas Corporation	Method for improving attachment reliability of semiconductor chips and modules	6251766	26-Jun-2001
Invensas Corporation	Method for generating a clock phase signal for controlling operation of a dram array	6259651	10-Jul-2001
Invensas Corporation	Plasma processing methods and apparatus	6261375	17-Jul-2001
Invensas Corporation	Pad metallization over active circuitry	6261939	17-Jul-2001
Invensas Corporation	Conductive epoxy flip-chip on chip	6271598	07-Aug-2001
Invensas Corporation	Reduced skew timing scheme for write circuitry used in memory circuits	6278653	21-Aug-2001
Invensas Corporation	Semiconductor device and method for manufacturing the same	6281026	28-Aug-2001
Invensas Corporation	Substrate structure for improving attachment reliability of semiconductor chips and modules	6281581	28-Aug-2001
Invensas Corporation	Plasma processing methods and apparatus	6287976	11-Sep-2001

Invensas Corporation	Semiconductor device and method for manufacturing the same	6291309	18-Sep-2001
Invensas Corporation	Method of manufacturing a semiconductor device	6291352	18-Sep-2001
Invensas Corporation	Thermal deformation management for chip carriers	6291776	18-Sep-2001
Invensas Corporation	Semiconductor flip-chip assembly with pre-applied encapsulating layers	6297560	02-Oct-2001
Invensas Corporation	Asynchronous memory self time scheme	6301176	09-Oct-2001
Invensas Corporation	Electrodeposition of metals in small recesses using modulated electric fields	6303014	16-Oct-2001
Invensas Corporation	Sequential electrodeposition of metals using modulated electric fields for manufacture of circuit boards having features of different sizes	6309528	30-Oct-2001
Invensas Corporation	Method of making shallow junction semiconductor devices	6309937	30-Oct-2001
Invensas Corporation	High performance chip/package inductor integration	6310386	30-Oct-2001
Invensas Corporation	Delayed start oscillator circuit	6317007	13-Nov-2001

Invensas Corporation	Pulse reverse electrodeposition for metallization and planarization of semiconductor substrates	6319384	20-Nov-2001
Invensas Corporation	Data carrier having an implanted module based on a metal lead frame	6321993	27-Nov-2001
Invensas Corporation	Package of integrated circuits and vertical integration	6322903	27-Nov-2001
Invensas Corporation	Plasma processing methods and apparatus	6323134	27-Nov-2001
Invensas Corporation	High-speed read-write circuitry for semiconductor memory	6324110	27-Nov-2001
Invensas Corporation	Multiple row wire bonding with ball bonds of outer bond pads bonded on the leads	6329278	11-Dec-2001
Invensas Corporation	Method for preparing a conductive pad for electrical connection and conductive pad formed	6335104	1-Jan-2002
Invensas Corporation	Semiconductor flip-chip package and method for the fabrication thereof	6335571	01-Jan-2002
Invensas Corporation	Method for direct chip attach by solder bumps and an underfill layer	6341418	29-Jan-2002
Invensas Corporation	Circuit board component retention	6347732	19-Feb-2002
Invensas Corporation	Placement system apparatus and method	6355298	12-Mar-2002

Invensas Corporation	Employing an acidic liquid and an abrasive surface to polish a semiconductor topography	6361415	26-Mar-2002
Invensas Corporation	Stacked semiconductor device	6362529	26-Mar-2002
Invensas Corporation	Memory system for use on a circuit board in which the number of loads are minimized	6362997	26-Mar-2002
Invensas Corporation	Dram cell having a vertical transistor and a capacitor formed on the sidewalls of a trench isolation	6365452	02-Apr-2002
Invensas Corporation	Method of making a semiconductor device including testing before thinning the semiconductor substrate	6365513	02-Apr-2002
Invensas Corporation	Formation of a novel dram cell	6369418	09-Apr-2002
Invensas Corporation	Single-port multi-bank memory system having read and write buffers and method of operating same	6370073	09-Apr-2002
Invensas Corporation	High speed circuit of particular utility in delay and phase locked loops	6384654	07-May-2002
Invensas Corporation	Hybrid molds for molten solder screening process	6390439	21-May-2002
Invensas Corporation	Single reference plane plastic ball grid array package	6396140	28-May-2002

Invensas Corporation	Semiconductor flip-chip package and method for the fabrication thereof	6399426	04-Jun-2002
Invensas Corporation	Method for increasing trace rows of a ball grid array	6406936	18-Jun-2002
Invensas Corporation	Semiconductor blocking layer for preventing uv radiation damage to mos gate oxides	6410210	25-Jun-2002
Invensas Corporation	Method to reduce number of wire-bond loop heights versus the total quantity of power and signal rings	6414386	02-Jul-2002
Invensas Corporation	Local write driver circuit for an integrated circuit device incorporating embedded dynamic random access memory (dram)	6414897	02-Jul-2002
Invensas Corporation	Integrated circuits and methods for their fabrication	6420209	16-Jul-2002
Invensas Corporation	Monitoring and controlling separate plasma jets to achieve desired properties in a combined stream	6423923	23-Jul-2002
Invensas Corporation	Semiconductor devices configured to tolerate connection misalignment	6424028	23-Jul-2002
Invensas Corporation	Programmable moving inversion sequencer for memory bist address generation	6425103	23-Jul-2002

Invensas Corporation	Two-phase charge-sharing data latch for memory circuit	6434069	13-Aug-2002
Invensas Corporation	Nickel alloy films for reduced intermetallic formation in solder	6444562	03-Sep-2002
Invensas Corporation	Thinning and dicing of semiconductor wafers using dry etch, and obtaining semiconductor chips with rounded bottom edges and corners	6448153	10-Sep-2002
Invensas Corporation	Read/write buffers for complete hiding of the refresh of a semiconductor memory and method of operating same	6449685	10-Sep-2002
Invensas Corporation	Layout of vdd and vss balls in a four layer pbga	6452262	17-Sep-2002
Invensas Corporation	Conductive adhesive interconnection with insulating polymer carrier	6458623	01-Oct-2002
Invensas Corporation	Monitoring and controlling separate plasma jets to achieve desired properties in a combined stream	6462300	08-Oct-2002
Invensas Corporation	Reduced topography dram cell fabricated using a modified logic process and method for operating same	6468855	22-Oct-2002
Invensas Corporation	Enhanced laminate flipchip package using a high cte heatspreader	6472762	29-Oct-2002

Invensas Corporation	Hard mask process to control etch profiles in a gate stack	6475922	05-Nov-2002
Invensas Corporation	Memory controller arbitrating ras, cas and bank precharge signals	6477598	05-Nov-2002
Invensas Corporation	Method for manufacturing semiconductor device	6479306	12-Nov-2002
Invensas Corporation	Self-time scheme to reduce cycle time for memories	6483754	19-Nov-2002
Invensas Corporation	Tape design to reduce warpage	6486002	26-Nov-2002
Invensas Corporation	Wire bonding method and apparatus	6488198	03-Dec-2002
Invensas Corporation	Molded tape ball grid array package	6489571	03-Dec-2002
Invensas Corporation	Memory system for use on a circuit board in which the number of loads are minimized	6496404	17-Dec-2002
Invensas Corporation	Thinning and dicing of semiconductor wafers using dry etch, and obtaining semiconductor chips with rounded bottom edges and corners	6498074	24-Dec-2002
Invensas Corporation	Semiconductor structures having multiple conductive layers in an opening, and methods for fabricating same	6498381	24-Dec-2002
Invensas Corporation	Method and apparatus for completely hiding refresh operations in a dram device using clock division	6504780	07-Jan-2003

Invensas Corporation	Semiconductor flip-chip package and method for the fabrication thereof	6518677	11-Feb-2003
Invensas Corporation	Reduction of chip carrier flexing during thermal cycling	6528179	04-Mar-2003
Invensas Corporation	Semiconductor device and method of producing the same	6534874	18-Mar-2003
Invensas Corporation	High density design for organic chip carriers	6538213	25-Mar-2003
Invensas Corporation	Monitoring and controlling separate plasma jets to achieve desired properties in a combined stream	6541729	01-Apr-2003
Invensas Corporation	Ram having dynamically switchable access modes	6549483	15-Apr-2003
Invensas Corporation	Apparatus and method for delamination-resistant, array type molding of increased mold cap size laminate packages	6562272	13-May-2003
Invensas Corporation	Pbga electrical noise isolation of signal traces	6566167	20-May-2003
Invensas Corporation	Semiconductor flip-chip package and method for the fabrication thereof	6566234	20-May-2003
Invensas Corporation	Planarized semiconductor interconnect topography and method for polishing a metal layer to form wide interconnect structures	6566249	20-May-2003

Invensas Corporation	Method for direct chip attach by solder bumps and an underfill layer	6566612	20-May-2003
Invensas Corporation	Precharge and reference voltage technique for dynamic random access memories	6570799	27-May-2003
Invensas Corporation	Method of reforming reformable members of an electronic package and the resultant electronic package	6583354	24-Jun-2003
Invensas Corporation	Memory controller with arbitration among several strobe requests	6591323	08-Jul-2003
Invensas Corporation	Chip module with bond-wire connections with small loop height	6593664	15-Jul-2003
Invensas Corporation	Precision on-chip transmission line termination	6605958	12-Aug-2003
Invensas Corporation	Integrated circuit package substrate with high density routing mechanism	6608376	19-Aug-2003
Invensas Corporation	Automatic delay technique for early read and write operations in synchronous dynamic random access memories	6608797	19-Aug-2003
Invensas Corporation	Packaged integrated circuits and methods of producing thereof	6624505	23-Sep-2003
Invensas Corporation	Data path decoding technique for an embedded memory array	6625066	23-Sep-2003

Invensas Corporation	Data path decoding technique for an embedded memory array	6625069	23-Sep-2003
Invensas Corporation	Look-ahead refresh for an integrated circuit memory	6625078	23-Sep-2003
Invensas Corporation	Plasma processing methods and apparatus	6627039	30-Sep-2003
Invensas Corporation	Semiconductor blocking layer for preventing uv radiation damage to mos gate oxides	6627536	30-Sep-2003
Invensas Corporation	Detection and handling of semiconductor wafer and wafer-like objects	6631935	14-Oct-2003
Invensas Corporation	Article holders and article positioning methods	6638004	28-Oct-2003
Invensas Corporation	Integrated circuits and methods for their fabrication	6639303	28-Oct-2003
Invensas Corporation	Self-time scheme to reduce cycle time for memories	6643204	04-Nov-2003
Invensas Corporation	Simultaneous function dynamic random access memory device technique	6643212	04-Nov-2003
Invensas Corporation	Integrated circuit device	6646289	11-Nov-2003
Invensas Corporation	Reduced topography dram cell fabricated using a modified logic process and method for operating same	6654295	25-Nov-2003
Invensas Corporation	Apparatus for recording and/or reading program history	6662150	09-Dec-2003

Invensas Corporation	Integrated circuit structures with a conductor formed in a through hole in a semiconductor substrate and protruding from a surface of the substrate	6664129	16-Dec-2003
Invensas Corporation	Full additive process with filled plated through holes	6664485	16-Dec-2003
Invensas Corporation	Article holders with sensors detecting a type of article held by the holder	6665583	16-Dec-2003
Invensas Corporation	Brim and gas escape for non-contact wafer holder	6667242	23-Dec-2003
Invensas Corporation	Refresh initiated precharge technique for dynamic random access memory arrays using look-ahead refresh	6667927	23-Dec-2003
Invensas Corporation	Method of bonding wires	6672503	06-Jan-2004
Invensas Corporation	Method for forming a semiconductor structure using a disposable hardmask	6682996	27-Jan-2004
Invensas Corporation	Ground plane on 2 layer pbga	6687133	03-Feb-2004
Invensas Corporation	Detection and handling of semiconductor wafers and wafer-like objects	6688662	10-Feb-2004
Invensas Corporation	Semiconductor chip, wiring board and manufacturing process thereof as well as semiconductor device	6693358	17-Feb-2004

Invensas Corporation	Packaging of integrated circuits and vertical integration	6693361	17-Feb-2004
Invensas Corporation	Method of manufacturing a semiconductor device	6703270	09-Mar-2004
Invensas Corporation	Method and apparatus for completely hiding refresh operations in a dram device using multiple clock division	6707743	16-Mar-2004
Invensas Corporation	Buffering system bus for external-memory access	6708257	16-Mar-2004
Invensas Corporation	High performance chip/package inductor integration	6713375	30-Mar-2004
Invensas Corporation	High-speed read-write circuitry for semiconductor memory devices	6714470	30-Mar-2004
Invensas Corporation	Devices having substrates with opening passing through the substrates and conductors in the openings, and methods of manufacture	6717254	06-Apr-2004
Invensas Corporation	Chip carrier for a high-frequency electronic package	6717255	06-Apr-2004
Invensas Corporation	Memory testing for built-in self-repair system	6728910	27-Apr-2004
Invensas Corporation	Clock distribution networks and conductive lines in semiconductor integrated circuits	6730540	04-May-2004

Invensas Corporation	Folded-flex bondwire-less multichip power package	6731000	04-May-2004
Invensas Corporation	Test interface for verification of high speed embedded synchronous dynamic random access memory (sdram) circuitry	6732305	04-May-2004
Invensas Corporation	Integrated circuit with flash memory including dedicated flash bus and flash bridge	6735661	11-May-2004
Invensas Corporation	Integrated circuits and methods for their fabrication	6740582	25-May-2004
Invensas Corporation	Dram cell having a capacitor structure fabricated partially in a cavity and method for operating same	6744676	01-Jun-2004
Invensas Corporation	Asynchronous input data path technique for increasing speed and reducing latency in integrated circuit devices incorporating dynamic random access memory (dram) arrays and embedded dram	6744690	01-Jun-2004
Invensas Corporation	Method and packaging structure for optimizing warpage of flip chip organic packages	6747331	08-Jun-2004
Invensas Corporation	Method and apparatus for completely hiding refresh operations in a dram device using clock division	6751157	15-Jun-2004

Invensas Corporation	Method for manufacturing a structure comprising a substrate with a cavity and a semiconductor integrated circuit bonded to a contact pad located in the cavity	6753205	22-Jun-2004
Invensas Corporation	Wire bonding to dual metal covered pad surfaces	6759597	06-Jul-2004
Invensas Corporation	Ball assignment for ball grid array package	6762366	13-Jul-2004
Invensas Corporation	Jogging structure for wiring translation between grids with non-integral pitch ratios in chip carrier modules	6762489	13-Jul-2004
Invensas Corporation	Semiconductor device comprising a non-volatile memory	6765261	20-Jul-2004
Invensas Corporation	Partially captured oriented interconnections for bga packages and a method of forming the interconnections	6774474	10-Aug-2004
Invensas Corporation	Semiconductor flip-chip package and method for the fabrication thereof	6774493	10-Aug-2004
Invensas Corporation	Methods for producing packaged integrated circuit devices & packaged integrated circuit devices produced thereby	6777767	17-Aug-2004
Invensas Corporation	Integrated circuit package substrate with multiple voltage supplies	6777802	17-Aug-2004

Invensas Corporation	Method for fabricating a wiring substrate by electroplating a wiring film on a metal base	6782610	31-Aug-2004
Invensas Corporation	Pad metallization over active circuitry	6787908	07-Sep-2004
Invensas Corporation	Bitline reference voltage circuit	6788590	07-Sep-2004
Invensas Corporation	Integrated circuit packaging that uses guard conductors to isolate noise-sensitive signals within the package substrate	6791177	14-Sep-2004
Invensas Corporation	Formation of novel dram cell capacitors by integration of capacitors with isolation trench sidewalls	6794698	21-Sep-2004
Invensas Corporation	Method and apparatus for lengthening the data-retention time of a dram device in standby mode	6795364	21-Sep-2004
Invensas Corporation	Lead-free tin-silver-copper alloy solder composition	6805974	19-Oct-2004
Invensas Corporation	Method and apparatus for processing an array of packaged semiconductor devices	6806725	19-Oct-2004
Invensas Corporation	Non-volatile memory with crown electrode to increase capacitance between control gate and floating gate	6808169	26-Oct-2004
Invensas Corporation	Bandgap reference circuit	6815941	09-Nov-2004

Invensas Corporation	Stiffener design	6825066	30-Nov-2004
Invensas Corporation	Pbga electrical noise isolation of signal traces	6825554	30-Nov-2004
Invensas Corporation	Manufacturing method for wiring circuit substrates	6828221	07-Dec-2004
Invensas Corporation	Fabrication of semiconductor structures having multiple conductive layers in an opening	6844241	18-Jan-2005
Invensas Corporation	LOW TEMPERATURE SOLDER CHIP ATTACH STRUCTURE	6847118	25-Jan-2005
Invensas Corporation	Planarized semiconductor interconnect topography and method for polishing a metal layer to form interconnect	6849946	01-Feb-2005
Invensas Corporation	System and method for eliminating write backs with buffer for exception processing	6851044	01-Feb-2005
Invensas Corporation	STRUCTURE AND METHOD FOR LEAD FREE SOLDER ELECTRONIC PACKAGE INTERCONNECTIONS	6854636	15-Feb-2005
Invensas Corporation	Semiconductor chip, wiring board and manufacturing process thereof as well as semiconductor device	6856026	15-Feb-2005
Invensas Corporation	Semiconductor device	6858946	22-Feb-2005
Invensas Corporation	System and method for eliminating write back to register using dead field indicator	6862677	01-Mar-2005

Invensas Corporation	Sequential electrodeposition of metals using modulated electric fields for manufacture of circuit boards having features of different sizes	6863793	08-Mar-2005
Invensas Corporation	Row redundancy memory repair scheme with shift to eliminate timing penalty	6870782	22-Mar-2005
Invensas Corporation	Pulse reverse electrodeposition for metallization and planarization of semiconductor substrates	6878259	12-Apr-2005
Invensas Corporation	Memory i/o buffer using shared read/write circuitry	6879524	12-Apr-2005
Invensas Corporation	Integrated circuit structures with a conductor formed in a through hole in a semiconductor substrate and protruding from a surface of the substrate	6882030	19-Apr-2005
Invensas Corporation	Connecting member between wiring films, manufacturing method thereof, and manufacturing method of multilayer wiring substrate	6884709	26-Apr-2005
Invensas Corporation	Integrated circuit package substrate with high density routing mechanism	6891260	10-May-2005

Invensas Corporation	Integrated circuit package having bypass capacitors coupled to bottom of package substrate and supporting surface mounting technology	6894385	17-May-2005
Invensas Corporation	Ram having dynamically switchable access modes	6894941	17-May-2005
Invensas Corporation	Electroplating and electroless plating of conductive materials into openings, and structures obtained thereby	6897148	24-May-2005
Invensas Corporation	Integrated circuit package and method for a pbga package having a multiplicity of staggered power ring segments for power connection to integrated circuit die	6897555	24-May-2005
Invensas Corporation	Method and apparatus for temperature adaptive refresh in 1t-sram compatible memory using the subthreshold characteristics of mosfet transistors	6898140	24-May-2005
Invensas Corporation	Non-contiguous masked refresh for an integrated circuit memory	6912168	28-Jun-2005
Invensas Corporation	Stress accommodation in electronic device interconnect technology for millimeter contact locations	6919515	19-Jul-2005

Invensas Corporation	Method of forming filled blind vias	6924224	02-Aug-2005
Invensas Corporation	Semiconductor device provided with rewiring layer	6927489	09-Aug-2005
Invensas Corporation	Organic dielectric electronic interconnect structures and method for making	6931723	23-Aug-2005
Invensas Corporation	Method to reduce number of wire-bond loop heights versus the total quantity of power and signal rings	6946746	20-Sep-2005
Invensas Corporation	Methods of manufacturing devices having substrates with opening passing through the substrates and conductors in the openings	6958285	25-Oct-2005
Invensas Corporation	Semiconductor device and method for manufacturing the same	6969623	29-Nov-2005
Invensas Corporation	Methods and apparatus for packaging integrated circuit devices	6972480	06-Dec-2005
Invensas Corporation	Method of reforming reformable members of an electronic package and the resultant electronic package	6978542	27-Dec-2005
Invensas Corporation	Substrate alignment method and apparatus	6983872	10-Jan-2006

Invensas Corporation	LOW TEMPERATURE SOLDER CHIP ATTACH STRUCTURE AND PROCESS TO PRODUCE A HIGH TEMPERATURE INTERCONNECTION	6994243	7-Feb-2006
Invensas Corporation	Ball grid array module	6994803	07-Feb-2006
Invensas Corporation	Method for forming robust solder interconnect structures by reducing effects of seed layer underetching	6995084	07-Feb-2006
Invensas Corporation	I/c chip suitable for wire bonding	6995475	07-Feb-2006
Invensas Corporation	Semiconductor structures having multiple conductive layers in an opening, and methods for fabricating same	7001825	21-Feb-2006
Invensas Corporation	Dual word line mode for drams	7002874	21-Feb-2006
Invensas Corporation	Method of reforming reformable members of an electronic package and the resultant electronic package	7014094	21-Mar-2006
Invensas Corporation	Method and packaging structure for optimizing warpage of flip chip organic packages	7026706	11-Apr-2006
Invensas Corporation	Methods for producing packaged integrated circuit devices and packaged integrated circuit devices produced thereby	7033664	25-Apr-2006

Invensas Corporation	Packaging substrates for integrated circuits and soldering methods	7034401	25-Apr-2006
Invensas Corporation	Integrated circuits and packaging substrates with cavities, and attachment methods including insertion of protruding contact pads into cavities	7049170	23-May-2006
Invensas Corporation	Designing a ball assignment for a ball grid array package	7051434	30-May-2006
Invensas Corporation	Fabrication method of semiconductor device	7052934	30-May-2006
Invensas Corporation	Memory system	7055072	30-May-2006
Invensas Corporation	Packaging substrates for integrated circuits and soldering methods	7060601	13-Jun-2006
Invensas Corporation	Memory implementation for handling integrated circuit fabrication faults	7062695	13-Jun-2006
Invensas Corporation	Method and apparatus for transferring solder bumps	7070087	04-Jul-2006
Invensas Corporation	Electronic package with filled blinds vias	7084509	01-Aug-2006
Invensas Corporation	Packaging integrated circuits with adhesive posts	7094966	22-Aug-2006
Invensas Corporation	Manufacturing method for wiring circuit substrate	7096578	29-Aug-2006
Invensas Corporation	Detection and handling of semiconductor wafers and wafer-like objects	7104579	12-Sep-2006

Invensas Corporation	Routing scheme for differential pairs in flip chip substrates	7105926	12-Sep-2006
Invensas Corporation	Method and system of testing data retention of memory	7117408	03-Oct-2006
Invensas Corporation	Quad flat non-leaded package comprising a semiconductor device	7119421	10-Oct-2006
Invensas Corporation	Wide-range programmable delay line	7119596	10-Oct-2006
Invensas Corporation	Leadframe with enhanced encapsulation adhesion	7125750	24-Oct-2006
Invensas Corporation	Methods for producing packaged integrated circuit devices & packaged integrated circuit devices produced thereby	7144745	05-Dec-2006
Invensas Corporation	Integrated circuit device	7157742	02-Jan-2007
Invensas Corporation	Reduced gate delay multiplexed interface and output buffer circuit for integrated circuit devices incorporating random access memory arrays	7161214	09-Jan-2007
Invensas Corporation	Clock distribution networks and conductive lines in semiconductor integrated circuits	7173327	06-Feb-2007

Invensas Corporation	Integrated circuits and packaging substrates with cavities, and attachment methods including insertion of protruding contact pads into cavities	7186586	06-Mar-2007
Invensas Corporation	METHODS AND APPARATUS FOR PACKAGING INTEGRATED CIRCUIT DEVICES	7192796	20-Mar-2007
Invensas Corporation	Method of fabricating a wire bond with multiple stitch bonds	7214606	08-May-2007
Invensas Corporation	STACKED DIE BGA OR LGA COMPONENT ASSEMBLY	7215018	8-May-2007
Invensas Corporation	Semiconductor device, module for optical devices, and manufacturing method of semiconductor device	7221051	22-May-2007
Invensas Corporation	Attachment of integrated circuit structures and other substrates to substrates with vias	7241641	10-Jul-2007
Invensas Corporation	Attachment of integrated circuit structures and other substrates to substrates with vias	7241675	10-Jul-2007
Invensas Corporation	Micropede stacked die component assembly	7245021	17-Jul-2007
Invensas Corporation	Coarse delay tuner circuits with edge suppressors in delay locked loops	7248087	24-Jul-2007

Invensas Corporation	Organic dielectric electronic interconnect structures and method for making	7253512	07-Aug-2007
Invensas Corporation	Methods and apparatus for packaging integrated circuit devices	7265440	04-Sep-2007
Invensas Corporation	Word line driver for dram embedded in a logic process	7274618	25-Sep-2007
Invensas Corporation	Transparent error correcting memory that supports partial-word write	7275200	25-Sep-2007
Invensas Corporation	Wafer-leveled chip packaging structure and method thereof	7294920	13-Nov-2007
Invensas Corporation	Semiconductor device and method for fabricating the same	7297624	20-Nov-2007
Invensas Corporation	Layout area efficient, high speed, dynamic multi-input exclusive or (xor) and exclusive nor (xnor) logic gate circuit designs for integrated circuit devices	7298171	20-Nov-2007
Invensas Corporation	Two layer substrate ball grid array design	7327043	05-Feb-2008
Invensas Corporation	Multilayer wiring board for an electronic device	7342802	11-Mar-2008
Invensas Corporation	Integrated circuit with dynamic communication service selection	7346726	18-Mar-2008
Invensas Corporation	Hierarchical memory access via pipelining with deferred arbitration	7353310	01-Apr-2008

Invensas Corporation	Data carrier with a module with a reinforcement strip	7361976	22-Apr-2008
Invensas Corporation	Semiconductor device and fabrication method thereof	7365440	29-Apr-2008
Invensas Corporation	Predictive error correction code generation facilitating a high-speed byte-write in a semiconductor memory	7392456	24-Jun-2008
Invensas Corporation	Ball grid array assignment	7405946	29-Jul-2008
Invensas Corporation	Packaged integrated circuits and methods of producing thereof	7408249	05-Aug-2008
Invensas Corporation	High speed interface design	7414322	19-Aug-2008
Invensas Corporation	Heat spreader in integrated circuit package	7420809	02-Sep-2008
Invensas Corporation	Method of forming electrode for semiconductor device	7442642	28-Oct-2008
Invensas Corporation	Methods and apparatus for rf shielding in vertically-integrated semiconductor devices	7446017	04-Nov-2008
Invensas Corporation	Method and system for powering an integrated circuit	7446559	04-Nov-2008
Invensas Corporation	Version-programmable circuit module	7454188	18-Nov-2008
Invensas Corporation	Method for forming robust solder interconnect structures by reducing effects of seed layer underetching	7473997	06-Jan-2009

Invensas Corporation	METHODS AND APPARATUS FOR PACKAGING INTEGRATED CIRCUIT DEVICES	7479398	20-Jan-2009
Invensas Corporation	Method of forming low wire loops and wire loops formed using the method	7494042	24-Feb-2009
Invensas Corporation	METHODS AND APPARATUS FOR PACKAGING INTEGRATED CIRCUIT DEVICES	7495341	24-Feb-2009
Invensas Corporation	Multilayer wiring board for an electronic device	7505281	17-Mar-2009
Invensas Corporation	Static random access memory (sram) compatible, high availability memory array and method employing synchronous dynamic random access memory (dram) in conjunction with a data cache and separate read and write registers and tag blocks	7506100	17-Mar-2009
Invensas Corporation	DIELECTRIC TRENCHES, NICKEL/TANTALUM OXIDE STRUCTURES, AND CHEMICAL MECHANICAL POLISHING TECHNIQUES	7510928	31-Mar-2009
Invensas Corporation	Electronic device and method of manufacturing thereof	7514801	07-Apr-2009

Invensas Corporation	Electroplating and electroless plating of conductive materials into openings, and structures obtained thereby	7521360	21-Apr-2009
Invensas Corporation	Non-volatile memory embedded in a conventional logic process and methods for operating same	7522456	21-Apr-2009
Invensas Corporation	Wafer-leveled chip packaging structure and method thereof	7528009	05-May-2009
Invensas Corporation	Method and apparatus for packaging circuit devices	7535093	19-May-2009
Invensas Corporation	Die assembly having electrical interconnect	7535109	19-May-2009
Invensas Corporation	Manufacturing method for wiring circuit substrate	7546681	16-Jun-2009
Invensas Corporation	Wafer bonding method of system in package	7553743	30-Jun-2009
Invensas Corporation	Semiconductor device and method of manufacturing a semiconductor device	7553759	30-Jun-2009
Invensas Corporation	Method and apparatus of power ring positioning to minimize crosstalk	7569472	04-Aug-2009
Invensas Corporation	Method of forming a bond pad on an i/c chip and resulting structure	7572726	11-Aug-2009
Invensas Corporation	Packaged stacked semiconductor device and method for manufacturing the same	7576413	18-Aug-2009

Invensas Corporation	Wirebonding method and apparatus	7578425	25-Aug-2009
Invensas Corporation	Multiple bus charge sharing	7580304	25-Aug-2009
Invensas Corporation	Interconnections in simd processor architectures	7596679	29-Sep-2009
Invensas Corporation	Stacked integrated circuit assembly	7605477	20-Oct-2009
Invensas Corporation	Optimized charge sharing for data bus skew applications	7606093	20-Oct-2009
Invensas Corporation	Switched capacitor charge sharing technique for integrated circuit devices enabling signal generation of disparate selected signal values	7609570	27-Oct-2009
Invensas Corporation	DATA INVERSION REGISTER TECHNIQUE FOR INTEGRATED CIRCUIT MEMORY TESTING	7631233	8-Dec-2009
Invensas Corporation	Non-volatile memory embedded in a conventional logic process and methods for operating same	7633810	15-Dec-2009
Invensas Corporation	Non-volatile memory embedded in a conventional logic process and methods for operating same	7633811	15-Dec-2009
Invensas Corporation	Methods and apparatus for packaging integrated circuit devices	7642629	05-Jan-2010
Invensas Corporation	Processor bus arrangement	7647445	12-Jan-2010

Invensas Corporation	Short-circuit charge-sharing technique for integrated circuit devices	7649406	19-Jan-2010
Invensas Corporation	Non-volatile memory in cmos logic process	7671401	02-Mar-2010
Invensas Corporation	Integrated circuit package device with improved bond pad connections, a lead-frame and an electronic device	7671474	02-Mar-2010
Invensas Corporation	Scalable embedded dram array	7684229	23-Mar-2010
Invensas Corporation	Producing a covered through substrate via using a temporary cap layer	7704881	27-Apr-2010
Invensas Corporation	Three dimensional six surface conformal die coating	7705432	27-Apr-2010
Invensas Corporation	Methods of making microelectronic assemblies	7721422	25-May-2010
Invensas Corporation	Semiconductor device	7727807	01-Jun-2010
Invensas Corporation	Forming robust solder interconnect structures by reducing effects of seed layer underetching	7767575	03-Aug-2010
Invensas Corporation	Integrated circuit device	7781240	24-Aug-2010
Invensas Corporation	Integrated circuit embedded with non-volatile one-time-programmable and multiple-time programmable memory	7782668	24-Aug-2010

Invensas Corporation	Integrated circuit embedded with non-volatile multiple-time programmable memory having variable coupling	7787295	31-Aug-2010
Invensas Corporation	Method of making integrated circuit embedded with non-volatile one-time-programmable and multiple-time programmable memory	7787304	31-Aug-2010
Invensas Corporation	Method of making integrated circuit embedded with non-volatile one-time-programmable and multiple-time programmable memory	7787309	31-Aug-2010
Invensas Corporation	Method of forming an interconnect structure	7790606	07-Sep-2010
Invensas Corporation	Semiconductor through silicon vias of variable size and method of formation	7803714	28-Sep-2010
Invensas Corporation	Wafer-level fabrication of lidded chips with electrodeposited dielectric coating	7807508	05-Oct-2010
Invensas Corporation	Method for processing copper surface, method for forming copper pattern wiring and semiconductor device manufactured using such method	7825026	02-Nov-2010

Invensas Corporation	Packaged semiconductor device and method of manufacturing the packaged semiconductor device	7838983	23-Nov-2010
Invensas Corporation	Integrated circuit embedded with non-volatile programmable memory having variable coupling	7852672	14-Dec-2010
Invensas Corporation	Electronic device and method of manufacturing thereof	7858444	28-Dec-2010
Invensas Corporation	Semiconductor die separation method	7863159	04-Jan-2011
Invensas Corporation	Semiconductor chip, method of fabricating the same and semiconductor chip stack package	7863747	04-Jan-2011
Invensas Corporation	Method and apparatus for packaging circuit devices	7867874	11-Jan-2011
Invensas Corporation	Method of operating integrated circuit embedded with non-volatile programmable memory having variable coupling related application data	7876615	25-Jan-2011
Invensas Corporation	Semiconductor device and fabricating method thereof	7880292	01-Feb-2011
Invensas Corporation	Stacked integrated circuit assembly	7888176	15-Feb-2011

Invensas Corporation	Non-volatile memory programmable through areal capacitive coupling	7920426	05-Apr-2011
Invensas Corporation	Wafer level surface passivation of stackable integrated circuit chips	7923349	12-Apr-2011
Invensas Corporation	Structure and method of making interconnect element, and multilayer wiring board including the interconnect element	7923828	12-Apr-2011
Invensas Corporation	Wafer-level fabrication of lidded chips with electrodeposited dielectric coating	7935568	03-May-2011
Invensas Corporation	Through substrate vias for back-side interconnections on very thin semiconductor wafers	7935571	03-May-2011
Invensas Corporation	Wafer level chip packaging	7936062	03-May-2011
Invensas Corporation	Chip packages with covers	7939918	10-May-2011
Invensas Corporation	Formation of a through-electrode by inkjet deposition of resin pastes	7955974	07-Jun-2011

Invensas Corporation	TECHNIQUE FOR REDUCING PARITY BIT-WIDTHS FOR CHECK BIT AND SYNDROME GENERATION FOR DATA BLOCKS THROUGH THE USE OF ADDITIONAL CHECK BITS TO INCREASE THE NUMBER OF MINIMUM WEIGHTED CODES IN THE HAMMING CODE H-MATRIX	7962837	14-Jun-2011
Invensas Corporation	Dielectric trenches, nickel/tantalum oxide structures, and chemical mechanical polishing techniques	7964508	21-Jun-2011
Invensas Corporation	Semiconductor device and method for fabricating the same	7968965	28-Jun-2011
Invensas Corporation	Method and apparatus for packaging circuit devices	7977208	12-Jul-2011
Invensas Corporation	Method of manufacturing semiconductor device with electrode for external connection and semiconductor device obtained by means of said method	8017452	13-Sep-2011
Invensas Corporation	Multi-layered metal interconnection	8030779	04-Oct-2011
Invensas Corporation	Method for forming a through silicon via (tsv)	8039386	18-Oct-2011

Invensas Corporation	Semiconductor chip, method of fabricating the same and stack package having the same	8039962	18-Oct-2011
Invensas Corporation	Method of forming metal electrode of system in package	8053362	08-Nov-2011
Invensas Corporation	Semiconductor chip package with post electrodes	8110911	07-Feb-2012
Invensas Corporation	Flat leadless packages and stacked leadless package assemblies	8159053	17-Apr-2012
Invensas Corporation	Support mounted electrically interconnected die assembly	8178978	15-May-2012
Invensas Corporation	Semiconductor packaging process using through silicon vias	8193615	05-Jun-2012
Invensas Corporation	Non-volatile one-time-programmable and multiple-time programmable memory configuration circuit	8203861	19-Jun-2012
Invensas Corporation	Integrated circuit embedded with non-volatile programmable memory having variable coupling and separate read/write paths	8208299	26-Jun-2012

Invensas Corporation	Circuit and technique for reducing parity bit-widths for check bit and syndrome generation for data blocks through the use of additional check bits to increase the number of minimum weighted codes in the hamming code h-matrix	8239740	07-Aug-2012
Invensas Corporation	Stub minimization for multi-die wirebond assemblies with orthogonal windows	8254155	28-Aug-2012
Invensas Corporation	Method of producing semiconductor device and semiconductor device	8278738	02-Oct-2012
Invensas Corporation	Stub minimization for multi-die wirebond assemblies with orthogonal windows	8278764	02-Oct-2012
Invensas Corporation	Error correction code (ecc) circuit test mode	8281219	02-Oct-2012
Invensas Corporation	Methods for forming through-substrate conductor filled vias, and electronic assemblies formed using such methods	8283207	09-Oct-2012
Invensas Corporation	Interconnection element for electric circuits	8299368	30-Oct-2012
Invensas Corporation	Two terminal programmable hot channel electron non-volatile memory	8300470	30-Oct-2012

Invensas Corporation	Common drain non-volatile multiple-time programmable memory	8305805	06-Nov-2012
Invensas Corporation	CHIPS HAVING REAR CONTACTS CONNECTED BY THROUGH VIAS TO FRONT CONTACTS	8310036	13-Nov-2012
Invensas Corporation	Semiconductor package device	8314482	20-Nov-2012
Invensas Corporation	Wafer level surface passivation of stackable integrated circuit chips	8324081	04-Dec-2012
Invensas Corporation	Method of operating integrated circuit embedded with non-volatile programmable memory having variable coupling related application data	8325519	04-Dec-2012
Invensas Corporation	3-d circuits with integrated passive devices	8344503	01-Jan-2013
Invensas Corporation	Stub minimization for multi-die wirebond assemblies with parallel windows	8345441	01-Jan-2013
Invensas Corporation	Semiconductor device manufacturing method and semiconductor device	8349736	08-Jan-2013
Invensas Corporation	ASSEMBLY HAVING STACKED DIE MOUNTED ON SUBSTRATE	8357999	22-Jan-2013

Invensas Corporation	Method for package-on-package assembly with wire bonds to encapsulation surface	8372741	12-Feb-2013
Invensas Corporation	Electronic component used for wiring and method for manufacturing the same	8399980	19-Mar-2013
Invensas Corporation	Package-on-package assembly with wire bond vias	8404520	26-Mar-2013
Invensas Corporation	CHIPS HAVING REAR CONTACTS CONNECTED BY THROUGH VIAS TO FRONT CONTACTS	8405196	23-Mar-2013
Invensas Corporation	Stub minimization for wirebond assemblies without windows	8405207	26-Mar-2013
Invensas Corporation	Structures with through vias passing through a substrate comprising a planar insulating layer between semiconductor layers	8431431	30-Apr-2013
Invensas Corporation	Stub minimization for multi-die wirebond assemblies with parallel windows	8436457	07-May-2013
Invensas Corporation	Stub minimization using duplicate sets of signal terminals in assemblies without wirebonds to package substrate	8436477	07-May-2013
Invensas Corporation	Stub minimization for multi-die wirebond assemblies with parallel windows	8441111	14-May-2013

Invensas Corporation	Microelectronic interconnect element with decreased conductor spacing	8461460	11-Jun-2013
Invensas Corporation	Semiconductor device and method for manufacturing semiconductor device	8471367	25-Jun-2013
Invensas Corporation	Wirebonding method and apparatus	8474680	02-Jul-2013
Invensas Corporation	Circuit and technique for reducing parity bit-widths for check bit and syndrome generation for data blocks through the use of additional check bits to increase the number of minimum weighted codes in the hamming code h-matrix	8510641	13-Aug-2013
Invensas Corporation	Stub minimization using duplicate sets of terminals for wirebond assemblies without windows	8513813	20-Aug-2013
Invensas Corporation	Memory module in a package	8513817	20-Aug-2013
Invensas Corporation	Stub minimization for assemblies without wirebonds to package substrate	8525327	03-Sep-2013
Invensas Corporation	Chip-size double side connection package and method for manufacturing the same	8557700	15-Oct-2013

Invensas Corporation	Non-volatile one-time-programmable and multiple-time programmable memory having variable coupling and multilevel capability	8580622	12-Nov-2013
Invensas Corporation	Non-volatile one-time-programmable and multiple-time programmable memory configuration circuit	8582342	12-Nov-2013
Invensas Corporation	Wafer-leveled chip package structure and method thereof	8587091	19-Nov-2013
Invensas Corporation	Integrated circuit device	8592831	26-Nov-2013
Invensas Corporation	Method of operating integrated circuit embedded with non-volatile programmable memory having variable coupling related application data	8599612	03-Dec-2013
Invensas Corporation	Microelectronic assembly with multi-layer support structure	8604605	10-Dec-2013
Invensas Corporation	Stub minimization for assemblies without wirebonds to package substrate	8610260	17-Dec-2013
Invensas Corporation	Rear-face illuminated solid state image sensors	8624342	07-Jan-2014
Invensas Corporation	Chips with high fracture toughness through a metal ring	8624348	07-Jan-2014
Invensas Corporation	Electrically interconnected stacked die assemblies	8629543	14-Jan-2014

Invensas Corporation	Stub minimization for assemblies without wirebonds to package substrate	8629545	14-Jan-2014
Invensas Corporation	Dielectric trenches, nickel/tantalum oxide structures, and chemical mechanical polishing techniques	8633589	21-Jan-2014
Invensas Corporation	Flip chip package for dram with two underfill materials	8637992	28-Jan-2014
Invensas Corporation	Stub minimization using duplicate sets of terminals for wirebond assemblies without windows	8653646	18-Feb-2014
Invensas Corporation	Stub minimization using duplicate sets of signal in assemblies without wirebonds to package substrate	8659139	25-Feb-2014
Invensas Corporation	Stub minimization using duplicate sets of signal terminals in assemblies without wirebonds to package substrate	8659140	25-Feb-2014
Invensas Corporation	Stub minimization using duplicate sets of terminals for wirebond assemblies without windows	8659141	25-Feb-2014
Invensas Corporation	Stub minimization for wirebond assemblies without windows	8659142	25-Feb-2014
Invensas Corporation	Stub minimization for wirebond assemblies without windows	8659143	25-Feb-2014
Invensas Corporation	Parallel plate slot emission array	8664681	04-Mar-2014

Invensas Corporation	Stub minimization using duplicate sets of signal terminals	8670261	11-Mar-2014
Invensas Corporation	Stackable microelectronic package structures	8680684	25-Mar-2014
Invensas Corporation	Electrical interconnect for die stacked in zig-zag configuration	8680687	25-Mar-2014
Invensas Corporation	Microelectronic assembly tolerant to misplacement of microelectronic elements therein	8698323	15-Apr-2014
Invensas Corporation	Semiconductor die mount by conformal die coating	8704379	22-Apr-2014
Invensas Corporation	Non-volatile one-time-programmable and multiple-time programmable memory configuration circuit	8705263	22-Apr-2014
Invensas Corporation	Methods of forming 3-d circuits with integrated passive devices	8722459	13-May-2014
Invensas Corporation	Microelectronic package with stacked microelectronic units and method for manufacture thereof	8723327	13-May-2014
Invensas Corporation	In-package fly-by signaling	8723329	13-May-2014
Invensas Corporation	Electrically interconnected stacked die assemblies	8723332	13-May-2014
Invensas Corporation	Assembly having stacked die mounted on substrate	8729690	20-May-2014

Invensas Corporation	CHIPS HAVING REAR CONTACTS CONNECTED BY THROUGH VIAS TO FRONT CONTACTS	8735205	27-May-2014
Invensas Corporation	Semiconductor packaging process using through silicon vias	8735287	27-May-2014
Invensas Corporation	Structure and method of making interconnect element having metal traces embedded in surface of dielectric	8736064	27-May-2014
Invensas Corporation	Vertical electrical interconnect formed on support prior to die mount	8742602	03-Jun-2014
Invensas Corporation	Optical interposer	8757897	24-Jun-2014
Invensas Corporation	Method for package-on-package assembly with wire bonds to encapsulation surface	8772152	08-Jul-2014
Invensas Corporation	Reduced stress tsv and interposer structures	8772946	08-Jul-2014
Invensas Corporation	Low cte interposer	8780576	15-Jul-2014
Invensas Corporation	High strength through-substrate vias	8785790	22-Jul-2014
Invensas Corporation	Heat spreading substrate	8785961	22-Jul-2014
Invensas Corporation	Reconfigurable pop	8786069	22-Jul-2014
Invensas Corporation	Co-support system and microelectronic assembly	8787034	22-Jul-2014
Invensas Corporation	Method of processing a device substrate	8790996	29-Jul-2014
Invensas Corporation	High performance light emitting diode with vias	8816383	26-Aug-2014

Invensas Corporation	Memory module in a package	8823165	02-Sep-2014
Invensas Corporation	SEMICONDUCTOR DIE HAVING FINE PITCH ELECTRICAL INTERCONNECTS	8829677	9-Sep-2014
Invensas Corporation	Structures with through vias passing through a substrate comprising a planar insulating layer between semiconductor layers	8829683	09-Sep-2014
Invensas Corporation	Substrate-less stackable package with wire-bond interconnect	8835228	16-Sep-2014
Invensas Corporation	Package-on-package assembly with wire bond vias	8836136	16-Sep-2014
Invensas Corporation	High yield substrate assembly	8841204	23-Sep-2014
Invensas Corporation	Thin wafer handling and known good die test method	8846447	30-Sep-2014
Invensas Corporation	Microelectronic assembly with thermally and electrically conductive underfill	8847412	30-Sep-2014
Invensas Corporation	Co-support component and microelectronic assembly	8848391	30-Sep-2014
Invensas Corporation	Co-support module and microelectronic assembly	8848392	30-Sep-2014
Invensas Corporation	Structure and method of making interconnect element, and multilayer wiring board including the interconnect element	8859420	14-Oct-2014

Invensas Corporation	Chips with high fracture toughness through a metal ring	8865570	21-Oct-2014
Invensas Corporation	Common doped region with separate gate control for a logic compatible non-volatile memory cell	8873302	28-Oct-2014
Invensas Corporation	Structure for microelectronic packaging with bond elements to encapsulation surface	8878353	04-Nov-2014
Invensas Corporation	Fabrication of microelectronic assemblies having stack terminals coupled by connectors extending through encapsulation	8883563	11-Nov-2014
Invensas Corporation	Semiconductor die separation method	8884403	11-Nov-2014
Invensas Corporation	Low cte interposer without tsv structure and method	8884427	11-Nov-2014
Invensas Corporation	Microelectronic interconnect element with decreased conductor spacing	8900464	02-Dec-2014
Invensas Corporation	Rear-face illuminated solid state image sensors	8900910	02-Dec-2014
Invensas Corporation	High yield substrate assembly	8900974	02-Dec-2014
Invensas Corporation	Multi-die wirebond packages with elongated windows	8907500	09-Dec-2014
Invensas Corporation	Front facing piggyback wafer assembly	8912024	16-Dec-2014

Invensas Corporation	Stacked die assembly having reduced stress electrical interconnects	8912661	16-Dec-2014
Invensas Corporation	Cavities containing multi-wiring structures and devices	8916781	23-Dec-2014
Invensas Corporation	Stub minimization with terminal grids offset from center of package	8917532	23-Dec-2014
Invensas Corporation	Method of making wire bond vias and microelectronic package having wire bond vias	8940630	27-Jan-2015
Invensas Corporation	Non-crystalline inorganic light emitting diode	8941111	27-Jan-2015
Invensas Corporation	Manufacture of face-down microelectronic packages	8945987	03-Feb-2015
Invensas Corporation	Heat spreading substrate with embedded interconnects	8946757	03-Feb-2015
Invensas Corporation	Via in substrate with deposited layer	8946899	03-Feb-2015
Invensas Corporation	Microelectronic package and method of manufacture thereof	8946901	03-Feb-2015
Invensas Corporation	Methods of fabricating a flip chip package for DRAM with two underfill materials	8951845	10-Feb-2015
Invensas Corporation	Tunable composite interposer	8963335	24-Feb-2015

Invensas Corporation	Embedded heat spreader for package with multiple microelectronic elements and face-down connection	8970028	03-Mar-2015
Invensas Corporation	Improved quantum efficiency of multiple quantum wells	8975616	10-Mar-2015
Invensas Corporation	Structure for microelectronic packaging with terminals on dielectric mass	8975738	10-Mar-2015
Invensas Corporation	Tsv fabrication using a removable handling structure	8978247	17-Mar-2015
Invensas Corporation	Stackable microelectronic package structures	8980693	17-Mar-2015
Invensas Corporation	Stub minimization for multi-die wirebond assemblies with parallel windows	8981547	17-Mar-2015
Invensas Corporation	Metal pvd-free conducting structures	8981564	17-Mar-2015
Invensas Corporation	Microelectronic unit and package with positional reversal	8994170	31-Mar-2015
Invensas Corporation	Reduced stress tsv and interposer structures	9000600	07-Apr-2015
Invensas Corporation	Retention optimized memory device using predictive data inversion	9007866	14-Apr-2015

Invensas Corporation	Substrates with through vias with conductive features for connection to integrated circuit elements, and methods for forming through vias in substrates	9018094	28-Apr-2015
Invensas Corporation	Microelectronic assemblies with stack terminals coupled by connectors extending through encapsulation	9023691	05-May-2015
Invensas Corporation	Advanced device assembly structures and methods	9024205	05-May-2015
Invensas Corporation	Z-connection using electroless plating	9030017	12-May-2015
Invensas Corporation	Microelectronic assemblies having reinforcing collars on connectors extending through encapsulation	9034696	19-May-2015
Invensas Corporation	Package-on-package assembly with wire bond vias	9041227	26-May-2015
Invensas Corporation	Wafer-leveled chip packaging structure and method thereof	9059181	16-Jun-2015
Invensas Corporation	Methods and structure for carrier-less thin wafer handling	9064933	23-Jun-2015
Invensas Corporation	Single package dual channel memory with co-support	9070423	30-Jun-2015
Invensas Corporation	Bowl-shaped solder structure	9070676	30-Jun-2015
Invensas Corporation	Parallel plate slot emission array	9070849	30-Jun-2015
Invensas Corporation	Capacitors using porous alumina structures	9076594	07-Jul-2015

Invensas Corporation	Method and structures for via substrate repair and assembly	9076785	07-Jul-2015
Invensas Corporation	Severing bond wire by kinking and twisting	9082753	14-Jul-2015
Invensas Corporation	Off substrate kinking of bond wire	9087815	21-Jul-2015
Invensas Corporation	Structure for microelectronic packaging with bond elements to encapsulation surface	9095074	28-Jul-2015
Invensas Corporation	Method of processing a device substrate	9099482	04-Aug-2015
Invensas Corporation	Package-on-package assembly with wire bond vias	9105483	11-Aug-2015
Invensas Corporation	On-chip impedance network with digital coarse and analog fine tuning	9111671	18-Aug-2015
Invensas Corporation	Dielectric trenches, nickel/tantalum oxide structures, and chemical mechanical polishing techniques	9111902	18-Aug-2015
Invensas Corporation	Method of thinning a wafer to provide a raised peripheral edge	9111946	18-Aug-2015
Invensas Corporation	Co-support for xfd packaging	9123555	01-Sep-2015
Invensas Corporation	Microelectronic package with consolidated chip structures	9123600	01-Sep-2015
Invensas Corporation	Method and structures for heat dissipating interposers	9123780	01-Sep-2015

Invensas Corporation	Microelectronic package having wire bond vias and stiffening layer	9136254	15-Sep-2015
Invensas Corporation	Structures with through vias passing through a substrate comprising a planar insulating layer between semiconductor layers	9142511	22-Sep-2015
Invensas Corporation	Selective die electrical insulation by additive process	9147583	29-Sep-2015
Invensas Corporation	Electrical connector between die pad and z-interconnect for stacked die assemblies	9153517	06-Oct-2015
Invensas Corporation	Microelectronic elements with master/slave configurability	9153533	06-Oct-2015
Invensas Corporation	Making electrical components in handle wafers of integrated circuit packages	9165793	20-Oct-2015
Invensas Corporation	High performance package on package	9165906	20-Oct-2015
Invensas Corporation	Microelectronic package with stacked microelectronic units and method for manufacture thereof	9165911	20-Oct-2015
Invensas Corporation	Embedded packaging with preformed vias	9167710	20-Oct-2015
Invensas Corporation	Emi shield	9196588	24-Nov-2015
Invensas Corporation	Batch process fabrication of package-on-package microelectronic assemblies	9214454	15-Dec-2015

Invensas Corporation	Stub minimization with terminal grids offset from center of package	9214455	15-Dec-2015
Invensas Corporation	Microelectronic unit and package with positional reversal	9219050	22-Dec-2015
Invensas Corporation	Stub minimization using duplicate sets of signal terminals	9224431	29-Dec-2015
Invensas Corporation	Method of making integrated circuit embedded with non-volatile programmable memory having variable coupling	9224739	29-Dec-2015
Invensas Corporation	Porous alumina templates for electronic packages	9226396	29-Dec-2015
Invensas Corporation	Non-volatile memory devices having vertical drain to gate capacitive coupling	9230814	05-Jan-2016
Invensas Corporation	Methods of forming 3-d circuits with integrated passive devices	9236365	12-Jan-2016
Invensas Corporation	Carrier-less silicon interposer	9237648	12-Jan-2016
Invensas Corporation	In-package fly-by signaling	9241420	19-Jan-2016
Invensas Corporation	Semiconductor die mount by conformal die coating	9252116	02-Feb-2016
Invensas Corporation	Package-on-package assembly with wire bond vias	9252122	02-Feb-2016
Invensas Corporation	Microelectronic assemblies with integrated circuits and interposers with cavities, and methods of manufacture	9252127	02-Feb-2016

Invensas Corporation	Compact semiconductor package and related methods	9257396	09-Feb-2016
Invensas Corporation	Multiple bond via arrays of different wire heights on a same substrate	9263394	16-Feb-2016
Invensas Corporation	Substrate-less stackable package with wire-bond interconnect	9263413	16-Feb-2016
Invensas Corporation	Stub minimization using duplicate sets of signal terminals in assemblies without wirebonds to package substrate	9281271	08-Mar-2016
Invensas Corporation	Embedded heat spreader for package with multiple microelectronic elements and face-down connection	9281295	08-Mar-2016
Invensas Corporation	Die stacking techniques in bga memory package for small footprint cpu and memory motherboard design	9281296	08-Mar-2016
Invensas Corporation	Stub minimization using duplicate sets of signal terminals in assemblies without wirebonds to package substrate	9287195	15-Mar-2016
Invensas Corporation	Memory module in a package	9287216	15-Mar-2016
Invensas Corporation	Co-support for xfd packaging	9293444	22-Mar-2016
Invensas Corporation	Inverted optical device	9293641	22-Mar-2016
Invensas Corporation	Retention optimized memory device using predictive data inversion	9299398	29-Mar-2016

Invensas Corporation	Thermal vias disposed in a substrate without a liner layer	9299572	29-Mar-2016
Invensas Corporation	Support mounted electrically interconnected die assembly	9305862	05-Apr-2016
Invensas Corporation	Surface modified tsv structure and methods thereof	9312175	12-Apr-2016
Invensas Corporation	Multi-die wirebond packages with elongated windows	9318467	19-Apr-2016
Invensas Corporation	Structures formed using monocrystalline silicon and/or other materials for optical and other applications	9323010	26-Apr-2016
Invensas Corporation	Interposers with circuit modules encapsulated by moldable material in a cavity, and methods of fabrication	9324626	26-Apr-2016
Invensas Corporation	Substrate-to-carrier adhesion without mechanical adhesion between abutting surfaces thereof	9330954	03-May-2016
Invensas Corporation	Localized sealing of interconnect structures in small gaps	9331043	03-May-2016
Invensas Corporation	Contact arrangements for stackable microelectronic package structures	9337170	10-May-2016

Invensas Corporation	Bga ballout partition techniques for simplified layout in motherboard with multiple power supply rail	9343398	17-May-2016
Invensas Corporation	Device and method for localized underfill	9349614	24-May-2016
Invensas Corporation	Reduced stress tsv and interposer structures	9349669	24-May-2016
Invensas Corporation	Method for package-on-package assembly with wire bonds to encapsulation surface	9349706	24-May-2016
Invensas Corporation	Contact arrangements for stackable microelectronic package structures with multiple ranks	9349707	24-May-2016
Invensas Corporation	Methods and structure for carrier-less thin wafer handling	9355905	31-May-2016
Invensas Corporation	Microelectronic package with consolidated chip structures	9355996	31-May-2016
Invensas Corporation	Integrated circuit assemblies with reinforcement frames, and methods of manufacture	9355997	31-May-2016
Invensas Corporation	Batch process for package-on-package	9356006	31-May-2016
Invensas Corporation	Tunable composite interposer	9362204	07-Jun-2016
Invensas Corporation	Method for preparing low cost substrates	9365947	14-Jun-2016

Invensas Corporation	Co-support circuit panel and microelectronic packages	9368477	14-Jun-2016
Invensas Corporation	Microelectronic package and method of manufacture thereof	9368478	14-Jun-2016
Invensas Corporation	Thermal vias disposed in a substrate proximate to a well thereof	9368479	14-Jun-2016
Invensas Corporation	Stub minimization for assemblies without wirebonds to package substrate	9373565	21-Jun-2016
Invensas Corporation	Polymer member based interconnect	9373585	21-Jun-2016
Invensas Corporation	Stub minimization for wirebond assemblies without windows	9377824	28-Jun-2016
Invensas Corporation	Method of thinning a wafer to provide a raised peripheral edge	9378985	28-Jun-2016
Invensas Corporation	Metal pvd-free conducting structures	9379008	28-Jun-2016
Invensas Corporation	Die stacks with one or more bond via arrays of wire bond and wires with one or more arrays of bump interconnects	9379074	28-Jun-2016
Invensas Corporation	Heat spreading substrate	9390998	12-Jul-2016
Invensas Corporation	Reconstituted wafer-level package dram	9391008	12-Jul-2016

Invensas Corporation	Microelectronic components with features wrapping around protrusions of conductive vias protruding from through-holes passing through substrates	9397038	19-Jul-2016
Invensas Corporation	Warpage reduction in structures with electrical circuitry	9397051	19-Jul-2016
Invensas Corporation	Reliable device assembly	9398700	19-Jul-2016
Invensas Corporation	Low cte interposer	9401288	26-Jul-2016
Invensas Corporation	Circuit assemblies with multiple interposer substrates, and methods of fabrication	9402312	26-Jul-2016
Invensas Corporation	Via in substrate with deposited layer	9412646	09-Aug-2016
Invensas Corporation	Wire bond support structure and microelectronic package including wire bonds therefrom	9412714	09-Aug-2016
Invensas Corporation	Making multilayer 3D capacitors using arrays of upstanding rods or ridges	9412806	09-Aug-2016
Invensas Corporation	Stacked die integrated circuit	9418924	16-Aug-2016
Invensas Corporation	Stub minimization for multi-die wirebond assemblies with parallel windows	9423824	23-Aug-2016
Invensas Corporation	Stackable microelectronic package structures	9425167	23-Aug-2016
Invensas Corporation	High strength through-substrate vias	9433093	30-Aug-2016

Invensas Corporation	Reversed build-up substrate for 2.5D	9437536	06-Sep-2016
Invensas Corporation	Conductive connections, structures with such connections, and methods of manufacture	9437566	06-Sep-2016
Invensas Corporation	Z-connection using electroless plating	9443837	13-Sep-2016
Invensas Corporation	Low cost interposer and method of fabrication	9455162	27-Sep-2016
Invensas Corporation	Bowl-shaped solder structure	9455237	27-Sep-2016
Invensas Corporation	Single package dual channel memory with co-support	9460758	04-Oct-2016
Invensas Corporation	Non-crystalline inorganic light emitting diode	9461196	04-Oct-2016
Invensas Corporation	MICROELECTRONIC ASSEMBLIES FORMED USING METAL SILICIDE, AND METHODS OF FABRICATION	9502347	22-Nov-2016
Invensas Corporation	Data inversion register technique for integrated circuit memory testing	RE44726	21-Jan-2014
Invensas Corporation; Sony Corporation	Fabrication method of wiring substrate for mounting semiconductor element and semiconductor device	6372620	16-Apr-2002
Phorus, Inc.	PLAYBACK SYNCHRONIZATION	9,237,324	12-Jan-16
Phorus, Inc.	RECEIVER	D709859	29-Jul-14
Phorus, Inc.	SPEAKER	D716254	28-Oct-14
Tessera Advanced Technologies, Inc.	Semiconductor device having offsetchips	5773896	30-Jun-1998

Tessera Advanced Technologies, Inc.	Bipolar transistor having an improved epitaxial base region	5789800	04-Aug-1998
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device	5828107	27-Oct-1998
Tessera Advanced Technologies, Inc.	Semiconductor device	5898206	27-Apr-1999
Tessera Advanced Technologies, Inc.	Bandgap reference circuit and method	5900772	04-May-1999
Tessera Advanced Technologies, Inc.	Semiconductor module comprising semiconductor packages	5903049	11-May-1999
Tessera Advanced Technologies, Inc.	Buffer circuit with wide gate input transistor	5914516	22-Jun-1999
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing the same	5930599	27-Jul-1999
Tessera Advanced Technologies, Inc.	Plastic encapsulated semiconductor device and method of manufacturing the same	5942794	24-Aug-1999
Tessera Advanced Technologies, Inc.	Bank arbitration for SDRAM memory control	5987574	16-Nov-1999
Tessera Advanced Technologies, Inc.	Field effect transistor array including refractory metal silicide interconnection layer	5994726	30-Nov-1999
Tessera Advanced Technologies, Inc.	Current steering variable gain amplifier with linearizer	5999053	07-Dec-1999
Tessera Advanced Technologies, Inc.	Variable gain amplifier using impedance network	5999056	07-Dec-1999
Tessera Advanced Technologies, Inc.	Semiconductor device mounting structure	6016013	18-Jan-2000

Tessera Advanced Technologies, Inc.	Semiconductor device and manufacture method thereof	6023095	08-Feb-2000
Tessera Advanced Technologies, Inc.	Method of manufacturing trench isolate semiconductor integrated circuit device	6027983	22-Feb-2000
Tessera Advanced Technologies, Inc.	High yield semiconductor device and method of fabricating the same	6031271	29-Feb-2000
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device for connecting semiconductor region and electrical wiring metal via titanium silicide layer and method of fabrication thereof	6031288	29-Feb-2000
Tessera Advanced Technologies, Inc.	Method for making multilayer wiring structure	6043145	28-Mar-2000
Tessera Advanced Technologies, Inc.	Level shift circuit	6043699	28-Mar-2000
Tessera Advanced Technologies, Inc.	Solid state image sensor and method for fabricating the same	6060732	09-May-2000

Tessera Advanced Technologies, Inc.	Projecting printing apparatus, projection printing method, mask pattern for estimating amplitude aberrations, method of estimating the quantity of amplitude aberration, and amplitude-aberration estimating filter	6061188	09-May-2000
Tessera Advanced Technologies, Inc.	Semiconductor device, lead frame, and lead bonding	6084310	04-Jul-2000
TESSERA ADVANCED TECHNOLOGIES, INC.	SEMICONDUCTOR MEMORY DEVICE	6101120	8-Aug-2000
Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor device with silicide layer without short circuit	6124190	26-Sep-2000
Tessera Advanced Technologies, Inc.	Plastic encapsulated semiconductor device and method of manufacturing the same	6130115	10-Oct-2000
Tessera Advanced Technologies, Inc.	Semiconductor memory device and a method for fabricating the same	6130449	10-Oct-2000
Tessera Advanced Technologies, Inc.	Semiconductor device having thin electrode layer adjacent gate insulator and method of manufacture	6144062	07-Nov-2000
Tessera Advanced Technologies, Inc.	Semiconductor device and method for manufacturing same	6150221	21-Nov-2000

Tessera Advanced Technologies, Inc.	Field effect transistor and a method for manufacturing a same	6172384	09-Jan-2001
TESSERA ADVANCED TECHNOLOGIES, INC.	POLISHING METHOD AND APPARATUS	6180020	30-Jan-2001
Tessera Advanced Technologies, Inc.	Semiconductor device with low permittivity interlayer insulating film and method of manufacturing the same	6187662	13-Feb-2001
Tessera Advanced Technologies, Inc.	Protective resistance element for a semiconductor device	6191454	20-Feb-2001
Tessera Advanced Technologies, Inc.	High yield semiconductor device and method of fabricating the same	6194261	27-Feb-2001
Tessera Advanced Technologies, Inc.	Transistor having main cell and sub-cells	6198117	06-Mar-2001
Tessera Advanced Technologies, Inc.	Semiconductor device	6198152	06-Mar-2001
Tessera Advanced Technologies, Inc.	Leadframe for use in manufacturing a resin-molded semiconductor device	6208020	27-Mar-2001
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device and process for manufacturing the same	6211003	03-Apr-2001
Tessera Advanced Technologies, Inc.	Semiconductor device and fabrication process thereof	6222269	24-Apr-2001
Tessera Advanced Technologies, Inc.	Semiconductor device and method for manufacturing thereof	6225657	01-May-2001

Tessera Advanced Technologies, Inc.	Generation of negative voltage using reference voltage	6229379	08-May-2001
Tessera Advanced Technologies, Inc.	Nonvolatile memory device with extended storage and high reliability through writing the same data into two memory cells	6256702	03-Jul-2001
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device for connecting semiconductor region and electrical wiring metal via titanium silicide layer and method of fabrication thereof	6268658	31-Jul-2001
Tessera Advanced Technologies, Inc.	Semiconductor device with high gettering capability to impurity present in semiconductor layer of soi substrate	6271541	07-Aug-2001
Tessera Advanced Technologies, Inc.	Semiconductor device and fabrication process thereof	6294833	25-Sep-2001
Tessera Advanced Technologies, Inc.	Semiconductor device with electrical isolation means	6299314	09-Oct-2001
Tessera Advanced Technologies, Inc.	DC gain enhancement for operational amplifiers	6300833	09-Oct-2001
Tessera Advanced Technologies, Inc.	Voltage comparator, operational amplifier and analog-to-digital conversion circuit employing the same	6304206	16-Oct-2001

Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device	6307236	23-Oct-2001
Tessera Advanced Technologies, Inc.	Package construction of semiconductor device	6317333	13-Nov-2001
Tessera Advanced Technologies, Inc.	Method for cleaning a substrate and cleaning solution	6319801	20-Nov-2001
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device and process for manufacturing the same	6329680	11-Dec-2001
Tessera Advanced Technologies, Inc.	Semiconductor device	6335565	01-Jan-2002
Tessera Advanced Technologies, Inc.	Resin-molded semiconductor device, method for manufacturing the same, and leadframe	6338984	15-Jan-2002
Tessera Advanced Technologies, Inc.	Method of manufacturing a semiconductor device	6340632	22-Jan-2002
Tessera Advanced Technologies, Inc.	Semiconductor device	6340793	22-Jan-2002
TESSERA ADVANCED TECHNOLOGIES, INC.	METHOD FOR PROCESSING SEMICONDUCTOR WAFER, FOR MAUFACTURING IC CARD, AND CARRIER	6342434	29-Jan-2002
Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor device, nonvolatile semiconductor memory device and method of manufacturing the same	6373096	16-Apr-2002
Tessera Advanced Technologies, Inc.	Semiconductor memory device and a method for fabricating the same	6376304	23-Apr-2002

Tessera Advanced Technologies, Inc.	Semiconductor device and fabrication method thereof	6380567	30-Apr-2002
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing the same	6383850	07-May-2002
Tessera Advanced Technologies, Inc.	Semiconductor memory device and method of manufacturing the same	6384450	07-May-2002
Tessera Advanced Technologies, Inc.	Process for manufacturing semiconductor integrated circuit device	6387744	14-May-2002
Tessera Advanced Technologies, Inc.	Solid state imaging device and manufacturing method thereof	6392261	21-May-2002
Tessera Advanced Technologies, Inc.	Semiconductor device	6392277	21-May-2002
Tessera Advanced Technologies, Inc.	Semiconductor memory device having a multi-layer interconnection structure suitable for merging with logic	6392942	21-May-2002
Tessera Advanced Technologies, Inc.	Semiconductor memory device and method of fabricating the same	6396098	28-May-2002
Tessera Advanced Technologies, Inc.	Wiring structure of semiconductor device	6396150	28-May-2002
Tessera Advanced Technologies, Inc.	Semiconductor device	6399460	04-Jun-2002
Tessera Advanced Technologies, Inc.	Semiconductor device	6399985	04-Jun-2002
Tessera Advanced Technologies, Inc.	Manufacturing method of semiconductor integrated circuit device having a capacitor	6403413	11-Jun-2002

Tessera Advanced Technologies, Inc.	Radio device including a receiver and method of adjusting one of the high-frequency amplifier stages of a receiver	6408167	18-Jun-2002
Tessera Advanced Technologies, Inc.	Vented semiconductor device package having separate substrate, strengthening ring and cap structures	6410981	25-Jun-2002
Tessera Advanced Technologies, Inc.	Tft with partially depleted body	6414353	02-Jul-2002
Tessera Advanced Technologies, Inc.	Method for manufacturing a field effect transistor	6417035	09-Jul-2002
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device and process for manufacture of the same	6420227	16-Jul-2002
Tessera Advanced Technologies, Inc.	Substrate-cleaning method and substrate-cleaning solution	6423148	23-Jul-2002
TESSERA ADVANCED TECHNOLOGIES, INC.	METHOD OF MANUFACTURING SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE	6432799	13-Aug-2002
Tessera Advanced Technologies, Inc.	Cleaning method for semiconductor substrate and cleaning solution	6432836	13-Aug-2002
Tessera Advanced Technologies, Inc.	Printed wiring board, IC card module using the same, and method for producing IC card module	6433285	13-Aug-2002

Tessera Advanced Technologies, Inc.	High speed and low parasitic capacitance semiconductor device and method for fabricating the same	6436781	20-Aug-2002
Tessera Advanced Technologies, Inc.	Semiconductor device	6437409	20-Aug-2002
Tessera Advanced Technologies, Inc.	Capacitive element	6437968	20-Aug-2002
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing the same	6441441	27-Aug-2002
Tessera Advanced Technologies, Inc.	Method of making a non-volatile memory and semiconductor device	6444554	03-Sep-2002
Tessera Advanced Technologies, Inc.	Substrate-cleaning method and substrate-cleaning solution	6444583	03-Sep-2002
Tessera Advanced Technologies, Inc.	Method of manufacturing a semiconductor memory device having a capacitor with improved dielectric layer	6448189	10-Sep-2002
Tessera Advanced Technologies, Inc.	Image sensor	6455909	24-Sep-2002
Tessera Advanced Technologies, Inc.	Method and system for selecting and using source operands in computer system instructions	6457118	24-Sep-2002
Tessera Advanced Technologies, Inc.	Non-volatile semiconductor memory and method of making same, and semiconductor device and method of making the device	6461916	08-Oct-2002
Tessera Advanced Technologies, Inc.	Semiconductor device and method for manufacturing the same	6462419	08-Oct-2002

Tessera Advanced Technologies, Inc.	Semiconductor device	6465832	15-Oct-2002
Tessera Advanced Technologies, Inc.	Solid state image sensor using an intermediate refractive index antireflection film and method for fabricating the same	6468826	22-Oct-2002
Tessera Advanced Technologies, Inc.	Semiconductor device with electrical isolation means	6468857	22-Oct-2002
Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor device	6468898	22-Oct-2002
Tessera Advanced Technologies, Inc.	Semiconductor device having a protective circuit	6469354	22-Oct-2002
Tessera Advanced Technologies, Inc.	Solid-state imaging device and method of its production	6472255	29-Oct-2002
Tessera Advanced Technologies, Inc.	Manufacturing method of semiconductor with a cleansing agent	6472287	29-Oct-2002
Tessera Advanced Technologies, Inc.	System and method for flexibly distributing timing signals	6472922	29-Oct-2002
TESSERA ADVANCED TECHNOLOGIES, INC.	POLISHING METHOD AND APPARATUS	6478977	12-Nov-2002
Tessera Advanced Technologies, Inc.	Fabrication process for a semiconductor device with damascene interconnect lines of the same level separated by insulators with different dielectric constants	6483193	19-Nov-2002

Tessera Advanced Technologies, Inc.	Semiconductor device having nonvolatile memory and method of manufacturing thereof	6489649	03-Dec-2002
Tessera Advanced Technologies, Inc.	Semiconductor device	6492719	10-Dec-2002
Tessera Advanced Technologies, Inc.	Semiconductor device and method for patterning the semiconductor device in which line patterns terminate at different lengths to prevent the occurrence of a short or break	6495870	17-Dec-2002
Tessera Advanced Technologies, Inc.	Method of forming a cmos structure having gate insulation films of different thicknesses	6500715	31-Dec-2002
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device and process for manufacturing the same	6501115	31-Dec-2002
Tessera Advanced Technologies, Inc.	Lead frame which includes a die pad, a support lead, and inner leads	6501156	31-Dec-2002
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacture thereof	6503788	07-Jan-2003

Tessera Advanced Technologies, Inc.	Method of fabricating a semiconductor integrated circuit device for connecting semiconductor region and electrical wiring metal via titanium silicide layer	6503803	07-Jan-2003
Tessera Advanced Technologies, Inc.	Semiconductor device and method for manufacturing thereof	6509224	21-Jan-2003
Tessera Advanced Technologies, Inc.	Semiconductor device having a plurality of stacked semiconductor chips on a wiring board	6509638	21-Jan-2003
Tessera Advanced Technologies, Inc.	Semiconductor device	6512176	28-Jan-2003
Tessera Advanced Technologies, Inc.	Semiconductor device and method for producing the same	6512298	28-Jan-2003
Tessera Advanced Technologies, Inc.	Probe card	6518779	11-Feb-2003
Tessera Advanced Technologies, Inc.	Driver timing and circuit technique for a low noise charge pump circuit	6518829	11-Feb-2003
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing the same	6521509	18-Feb-2003
Tessera Advanced Technologies, Inc.	Semiconductor device having thin electrode layer adjacent gate insulator and method of manufacture	6521943	18-Feb-2003
Tessera Advanced Technologies, Inc.	Voltage boost system having feedback control	6525614	25-Feb-2003

Tessera Advanced Technologies, Inc.	Method of manufacturing a semiconductor device	6528400	04-Mar-2003
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit and nonvolatile memory element	6528839	04-Mar-2003
Tessera Advanced Technologies, Inc.	Semiconductor device having an improved interlayer contact and manufacturing method thereof	6531737	11-Mar-2003
Tessera Advanced Technologies, Inc.	Method of forming a capacitor in a semiconductor integrated circuit device using a metal silicon nitride layer to protect an underlying metal silicide layer from oxidation during subsequent processing steps	6534375	18-Mar-2003
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device and method of manufacturing the same	6541333	01-Apr-2003
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit and nonvolatile memory element	6545311	08-Apr-2003
Tessera Advanced Technologies, Inc.	Sense amplifier for dynamic random access memory ("DRAM") devices having enhanced read and write speed	6552943	22-Apr-2003
Tessera Advanced Technologies, Inc.	Four current transistor temperature sensor and method	6554469	29-Apr-2003

Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing the same	6555464	29-Apr-2003
Tessera Advanced Technologies, Inc.	Semiconductor device and manufacturing method thereof	6563182	13-May-2003
TESSERA ADVANCED TECHNOLOGIES, INC.	METHODS OF PROCESSING SEMICONDUCTOR WAFER AND PRODUCING IC CARD, AND CARRIER	6573158	3-Jun-2003
Tessera Advanced Technologies, Inc.	Methods of processing semiconductor wafer, and producing ic card, and carrier	6589855	08-Jul-2003
Tessera Advanced Technologies, Inc.	Semiconductor device and manufacturing method thereof	6589863	08-Jul-2003
Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor device	6596585	22-Jul-2003
Tessera Advanced Technologies, Inc.	Semiconductor device with capacitor and method of manufacturing thereof	6603163	05-Aug-2003
Tessera Advanced Technologies, Inc.	Lead frame and method for fabricating resin-encapsulated semiconductor device using the same	6603194	05-Aug-2003
Tessera Advanced Technologies, Inc.	Re-synchronization method for a communication device	6603979	05-Aug-2003
Tessera Advanced Technologies, Inc.	Semiconductor device	6611012	26-Aug-2003

Tessera Advanced Technologies, Inc.	Semiconductor device including resistors isolated and equidistant from diffusion regions	6611042	26-Aug-2003
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit and nonvolatile memory element	6614684	02-Sep-2003
Tessera Advanced Technologies, Inc.	Etching method	6617244	09-Sep-2003
Tessera Advanced Technologies, Inc.	Semiconductor device and flat electrodes	6617688	09-Sep-2003
Tessera Advanced Technologies, Inc.	Semiconductor device and method for manufacturing the same	6624504	23-Sep-2003
Tessera Advanced Technologies, Inc.	Semiconductor device	6630731	07-Oct-2003
Tessera Advanced Technologies, Inc.	Manufacturing method of semiconductor integrated circuit device	6632744	14-Oct-2003
Tessera Advanced Technologies, Inc.	Semiconductor device	6664640	16-Dec-2003
Tessera Advanced Technologies, Inc.	Semiconductor package having two chips internally connected together with bump electrodes and both chips externally connected to a lead frame with bond wires	6677674	13-Jan-2004
Tessera Advanced Technologies, Inc.	Etching and cleaning methods and etching and cleaning apparatuses used therefor	6683007	27-Jan-2004
Tessera Advanced Technologies, Inc.	Analog-to-digital conversion circuit having increased conversion speed and high conversion accuracy	6683554	27-Jan-2004

Tessera Advanced Technologies, Inc.	Semiconductor device	6693347	17-Feb-2004
Tessera Advanced Technologies, Inc.	Stacked semiconductor chips attached to a wiring board	6707143	16-Mar-2004
Tessera Advanced Technologies, Inc.	Semiconductor photodetector	6718108	06-Apr-2004
Tessera Advanced Technologies, Inc.	Capacitor structure and a semiconductor device with a first metal layer, a second metal silicide layer formed over the first metal layer and a second metal layer formed over the second metal silicide layer	6720603	13-Apr-2004
Tessera Advanced Technologies, Inc.	Semiconductor device having thin electrode layer adjacent gate insulator and method of manufacture	6723625	20-Apr-2004
Tessera Advanced Technologies, Inc.	Semiconductor device	6727152	27-Apr-2004
Tessera Advanced Technologies, Inc.	Manufacturing method of semiconductor integrated circuit device, and semiconductor integrated circuit device	6750496	15-Jun-2004
Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor device	6764902	20-Jul-2004
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device and method of manufacturing the same	6770527	03-Aug-2004

Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor device, nonvolatile semiconductor memory device and method of manufacturing the same	6770533	03-Aug-2004
Tessera Advanced Technologies, Inc.	Method for producing a semiconductor device	6770547	03-Aug-2004
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing the same	6774020	10-Aug-2004
Tessera Advanced Technologies, Inc.	Stacked semiconductor chips on a wiring board	6777796	17-Aug-2004
Tessera Advanced Technologies, Inc.	Semiconductor device including a diffusion layer formed between electrode portions	6784557	31-Aug-2004
Tessera Advanced Technologies, Inc.	Semiconductor device	6785165	31-Aug-2004
Tessera Advanced Technologies, Inc.	Semiconductor device having offset insulation film formed on insulation film, and method of manufacturing the same	6806537	19-Oct-2004

Tessera Advanced Technologies, Inc.	Manufacturing method of semiconductor integrated circuit including simultaneous formation of via-hole reaching metal wiring and concave groove in interlayer film and semiconductor integrated circuit manufactured with the manufacturing method	6809037	26-Oct-2004
Tessera Advanced Technologies, Inc.	Field-effect type semiconductor device for power amplifier	6815707	09-Nov-2004
Tessera Advanced Technologies, Inc.	Semiconductor memory element, semiconductor device and control method thereof	6815763	09-Nov-2004
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device having bump electrodes for signal or power only, and testing pads that are not coupled to bump electrodes	6831294	14-Dec-2004
Tessera Advanced Technologies, Inc.	Lead frame and method for fabricating resin-encapsulated semiconductor device using the same	6835600	28-Dec-2004
Tessera Advanced Technologies, Inc.	Semiconductor device and method for producing the same	6852616	08-Feb-2005
Tessera Advanced Technologies, Inc.	Semiconductor device including a capacitance	6858918	22-Feb-2005

Tessera Advanced Technologies, Inc.	Resin molded type semiconductor device and a method of manufacturing the same	6861735	01-Mar-2005
Tessera Advanced Technologies, Inc.	Semiconductor device	6862220	01-Mar-2005
Tessera Advanced Technologies, Inc.	Mobile radio set of a cellular network for the transmission of speech and/or data, and a method therefor	6862431	01-Mar-2005
Tessera Advanced Technologies, Inc.	Semiconductor device and method and apparatus for manufacturing the same	6879042	12-Apr-2005
Tessera Advanced Technologies, Inc.	Method of manufacturing a semiconductor device having plural semiconductor chips, wherein electrodes of the semiconductor chips are electrically connected together via wiring substrates of the semiconductor chips	6900074	31-May-2005
Tessera Advanced Technologies, Inc.	Resin molded semiconductor device on a lead frame and method of manufacturing the same	6900524	31-May-2005
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit and nonvolatile memory element	6906954	14-Jun-2005
Tessera Advanced Technologies, Inc.	Resin encapsulation semiconductor device utilizing grooved leads and die pad	6909168	21-Jun-2005
Tessera Advanced Technologies, Inc.	Wide band antenna	6914561	05-Jul-2005

Tessera Advanced Technologies, Inc.	Semiconductor device, its manufacturing method and mounting structure of semiconductor device	6930388	16-Aug-2005
Tessera Advanced Technologies, Inc.	Semiconductor device including a diffusion layer	6954001	11-Oct-2005
Tessera Advanced Technologies, Inc.	Semiconductor device with folded film substrate and display device using the same	6956288	18-Oct-2005
Tessera Advanced Technologies, Inc.	Etching and cleaning methods and etching and cleaning apparatuses used therefor	6964724	15-Nov-2005
Tessera Advanced Technologies, Inc.	Semiconductor integrated device and method of fabrication thereof	6969671	29-Nov-2005
Tessera Advanced Technologies, Inc.	Nonvolatile semiconductor memory device	6972997	06-Dec-2005
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit having bonding optional function	6976200	13-Dec-2005
Tessera Advanced Technologies, Inc.	Semiconductor device and method for fabricating the same	6992396	31-Jan-2006
Tessera Advanced Technologies, Inc.	Manufacturing method of semiconductor integrated circuit device	7001712	21-Feb-2006
Tessera Advanced Technologies, Inc.	Solid state image pick-up device	7030919	18-Apr-2006
Tessera Advanced Technologies, Inc.	Method For Fabricating A Semiconductor Device Having Salicide	7033932	25-Apr-2006

Tessera Advanced Technologies, Inc.	Leadframe, plastic-encapsulated semiconductor device, and method for fabricating the same	7042071	09-May-2006
Tessera Advanced Technologies, Inc.	Semiconductor device including an interconnect having copper as a main component	7042095	09-May-2006
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit and nonvolatile memory element	7042764	09-May-2006
Tessera Advanced Technologies, Inc.	Field-effect type semiconductor device for power amplifier	7045412	16-May-2006
Tessera Advanced Technologies, Inc.	Semiconductor memory element, semiconductor device and control method thereof	7045853	16-May-2006
Tessera Advanced Technologies, Inc.	Semiconductor device and manufacturing method thereof	7045898	16-May-2006
Tessera Advanced Technologies, Inc.	Method of manufacturing a dual gate semiconductor device with a poly-metal electrode	7049665	23-May-2006
Tessera Advanced Technologies, Inc.	System for managing data objects	7051291	23-May-2006
Tessera Advanced Technologies, Inc.	Semiconductor device and method for producing the same	7057283	06-Jun-2006
Tessera Advanced Technologies, Inc.	Semiconductor device and its manufacturing method	7064005	20-Jun-2006
Tessera Advanced Technologies, Inc.	Electrostatic discharge device	7067884	27-Jun-2006

Tessera Advanced Technologies, Inc.	Methods Of Fabricating Mim Capacitors In Semiconductor Devices	7071054	04-Jul-2006
Tessera Advanced Technologies, Inc.	Methods Of Fabricating Mim Capacitors Of Semiconductor Devices	7071057	04-Jul-2006
Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor device	7075139	11-Jul-2006
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit having bonding optional function	7076705	11-Jul-2006
Tessera Advanced Technologies, Inc.	Semiconductor device	7078818	18-Jul-2006
Tessera Advanced Technologies, Inc.	Semiconductor device and a method of manufacturing the same	7087474	08-Aug-2006
Tessera Advanced Technologies, Inc.	Constant voltage power supply circuit	7091709	15-Aug-2006
Tessera Advanced Technologies, Inc.	Semiconductor device and method for patterning	7105873	12-Sep-2006
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing same	7109553	19-Sep-2006
Tessera Advanced Technologies, Inc.	Semiconductor device including n-channel fets and p-channel fets with improved drain current characteristics	7109568	19-Sep-2006
Tessera Advanced Technologies, Inc.	Semiconductor device including a capacitance	7112835	26-Sep-2006
Tessera Advanced Technologies, Inc.	Wide band antenna	7116277	03-Oct-2006
Tessera Advanced Technologies, Inc.	Semiconductor interconnect structure	7119441	10-Oct-2006

Tessera Advanced Technologies, Inc.	Master slice semiconductor integrated circuit	7120891	10-Oct-2006
Tessera Advanced Technologies, Inc.	Semiconductor device and method manufacturing the same	7122900	17-Oct-2006
Tessera Advanced Technologies, Inc.	Wide band antenna	7123195	17-Oct-2006
Tessera Advanced Technologies, Inc.	Lead frame, resin-encapsulated semiconductor device, and method of producing the same	7126209	24-Oct-2006
Tessera Advanced Technologies, Inc.	Method of designing semiconductor device, semiconductor device and recording medium	7129543	31-Oct-2006
Tessera Advanced Technologies, Inc.	Nonvolatile semiconductor memory device	7130223	31-Oct-2006
Tessera Advanced Technologies, Inc.	Leadframe, plastic-encapsulated semiconductor device, and method for fabricating the same	7132315	07-Nov-2006
Tessera Advanced Technologies, Inc.	Semiconductor device and method for manufacturing the same	7138706	21-Nov-2006
Tessera Advanced Technologies, Inc.	Semiconductor device	7138722	21-Nov-2006
Tessera Advanced Technologies, Inc.	Non-volatile semiconductor memory and method of making same, and semiconductor device and method of making device	7141475	28-Nov-2006

Tessera Advanced Technologies, Inc.	Non-volatile semiconductor memory and method of making same, and semiconductor device and method of making device	7179711	20-Feb-2007
Tessera Advanced Technologies, Inc.	Metal Interconnection Lines Of Semiconductor Devices And Methods Of Forming The Same	7186639	06-Mar-2007
Tessera Advanced Technologies, Inc.	Semiconductor device and method for fabricating the same	7192804	20-Mar-2007
Tessera Advanced Technologies, Inc.	Semiconductor memory device and access method and memory control system for same	7193923	20-Mar-2007
Tessera Advanced Technologies, Inc.	Non-volatile semiconductor memory and method of making same, and semiconductor device and method of making device	7195976	27-Mar-2007
Tessera Advanced Technologies, Inc.	Ccd image sensor	7196303	27-Mar-2007
Tessera Advanced Technologies, Inc.	Semiconductor device having a multi-chip stacked structure and reduced thickness	7196407	27-Mar-2007
Tessera Advanced Technologies, Inc.	Wide band antenna	7202820	10-Apr-2007
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit, and electrostatic withstand voltage test method and apparatus therefor	7205783	17-Apr-2007
Tessera Advanced Technologies, Inc.	Method Of Fabricating Flash Memory Device	7214581	08-May-2007

Tessera Advanced Technologies, Inc.	Estimating eb/nt in a cdma system using power control bits	7228146	05-Jun-2007
Tessera Advanced Technologies, Inc.	Method of producing a semiconductor device having a multi-layered insulation film	7229910	12-Jun-2007
Tessera Advanced Technologies, Inc.	Semiconductor device and manufacturing method for the same	7229921	12-Jun-2007
Tessera Advanced Technologies, Inc.	Stacked chip semiconductor device and method for manufacturing the same	7239021	03-Jul-2007
Tessera Advanced Technologies, Inc.	Method Of Fabricating Semiconductor Device Using Selective Epitaxial Growth	7247533	24-Jul-2007
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device having particular testing pad arrangement	7247879	24-Jul-2007
Tessera Advanced Technologies, Inc.	Nonvolatile Semiconductor Memory Devices And Methods Of Manufacturing The Same	7247917	24-Jul-2007
Tessera Advanced Technologies, Inc.	Soi substrate and method for manufacturing the same	7262486	28-Aug-2007
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit and nonvolatile memory element	7289361	30-Oct-2007
Tessera Advanced Technologies, Inc.	Wide band antenna	7295163	13-Nov-2007

Tessera Advanced Technologies, Inc.	Non-volatile semiconductor memory and method of making same, and semiconductor device and method of making device	7304345	04-Dec-2007
Tessera Advanced Technologies, Inc.	Copper Line Of Semiconductor Device And Method For Forming The Same	7314831	01-Jan-2008
Tessera Advanced Technologies, Inc.	Methods For Forming Copper Interconnect Of Semiconductor Devices	7326645	05-Feb-2008
Tessera Advanced Technologies, Inc.	Resin-encapsulation semiconductor device and method for fabricating the same	7338838	04-Mar-2008
Tessera Advanced Technologies, Inc.	Method For Forming Via Hole And Trench For Dual Damascene Interconnection	7344992	18-Mar-2008
Tessera Advanced Technologies, Inc.	Semiconductor device with semiconductor layer having various thickness	7358569	15-Apr-2008
Tessera Advanced Technologies, Inc.	Rf Semiconductor Devices And Methods For Fabricating The Same	7361583	22-Apr-2008
Tessera Advanced Technologies, Inc.	Semiconductor device and a method of manufacturing the same	7384834	10-Jun-2008
Tessera Advanced Technologies, Inc.	Semiconductor memory device and signal processing system	7406649	29-Jul-2008

Tessera Advanced Technologies, Inc.	Method of forming a cmos structure having gate insulation films of different thicknesses	7427791	23-Sep-2008
Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor integrated circuit	7439118	21-Oct-2008
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit and nonvolatile memory element	7463517	09-Dec-2008
Tessera Advanced Technologies, Inc.	Flash Memory And Method For Manufacturing The Same	7465629	16-Dec-2008
Tessera Advanced Technologies, Inc.	Tungsten Plug Structure Of Semiconductor Device And Method For Forming The Same	7482692	27-Jan-2009
Tessera Advanced Technologies, Inc.	Communication apparatus, method and programs	7502350	10-Mar-2009
Tessera Advanced Technologies, Inc.	Metal Interconnection Lines Of Semiconductor Devices And Methods Of Forming The Same	7514793	07-Apr-2009
Tessera Advanced Technologies, Inc.	Stacked chip semiconductor device and method for manufacturing the same	7521288	21-Apr-2009
Tessera Advanced Technologies, Inc.	Method For Fabricating A Semiconductor Device	7521771	21-Apr-2009

Tessera Advanced Technologies, Inc.	Non-volatile semiconductor memory and method of making same, and semiconductor device and method of making device	7528036	05-May-2009
Tessera Advanced Technologies, Inc.	Time base adjustment in a data processing device	7535385	19-May-2009
Tessera Advanced Technologies, Inc.	Resin molded type semiconductor device and a method of manufacturing the same	7538416	26-May-2009
Tessera Advanced Technologies, Inc.	Semiconductor storage device	7542355	02-Jun-2009
Tessera Advanced Technologies, Inc.	A method of acquiring a received spread spectrum signal	7545853	09-Jun-2009
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device and manufacture thereof	7550763	23-Jun-2009
Tessera Advanced Technologies, Inc.	Computer system	7571282	04-Aug-2009
Tessera Advanced Technologies, Inc.	Semiconductor Device And Method For Manufacturing The Same	7575980	18-Aug-2009
Tessera Advanced Technologies, Inc.	System for managing data objects	7581195	25-Aug-2009
Tessera Advanced Technologies, Inc.	Semiconductor device and method for patterning	7582921	01-Sep-2009
Tessera Advanced Technologies, Inc.	Semiconductor device and manufacturing method thereof	7595222	29-Sep-2009
Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor integrated circuit	7601579	13-Oct-2009

Tessera Advanced Technologies, Inc.	Semiconductor device and semiconductor wafer having a multi-layered insulation film	7602048	13-Oct-2009
Tessera Advanced Technologies, Inc.	Band Gap Reference Voltage Generation Circuit	7602236	13-Oct-2009
Tessera Advanced Technologies, Inc.	Semiconductor device including a capacitance	7608879	27-Oct-2009
Tessera Advanced Technologies, Inc.	Wire Pad Of Semiconductor Device	7642659	05-Jan-2010
Tessera Advanced Technologies, Inc.	Receiver for a multi-carrier signal	7650129	19-Jan-2010
Tessera Advanced Technologies, Inc.	Semiconductor device and semiconductor wafer and a method for manufacturing the same	7663244	16-Feb-2010
Tessera Advanced Technologies, Inc.	Semiconductor device, semiconductor wafer, and methods of producing same device and wafer	7674721	09-Mar-2010
Tessera Advanced Technologies, Inc.	Substrate treating method and method of manufacturing semiconductor apparatus	7691672	06-Apr-2010
Tessera Advanced Technologies, Inc.	Non-volatile semiconductor memory and method of making same, and semiconductor device and method of making device	7692234	06-Apr-2010
Tessera Advanced Technologies, Inc.	Method of manufacturing semiconductor device	7718524	18-May-2010

Tessera Advanced Technologies, Inc.	Semiconductor device having recessed connector portions	7728429	01-Jun-2010
Tessera Advanced Technologies, Inc.	Semiconductor device and semiconductor module employing thereof	7768133	03-Aug-2010
Tessera Advanced Technologies, Inc.	Method of forming a cmos structure having gate insulation films of different thicknesses	7781814	24-Aug-2010
Tessera Advanced Technologies, Inc.	Method and arrangement for setting the transmission of a mobile communication device	7809393	05-Oct-2010
Tessera Advanced Technologies, Inc.	Semiconductor device and semiconductor wafer and a method for manufacturing the same	7812457	12-Oct-2010
Tessera Advanced Technologies, Inc.	Semiconductor device, semiconductor wafer, and methods of producing the same device and wafer	7816280	19-Oct-2010
Tessera Advanced Technologies, Inc.	Semiconductor device and method of fabrication	7829995	09-Nov-2010
Tessera Advanced Technologies, Inc.	Semiconductor Device And Method For Manufacturing The Same	7839006	23-Nov-2010
Tessera Advanced Technologies, Inc.	Method Of Forming Dummy Pattern	7849436	07-Dec-2010

Tessera Advanced Technologies, Inc.	Semiconductor device, method for manufacturing the same, and semiconductor device mounting structure	7851904	14-Dec-2010
Tessera Advanced Technologies, Inc.	Etching and cleaning methods and etching and cleaning apparatuses used therefor	7862658	04-Jan-2011
Tessera Advanced Technologies, Inc.	Device For Protecting Semiconductor Ic	7869175	11-Jan-2011
Tessera Advanced Technologies, Inc.	Semiconductor device and semiconductor module employing thereof	7898073	01-Mar-2011
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device and manufacture thereof	7910922	22-Mar-2011
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device with a fuse circuit	7910960	22-Mar-2011
Tessera Advanced Technologies, Inc.	Differential Pre-Emphasis Driver	7940075	10-May-2011
Tessera Advanced Technologies, Inc.	Start-Up Circuit For Reference Voltage Generation Circuit	7944195	17-May-2011
Tessera Advanced Technologies, Inc.	Semiconductor device and method manufacturing the same	7947596	24-May-2011
Tessera Advanced Technologies, Inc.	Flash Memory And Method For Manufacturing The Same	7952133	31-May-2011

Tessera Advanced Technologies, Inc.	Resin-sealed semiconductor device, leadframe with die pads, and manufacturing method for leadframe with die pads	7952177	31-May-2011
Tessera Advanced Technologies, Inc.	Carrier frame for electronic components and production method for electronic components	7960828	14-Jun-2011
Tessera Advanced Technologies, Inc.	Semiconductor device providing a first electrical conductor and a second electrical conductor in one through hole and method for manufacturing the same	7964972	21-Jun-2011
Tessera Advanced Technologies, Inc.	Boost Operational Amplifier	7978010	12-Jul-2011
Tessera Advanced Technologies, Inc.	Start-Up Circuit For Generating Bandgap Reference Voltage	8008966	30-Aug-2011
Tessera Advanced Technologies, Inc.	Radio communication apparatus	8019314	13-Sep-2011
Tessera Advanced Technologies, Inc.	Semiconductor device and method for manufacturing same	8035230	11-Oct-2011
Tessera Advanced Technologies, Inc.	Lead frame, semiconductor device, method of manufacturing the lead frame, and method of manufacturing the semiconductor device	8039932	18-Oct-2011

Tessera Advanced Technologies, Inc.	Low-Dropout Voltage Regulator With Level Limiter Limiting Level Of Output Voltage When Level Of Load Current Changes And Method Of Operating The Same	8040118	18-Oct-2011
Tessera Advanced Technologies, Inc.	Semiconductor device and method of fabrication	8072057	06-Dec-2011
Tessera Advanced Technologies, Inc.	Semiconductor device	8097962	17-Jan-2012
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing the same	8106518	31-Jan-2012
Tessera Advanced Technologies, Inc.	Manufacturing process of semiconductor device and semiconductor device	8110900	07-Feb-2012
Tessera Advanced Technologies, Inc.	Method For Placing Dummy Patterns In A Semiconductor Device Layout	8117582	14-Feb-2012
Tessera Advanced Technologies, Inc.	Information delivery system, method, information processing apparatus, and method	8150906	03-Apr-2012
Tessera Advanced Technologies, Inc.	Semiconductor memory system and signal processing system	8166371	24-Apr-2012
Tessera Advanced Technologies, Inc.	Method for providing and obtaining content	8175976	08-May-2012
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing the same	8178977	15-May-2012

Tessera Advanced Technologies, Inc.	Resin encapsulated semiconductor device and method for manufacturing the same	8193091	05-Jun-2012
Tessera Advanced Technologies, Inc.	Solid state image pick-up device for imaging an object placed thereon	8233063	31-Jul-2012
Tessera Advanced Technologies, Inc.	Multilayer semiconductor device and electronic equipment	8269335	18-Sep-2012
Tessera Advanced Technologies, Inc.	Wiring board, semiconductor device and method for manufacturing the same	8283775	09-Oct-2012
Tessera Advanced Technologies, Inc.	Semiconductor device	8330266	11-Dec-2012
Tessera Advanced Technologies, Inc.	System for managing data objects	8352882	08-Jan-2013
Tessera Advanced Technologies, Inc.	Semiconductor device providing a first electrical conductor and a second electrical conductor in one through hole and method for manufacturing the same	8390098	05-Mar-2013
Tessera Advanced Technologies, Inc.	Through-substrate via and redistribution layer with metal paste	8395267	12-Mar-2013
Tessera Advanced Technologies, Inc.	Semiconductor device and multilayer semiconductor device	8405221	26-Mar-2013
Tessera Advanced Technologies, Inc.	Solid state imaging device for imaging an object placed thereon	8416330	09-Apr-2013

Tessera Advanced Technologies, Inc.	Etching and cleaning methods and etching and cleaning apparatuses used therefor	8420549	16-Apr-2013
Tessera Advanced Technologies, Inc.	Temperature Independent Reference Current Generator Using Positive And Negative Temperature Coefficient Currents	8441246	14-May-2013
Tessera Advanced Technologies, Inc.	Semiconductor integrated circuit device	8629481	14-Jan-2014
Tessera Advanced Technologies, Inc.	Method of forming a cmos structure having gate insulation films of different thicknesses	8674419	18-Mar-2014
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing the same	8816506	26-Aug-2014
Tessera Advanced Technologies, Inc.	Information delivery system for generating a data stream with a server system based on a content file received from a client device	8856217	07-Oct-2014
Tessera Advanced Technologies, Inc.	Semiconductor device	8907468	09-Dec-2014
Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing same	9076700	07-Jul-2015
Tessera Advanced Technologies, Inc.	Method of forming a cmos structure having gate insulation films of different thicknesses	9111909	18-Aug-2015

Tessera Advanced Technologies, Inc.	Semiconductor device and method of manufacturing same	9318418	19-Apr-2016
Tessera Advanced Technologies, Inc.	System for managing data objects	9377927	28-Jun-2016
Tessera Advanced Technologies, Inc.	Information delivery system for generating a data stream with a server system based on a content file received from a client device	9451052	20-Sep-2016
Tessera Advanced Technologies, Inc.	Semiconductor memory device	RE45698	29-Sep-2015
Tessera, Inc.	Curved lead configurations	5859472	12-Jan-1999
Tessera, Inc.	System and method for forming a grid array device package employing electromagnetic shielding	5866943	02-Feb-1999
TESSERA, INC.	MULTIPLE PART COMPLIANT INTERFACE FOR PACKAGING OF A SEMICONDUCTOR CHIP AND METHOD THEREFOR	5915170	22-Jun-1999
Tessera, Inc.	Bonding lead structure with enhanced encapsulation	5937276	10-Aug-1999
Tessera, Inc.	Lidless socket and method of making same	5951305	14-Sep-1999
Tessera, Inc.	Microelectronic mounting with multiple lead deformation using restraining straps	5976913	02-Nov-1999
Tessera, Inc.	Low profile socket for microelectronic components and method for making the same	5983492	16-Nov-1999

TESSERA, INC.	MICROELECTRONIC ASSEMBLY FABRICATION WITH TERMINAL FORMATION FROM A CONDUCTIVE LAYER	5989936	23-Nov-1999
Tessera, Inc.	Process of manufacturing compliant wirebond packages	5989939	23-Nov-1999
TESSERA, INC.	METHOD OF MAKING CHIP MOUNTINGS AND ASSEMBLIES	5994222	30-Nov-1999
Tessera, Inc.	Semiconductor chip package with dual layer terminal and lead structure	5994781	30-Nov-1999
Tessera, Inc.	Microelectronic component with rigid interposer	6002168	14-Dec-1999
Tessera, Inc.	Flexible contact post and post socket and associated methods therefor	6007349	28-Dec-1999
Tessera, Inc.	Integrated circuit package having bond fingers with alternate bonding areas	6008532	28-Dec-1999
Tessera, Inc.	Grid array device package including advanced heat transfer mechanism	6008536	28-Dec-1999
TESSERA, INC.	METHOD OF FORMING COMPLIANT MICROELECTRONIC MOUNTING DEVICE	6012224	11-Jan-2000
Tessera, Inc.	Bondable compliant pads for packaging of a semiconductor chip and method therefor	6030856	29-Feb-2000

TESSERA, INC.	VACUUM DISPENSE METHOD FOR DISPENSING AN ENCAPSULANT AND MACHINE THEREFOR	6046076	4-Apr-2000
Tessera, Inc.	Universal unit strip/carrier frame assembly and methods	6049972	18-Apr-2000
Tessera, Inc.	Method of making a compliant multichip package	6054337	25-Apr-2000
TESSERA, INC.	LEAD FORMATION USING GRIDS	6063648	16-May-2000
Tessera, Inc.	Methods of encapsulating a semiconductor chip using a settable encapsulant	6080605	27-Jun-2000
Tessera, Inc.	Semiconductor package assemblies with moisture vents	6080932	27-Jun-2000
Tessera, Inc.	Fabrication of components by coining	6083837	04-Jul-2000
Tessera, Inc.	Flexible connectors for microelectronic elements	6086386	11-Jul-2000
Tessera, Inc.	Compliant wirebond packages having wire loop	6107682	22-Aug-2000
Tessera, Inc.	Semiconductor package with translator for connection to an external substrate	6114763	05-Sep-2000
TESSERA, INC.	FLEXIBLE LEAD STRUCTURES AND METHODS OF MAKING SAME	6117694	12-Sep-2000
TESSERA, INC.	VACUUM DISPENSE APPARATUS FOR DISPENSING AN ENCAPSULANT	6126428	3-Oct-2000
Tessera, Inc.	Lidless socket and method of making same	6126455	03-Oct-2000

Tessera, Inc.	Packaged microelectronic elements with enhanced thermal conduction	6127724	03-Oct-2000
Tessera, Inc.	Method of encapsulating a microelectronic assembly utilizing a barrier	6130116	10-Oct-2000
Tessera, Inc.	Semiconductor chip package having chip-to-carrier mechanical/electrical connection formed via solid state diffusion	6130476	10-Oct-2000
Tessera, Inc.	Microelectronic connector with planar elastomer sockets	6133072	17-Oct-2000
Tessera, Inc.	Compliant multichip package	6147401	14-Nov-2000
Tessera, Inc.	Spacer plate solder ball placement fixture and methods therefor	6162661	19-Dec-2000
TESSERA, INC.	SEMICONDUCTOR CHIP ASSEMBLY	6169328	2-Jan-2001
Tessera, Inc.	Multilayer structure with interlocking protrusions	6188028	13-Feb-2001
Tessera, Inc.	Methods of making anisotropic conductive elements for use in microelectronic packaging	6190509	20-Feb-2001
Tessera, Inc.	Lamination machine and method to laminate a coverlay to a microelectronic package	6197665	06-Mar-2001
Tessera, Inc.	Low insertion force connector for microelectronic elements	6200143	13-Mar-2001

TESSERA, INC.	MICROELECTRONIC CONNECTIONS WITH LIQUID CONDUCTIVE ELEMENTS	6202298	20-Mar-2001
Tessera, Inc.	Method of assembling a semiconductor chip package	6204091	20-Mar-2001
Tessera, Inc.	Microelectronic mounting with multiple lead deformation using restraining straps	6208024	27-Mar-2001
Tessera, Inc.	Microelectronic component with rigid interposer	6208025	27-Mar-2001
Tessera, Inc.	Apparatus for electrically testing bare printed circuits	6211690	03-Apr-2001
Tessera, Inc.	Enhancements in framed sheet processing	6217972	17-Apr-2001
Tessera, Inc.	Microelectronic components with frangible lead sections	6218213	17-Apr-2001
Tessera, Inc.	Methods of encapsulating a semiconductor chip using a settable encapsulant	6218215	17-Apr-2001
Tessera, Inc.	Fabrication of deformable leads of microelectronic elements	6221750	24-Apr-2001
TESSERA, INC.	FRAMED SHEET PROCESSING	6228685	8-May-2001
TESSERA, INC.	METHOD OF FABRICATING A MICROELECTRONIC ASSEMBLY USING SHEETS WITH GAPS TO DEFINE LEAD REGIONS	6228686	8-May-2001

Tessera, Inc.	Low profile socket for microelectronic components and method for making the same	6229100	08-May-2001
TESSERA, INC.	METHOD OF MANUFACTURING A PLURALITY OF SEMICONDUCTOR PACKAGES AND THE RESULTING SEMICONDUCTOR PACKAGE STRUCTURES	6232152	15-May-2001
TESSERA, INC.	MICROELECTRONIC LEAD STRUCTURES WITH PLURAL CONDUCTORS	6239384	29-May-2001
TESSERA, INC.	ELECTRICAL CONNECTION WITH INWARDLY DEFORMABLE CONTACTS	6247228	19-Jun-2001
Tessera, Inc.	Metal-jacketed lead manufacturing process using resist layers	6248656	19-Jun-2001
Tessera, Inc.	Solder ball placement fixtures and methods	6253992	03-Jul-2001
Tessera, Inc.	Layered lead structures	6255723	03-Jul-2001
Tessera, Inc.	Encapsulant for microelectronic devices	6255738	03-Jul-2001
TESSERA, INC.	COMPONENTS WITH RELEASABLE LEADS AND METHODS OF MAKING RELEASABLE LEADS	6261863	17-Jul-2001
Tessera, Inc.	A method for making a connection component for a semiconductor chip package	6266872	31-Jul-2001

TESSERA, INC.	METHODS OF MAKING MICROELECTRONIC COMPONENTS HAVING ELECTROPHORETICALLY DEPOSITED LAYERS	6266874	31-Jul-2001
Tessera, Inc.	Manufacture of semiconductor connection components with frangible lead sections	6274822	14-Aug-2001
TESSERA, INC.	METHOD OF MAKING COMPLIANT MICROELECTRONIC ASSEMBLIES	6284563	4-Sep-2001
Tessera, Inc.	Transferable resilient element for packaging of a semiconductor chip and method therefor	6294040	25-Sep-2001
Tessera, Inc.	Method for creating a die shrink insensitive semiconductor package and component therefor	6300231	09-Oct-2001
Tessera, Inc.	Methods of making compliant interfaces and microelectronic packages using same	6300254	09-Oct-2001
Tessera, Inc.	Microelectronic assemblies with composite conductive elements	6303408	16-Oct-2001
Tessera, Inc.	Connection component and method of making same	6306752	23-Oct-2001
TESSERA, INC.	MICROELECTRONIC ASSEMBLY FABRICATION WITH TERMINAL FORMATION FROM A CONDUCTIVE LAYER	6307260	23-Oct-2001

Tessera, Inc.	Microelectronic components with frangible lead sections	6309910	30-Oct-2001
Tessera, Inc.	Semiconductor chip package with expander ring and method of making same	6309915	30-Oct-2001
Tessera, Inc.	Compliant multichip package	6313528	06-Nov-2001
Tessera, Inc.	Methods for creating wear resistant contact edges	6317974	20-Nov-2001
Tessera, Inc.	Method for fabricating microelectronic assemblies	6324754	04-Dec-2001
Tessera, Inc.	Encapsulation of microelectronic assemblies	6329224	11-Dec-2001
Tessera, Inc.	Components with conductive solder mask layers	6329605	11-Dec-2001
Tessera, Inc.	Process to produce a high temperature interconnection	6330967	18-Dec-2001
Tessera, Inc.	Etched glass solder bump transfer for flip chip integrated circuit devices	6332569	25-Dec-2001
Tessera, Inc.	Peelable lead structure and method of manufacture	6333207	25-Dec-2001
Tessera, Inc.	Selective removal of dielectric materials and plating process using same	6334942	01-Jan-2002
Tessera, Inc.	Microelectronic packages with solder interconnections	6335222	01-Jan-2002
Tessera, Inc.	Fixture for attaching a conformal chip carrier to a flip chip	6337509	08-Jan-2002

Tessera, Inc.	Enhancements in framed sheet processing	6338982	15-Jan-2002
Tessera, Inc.	Method of making connection component	6357112	19-Mar-2002
Tessera, Inc.	Semiconductor package assemblies with moisture vents and methods of making same	6358780	19-Mar-2002
TESSERA, INC.	METHOD OF MANUFACTURING A PLURALITY OF SEMICONDUCTOR PACKAGES AND THE RESULTING] SEMICONDUCTOR PACKAGE STRUCTURES	6359335	19-Mar-2002
TESSERA, INC.	MICROELECTRONIC UNIT FORMING METHODS AND MATERIALS	6361959	26-Mar-2002
Tessera, Inc.	Microelectronic mounting with multiple lead deformation using restraining straps	6362520	26-Mar-2002
Tessera, Inc.	Chip with internal signal routing in external element	6365975	02-Apr-2002
TESSERA, INC.	COMPLIANT MICROELECTRONIC MOUNTING DEVICE	6370032	9-Apr-2002
Tessera, Inc.	Bondable compliant pads for packaging of a semiconductor chip and method therefor	6373141	16-Apr-2002
Tessera, Inc.	Method of making a connection to a microelectronic element	6374487	23-Apr-2002
Tessera, Inc.	Conductive leads with non-wettable surfaces	6378758	30-Apr-2002

Tessera, Inc.	Off-center solder ball attach and methods therefor	6380060	30-Apr-2002
Tessera, Inc.	Lead formation using grids	6384475	07-May-2002
Tessera, Inc.	Compliant semiconductor chip package with fan-out leads and method of making same	6388340	14-May-2002
Tessera, Inc.	Compliant package with conductive elastomeric posts	6417029	09-Jul-2002
Tessera, Inc.	Components with releasable leads	6423907	23-Jul-2002
Tessera, Inc.	Method of making a connection to a microelectronic element	6428328	06-Aug-2002
TESSERA, INC.	MULTI-LAYER SUBSTRATES AND FABRICATION PROCESSES	6429112	6-Aug-2002
TESSERA, INC.	MICROELECTRONIC CONNECTIONS WITH LIQUID CONDUCTIVE ELEMENTS	6437240	20-Aug-2002
Tessera, Inc.	Fan-out translator for a semiconductor package	6441488	27-Aug-2002
Tessera, Inc.	Methods of encapsulating a semiconductor chip using a settable encapsulant	6458628	01-Oct-2002
TESSERA, INC.	METHOD OF FABRICATING SEMICONDUCTOR CHIP ASSEMBLIES	6460245	8-Oct-2002
Tessera, Inc.	Microelectronic assemblies having solder-wettable pads and conductive elements	6465747	15-Oct-2002
TESSERA, INC.	COMPLIANT MICROELECTRONIC ASSEMBLIES	6465878	15-Oct-2002

Tessera, Inc.	Compliant semiconductor package with anisotropic conductive material interconnects and methods therefor	6468830	22-Oct-2002
Tessera, Inc.	Method for creating a die shrink insensitive semiconductor package and component therefor	6489674	03-Dec-2002
Tessera, Inc.	Forming microelectronic connection components by electrophoretic deposition	6492201	10-Dec-2002
Tessera, Inc.	Microelectronic joining processes with bonding material application	6492251	10-Dec-2002
Tessera, Inc.	Lidless socket and method of making same	6493932	17-Dec-2002
Tessera, Inc.	Methods of making anisotropic conductive elements for use in microelectronic packaging	6518091	11-Feb-2003
Tessera, Inc.	Method of manufacturing connection components using a plasma patterned mask	6518160	11-Feb-2003
Tessera, Inc.	Method of assembling a semiconductor chip package	6518662	11-Feb-2003
TESSERA, INC.	METHOD FOR MAKING A SEMICONDUCTOR CHIP PACKAGE	6521480	18-Feb-2003

Tessera, Inc.	Methods of making bondable contacts and a tool for making such contacts	6527163	04-Mar-2003
Tessera, Inc.	Methods of making microelectronic assemblies using bonding stage and bonding stage therefor	6534392	18-Mar-2003
TESSERA, INC.	COMPONENTS WITH RELEASABLE LEADS AND METHODS OF MAKING RELEASABLE LEADS	6541845	1-Apr-2003
Tessera, Inc.	Microelectronic connector with planar elastomer sockets	6541867	01-Apr-2003
Tessera, Inc.	Encapsulation of microelectronic assemblies	6541874	01-Apr-2003
Tessera, Inc.	Microelectronic joining processes with temporary securement	6543131	08-Apr-2003
Tessera, Inc.	Method of making components with releasable leads	6557253	06-May-2003
Tessera, Inc.	Microelectronic packaging methods and components	6572781	03-Jun-2003
Tessera, Inc.	Graded metallic leads for connection to microelectronic elements	6573459	03-Jun-2003
Tessera, Inc.	Microelectronics component with rigid interposer	6573609	03-Jun-2003
Tessera, Inc.	Semiconductor packages having light sensitive chips	6583444	24-Jun-2003
Tessera, Inc.	Encapsulation of microelectronic assemblies	6602740	05-Aug-2003

Tessera, Inc.	Method of making a microelectronic assembly with multiple lead deformation using differential thermal expansion/contraction	6627478	30-Sep-2003
Tessera, Inc.	Components and methods with nested leads	6632733	14-Oct-2003
Tessera, Inc.	Compliant package with conductive elastomeric posts	6635514	21-Oct-2003
Tessera, Inc.	Microelectronic joining processes	6651321	25-Nov-2003
Tessera, Inc.	Microelectronic assembly formation with lead displacement	6657286	02-Dec-2003
Tessera, Inc.	Semiconductor chip package with interconnect structure	6664621	16-Dec-2003
Tessera, Inc.	Thermal and mechanical attachment of a heatspreader to a flip-chip integrated circuit structure using underfill	6673708	06-Jan-2004
Tessera, Inc.	Vapor phase connection techniques	6675469	13-Jan-2004
Tessera, Inc.	Method of making a microelectronic package including a component having conductive elements on a top side and a bottom side thereof	6678952	20-Jan-2004
Tessera, Inc.	Transferable resilient element for packaging of a semiconductor chip and method therefor	6686015	03-Feb-2004

Tessera, Inc.	Apparatus for processing flexible tape for microelectronic assemblies	6687980	10-Feb-2004
Tessera, Inc.	Stacked microelectronic assembly and method therefor	6699730	02-Mar-2004
Tessera, Inc.	Electrical connection with inwardly deformable contacts	6700072	02-Mar-2004
Tessera, Inc.	Electrical connection with inwardly deformable contact	6706973	16-Mar-2004
Tessera, Inc.	Low cost and compliant microelectronic packages for high i/o and fine pitch	6707149	16-Mar-2004
Tessera, Inc.	Spacer plate solder ball placement fixture and methods therefor	6709469	23-Mar-2004
Tessera, Inc.	Packaged microelectronic elements with enhanced thermal conduction	6709895	23-Mar-2004
Tessera, Inc.	Methods of making microelectronic assemblies having conductive elastomeric posts	6709899	23-Mar-2004
Tessera, Inc.	Methods of making microelectronic assemblies using compressed resilient layer	6716671	06-Apr-2004
Tessera, Inc.	Active trace rerouting	6748576	08-Jun-2004
Tessera, Inc.	Joining semiconductor units with bonding material	6750539	15-Jun-2004

Tessera, Inc.	Selective removal of dielectric materials and plating process using same	6758984	06-Jul-2004
Tessera, Inc.	Method of making components with releasable leads	6763579	20-Jul-2004
Tessera, Inc.	Microelectronic adaptors, assemblies and methods	6765288	20-Jul-2004
Tessera, Inc.	Compliant semiconductor package with anisotropic conductive material interconnects and methods therefor	6791169	14-Sep-2004
Tessera, Inc.	Methods of making anisotropic conductive elements for use in microelectronic packaging	6800537	05-Oct-2004
Tessera, Inc.	Methods of bonding microelectronic elements	6808958	26-Oct-2004
Tessera, Inc.	Method for forming a multi-layer circuit assembly	6820330	23-Nov-2004
Tessera, Inc.	Method of assembling a semiconductor chip package	6821815	23-Nov-2004
Tessera, Inc.	Microelectronic connection components utilizing conductive cores and polymeric coatings	6822320	23-Nov-2004
Tessera, Inc.	Connection components with anisotropic conductive material interconnection	6825552	30-Nov-2004
TESSERA, INC.	FLEXIBLE LEAD STRUCTURES AND METHODS OF MAKING SAME	6828668	7-Dec-2004

TESSERA, INC.	MICROELECTRONIC CONNECTIONS WITH LIQUID CONDUCTIVE ELEMENTS	6846700	25-Jan-2005
TESSERA, INC.	MICROELECTRONIC PACKAGE HAVING A COMPLIANT LAYER WITH BUMPED PROTRUSIONS	6847101	25-Jan-2005
TESSERA, INC.	MICROELECTRONIC ASSEMBLIES HAVING COMPLIANT LAYERS	6847107	25-Jan-2005
TESSERA, INC.	MICROELECTRONIC PACKAGES HAVING DEFORMED BONDED LEADS AND METHODS THEREFOR	6848173	1-Feb-2005
Tessera, Inc.	Microelectronic assemblies with composite conductive elements	6849953	01-Feb-2005
Tessera, Inc.	High-frequency chip packages	6856007	15-Feb-2005
TESSERA, INC.	METHODS FOR MANUFACTURING RESISTORS USING A SACRIFICIAL LAYER	6856235	15-Feb-2005
Tessera, Inc.	Method of making a microelectronic assembly	6867065	15-Mar-2005
Tessera, Inc.	Off-center solder ball attach assembly	6870267	22-Mar-2005
Tessera, Inc.	Methods of making microelectronic packages including electrically and/or thermally conductive element	6873039	29-Mar-2005
TESSERA, INC.	STACKED MICROELECTRONIC ASSEMBLIES AND METHODS OF MAKING SAME	6885106	26-Apr-2005
Tessera, Inc.	Semiconductor package having light sensitive chips	6888168	03-May-2005
Tessera, Inc.	Stacked packages	6897565	24-May-2005

Tessera, Inc.	Microelectronic elements with deformable leads	6906422	14-Jun-2005
Tessera, Inc.	Stacked packages	6913949	05-Jul-2005
Tessera, Inc.	Semiconductor chip package with interconnect structure	6921713	26-Jul-2005
Tessera, Inc.	Low cost and compliant microelectronic packages for high i/o and fine pitch	6927095	09-Aug-2005
Tessera, Inc.	Microelectronic assembly formation with releasable leads	6939735	06-Sep-2005
Tessera, Inc.	Assemblies having stacked semiconductor chips and methods of making same	6940158	06-Sep-2005
Tessera, Inc.	Assemblies having stacked semiconductor chips and methods of making same	6952047	04-Oct-2005
Tessera, Inc.	Methods of making microelectronic packages	6959489	01-Nov-2005
TESSERA, INC.	MULTI-LAYER SUBSTRATES AND FABRICATION PROCESSES	6965158	15-Nov-2005
Tessera, Inc.	Structure and method of making an enhanced surface area capacitor	6972473	06-Dec-2005
Tessera, Inc.	Compliant package with conductive elastomeric posts	6972495	06-Dec-2005
Tessera, Inc.	Stacked packages	6977440	20-Dec-2005
TESSERA, INC.	A METHOD FOR MAKING A MICROELECTRONIC INTERPOSER	6978538	27-Dec-2005

Tessera, Inc.	Microelectronic assemblies incorporating inductors	7012323	14-Mar-2006
Tessera, Inc.	Method for forming a multi-layer circuit assembly	7036222	02-May-2006
Tessera, Inc.	Resistor process	7049929	23-May-2006
Tessera, Inc.	Microelectronic packages with self-aligning features	7053485	30-May-2006
TESSERA, INC.	STACKED MICROELECTRONIC ASSEMBLIES WITH CENTRAL CONTACTS	7061121	13-Jun-2006
Tessera, Inc.	Components, methods and assemblies for multi-chip packages	7061122	13-Jun-2006
Tessera, Inc.	Connection component with peelable leads	7067742	27-Jun-2006
Tessera, Inc.	Assemblies having stacked semiconductor chips and methods of making same	7071547	04-Jul-2006
Tessera, Inc.	Microelectronic packages with elongated solder interconnections	7078819	18-Jul-2006
Tessera, Inc.	Method of making bondable leads using positive photoresist and structures made therefrom	7087510	08-Aug-2006
TESSERA, INC.	METHODS FOR MANUFACTURING RESISTORS USING A SACRIFICIAL LAYER	7091820	15-Aug-2006
Tessera, Inc.	Semiconductor package having light sensitive chips	7095054	22-Aug-2006

Tessera, Inc.	Ball assignment schemes for integrated circuit packages	7095107	22-Aug-2006
Tessera, Inc.	Microelectronic assemblies having low profile connections	7098074	29-Aug-2006
TESSERA, INC.	MICROELECTRONIC ASSEMBLIES HAVING COMPLIANT LAYERS	7112879	26-Sep-2006
Tessera, Inc.	Structure and method of making capped chips including vertical interconnects having stud bumps engaged to surfaces of said caps	7129576	31-Oct-2006
Tessera, Inc.	Stacked microelectronic assemblies	7149095	12-Dec-2006
Tessera, Inc.	Phased antenna array module	7151502	19-Dec-2006
Tessera, Inc.	Manufacture of microelectronic fold packages	7157309	02-Jan-2007
TESSERA, INC.	METHODS FOR MANUFACTURING RESISTORS USING A SACRIFICIAL LAYER	7165316	23-Jan-2007
Tessera, Inc.	Capacitor having low resistance electrode including a thin silicon layer	7170736	30-Jan-2007
Tessera, Inc.	Microelectronic packages and methods therefor	7176043	13-Feb-2007
Tessera, Inc.	High frequency chip packages with connecting elements	7176506	13-Feb-2007
Tessera, Inc.	Stacked packages and systems incorporating the same	7183643	27-Feb-2007

Tessera, Inc.	Structure and method of making a capacitor having low equivalent series resistance	7187536	06-Mar-2007
Tessera, Inc.	Method of making a microelectronic package	7188413	13-Mar-2007
Tessera, Inc.	Micro lead frame packages and methods of manufacturing the same	7202112	10-Apr-2007
Tessera, Inc.	Assemblies for temporarily connecting microelectronic elements for testing and methods therefor	7205659	17-Apr-2007
Tessera, Inc.	Substrate having a plurality of i/o routing arrangements for a microelectronic device	7208820	24-Apr-2007
Tessera, Inc.	Back-face and edge interconnects for lidded package	7224056	29-May-2007
Tessera, Inc.	Method of making assemblies having stacked semiconductor chips	7229850	12-Jun-2007
Tessera, Inc.	Methods of making microelectronic packages including folded substrates	7246431	24-Jul-2007
Tessera, Inc.	Connection structures for microelectronic devices and methods for forming such structures	7262368	28-Aug-2007
Tessera, Inc.	Microelectronic connection components having bondable wires	7268304	11-Sep-2007

Tessera, Inc.	High-frequency chip packages	7268426	11-Sep-2007
Tessera, Inc.	METHOD OF FABRICATING SEMICONDUCTOR CHIP ASSEMBLIES	7272888	25-Sep-2007
Tessera, Inc.	Methods of making microelectronic packages with conductive elastomeric posts	7276400	02-Oct-2007
Tessera, Inc.	Method of making assemblies having stacked semiconductor chips	7288433	30-Oct-2007
Tessera, Inc.	Components, methods and assemblies for stacked packages	7294928	13-Nov-2007
Tessera, Inc.	Structure and method of making sealed capped chips	7298030	20-Nov-2007
Tessera, Inc.	Microelectronic assemblies with springs	7304376	04-Dec-2007
Tessera, Inc.	Method for making a microelectronic package using pre-patterned, reusable mold and method for making the mold	7309447	18-Dec-2007
Tessera, Inc.	Micro lead frame packages and methods of manufacturing the same	7309910	18-Dec-2007
Tessera, Inc.	Microelectronic package having stacked semiconductor devices and a process for its fabrication	7317249	08-Jan-2008
Tessera, Inc.	Selective removal of dielectric materials and plating process using same	7332068	19-Feb-2008

Tessera, Inc.	Packaged chip having features for improved signal transmission on the package	7332799	19-Feb-2008
Tessera, Inc.	Microelectronic assembly having array including passive elements and interconnects	7335995	26-Feb-2008
Tessera, Inc.	Structure and method of forming capped chips	7351641	01-Apr-2008
Tessera, Inc.	Rigid flex interconnect via	7356923	15-Apr-2008
Tessera, Inc.	Multi-sheet conductive substrates for microelectronic devices and methods for forming such substrates	7361979	22-Apr-2008
Tessera, Inc.	Image sensor package and fabrication method	7368695	06-May-2008
Tessera, Inc.	Solid state lighting device	7397068	08-Jul-2008
Tessera, Inc.	MICROELECTRONIC ASSEMBLIES HAVING COMPLIANT LAYERS	7408260	5-Aug-2008
Tessera, Inc.	Methods of making microelectronic packages	7413926	19-Aug-2008
Tessera, Inc.	Components with conductive solder mask layers	7427423	23-Sep-2008
Tessera, Inc.	Liquid lens with piezoelectric voltage converter	7443597	28-Oct-2008
Tessera, Inc.	Wire bonded wafer level cavity package	7449779	11-Nov-2008
Tessera, Inc.	Compliant terminal mountings with vented spaces and methods	7453139	18-Nov-2008

Tessera, Inc.	Microelectronic packages and methods therefor	7453157	18-Nov-2008
Tessera, Inc.	METHOD OF FABRICATING SEMICONDUCTOR CHIP ASSEMBLIES	7454834	25-Nov-2008
Tessera, Inc.	Manufacture of mountable capped chips	7462932	09-Dec-2008
Tessera, Inc.	Formation of circuitry with modification of feature height	7462936	09-Dec-2008
Tessera, Inc.	Microelectronic package optionally having differing cover and device thermal expansivities	7485956	03-Feb-2009
Tessera, Inc.	Assembly including vertical and horizontal joined circuit panels	7489524	10-Feb-2009
Tessera, Inc.	Components with posts and pads	7495179	24-Feb-2009
Tessera, Inc.	Microelectronic component with foam-metal posts	7510401	31-Mar-2009
Tessera, Inc.	Compliant terminal mountings with vented spaces and methods	7521276	21-Apr-2009
Tessera, Inc.	Packaged systems with mram	7521785	21-Apr-2009
Tessera, Inc.	Microelectronic elements with compliant terminal mountings and methods for making the same	7534652	19-May-2009
Tessera, Inc.	Stack microelectronic assemblies	7545029	09-Jun-2009
Tessera, Inc.	Microelectronic packages and methods therefor	7554206	30-Jun-2009

Tessera, Inc.	Image sensor employing a plurality of photodetector arrays and/or rear-illuminated architecture	7566853	28-Jul-2009
Tessera, Inc.	High-frequency chip packages	7566955	28-Jul-2009
Tessera, Inc.	Method of forming a wall structure in a microelectronic assembly	7569424	04-Aug-2009
Tessera, Inc.	High q cavity resonators for microelectronics	7583165	01-Sep-2009
Tessera, Inc.	Stacked packages and microelectronic assemblies incorporating the same	7589409	15-Sep-2009
Tessera, Inc.	Pin referenced image sensor to reduce tilt in a camera module	7593636	22-Sep-2009
Tessera, Inc.	Stacked chip assembly with encapsulant layer	7605479	20-Oct-2009
Tessera, Inc.	Microelectronic component with photo-imageable substrate	7632708	15-Dec-2009
Tessera, Inc.	Microelectronic package	7638868	29-Dec-2009
Tessera, Inc.	Substrate for a flexible microelectronic assembly and a method of fabricating thereof	7659617	09-Feb-2010
Tessera, Inc.	Enabling uniformity of stacking process through bumpers	7683468	23-Mar-2010
Tessera, Inc.	Layered metal structure for interconnect element	7696439	13-Apr-2010

Tessera, Inc.	Microelectronic package with thermal access	7709297	04-May-2010
Tessera, Inc.	Micro pin grid array with pin motion isolation	7709968	04-May-2010
Tessera, Inc.	Microelectronic packages and methods therefor	7719121	18-May-2010
Tessera, Inc.	Semiconductor chip packages and assemblies with chip carrier units	7732912	08-Jun-2010
Tessera, Inc.	Chip assembly including package element and integrated circuit chip	7737513	15-Jun-2010
Tessera, Inc.	Microelectronic packages and methods therefor	7745943	29-Jun-2010
Tessera, Inc.	Microelectronic assemblies having compliancy and methods therefor	7749886	06-Jul-2010
Tessera, Inc.	Manufacture of mountable capped chips	7754537	13-Jul-2010
Tessera, Inc.	Microelectronic packages fabricated at the wafer level and methods therefor	7759166	20-Jul-2010
Tessera, Inc.	Substrate for a microelectronic package and method of fabricating thereof	7759782	20-Jul-2010
Tessera, Inc.	Stackable microelectronic device carriers, stacked device carriers and methods of making the same	7763983	27-Jul-2010

Tessera, Inc.	Microelectronic package element and method of fabricating thereof	7767497	03-Aug-2010
Tessera, Inc.	Microelectronic package having interconnected redistribution paths	7768117	03-Aug-2010
Tessera, Inc.	Compact lens turret assembly	7768574	03-Aug-2010
Tessera, Inc.	Polyceramic-coated tool for applying a flowable composition	7779776	24-Aug-2010
Tessera, Inc.	Packaged semiconductor chips	7791199	07-Sep-2010
Tessera, Inc.	Methods for forming connection structures for microelectronic devices	7793414	14-Sep-2010
Tessera, Inc.	Formation of circuitry with modification of feature height	7816251	19-Oct-2010
Tessera, Inc.	Edge connect wafer level stacking	7829438	09-Nov-2010
Tessera, Inc.	Low loss rf transmission lines having a reference conductor with a recess portion opposite a signal conductor	7855623	21-Dec-2010
Tessera, Inc.	Wire bonded wafer level cavity package	7858445	28-Dec-2010
Tessera, Inc.	MICROELECTRONIC ASSEMBLIES HAVING COMPLIANT LAYERS	7872344	18-Jan-2011
Tessera, Inc.	Reconstituted wafer level stacking	7901989	08-Mar-2011
Tessera, Inc.	Multilayer wiring element having pin interface	7911805	22-Mar-2011

Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH IMPEDANCE CONTROLLED WIREBOND AND CONDUCTIVE REFERENCE ELEMENT	7923851	12-Apr-2011
Tessera, Inc.	Components, methods and assemblies for stacked packages	7935569	03-May-2011
Tessera, Inc.	Microelectronic packages and methods therefor	7939934	10-May-2011
Tessera, Inc.	Stacked packages	7952195	31-May-2011
Tessera, Inc.	Stacking packages with alignment elements	7964947	21-Jun-2011
Tessera, Inc.	System and method for increasing the number of io-s on a ball grid package by wire bond stacking of same size packages through apertures	7989940	02-Aug-2011
Tessera, Inc.	Microelectronic packages having cavities for receiving microelectronic elements	7994622	09-Aug-2011
Tessera, Inc.	Package stacking through rotation	7994644	09-Aug-2011
Tessera, Inc.	Microelectronic assemblies having compliancy	7999379	16-Aug-2011
Tessera, Inc.	Microelectronic packages and methods therefor	7999397	16-Aug-2011
Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH JOINED BOND ELEMENTS HAVING LOWERED INDUCTANCE	8008785	30-Aug-2011
Tessera, Inc.	Edge connect wafer level stacking	8022527	20-Sep-2011

Tessera, Inc.	Stacked microelectronic packages	8026611	27-Sep-2011
Tessera, Inc.	Microelectronic package with thermal access	8034665	11-Oct-2011
Tessera, Inc.	Small chips with fan-out leads	8039363	18-Oct-2011
Tessera, Inc.	Microelectronic connection component	8039959	18-Oct-2011
Tessera, Inc.	Wafer level stacked packages with individual chip selection	8043895	25-Oct-2011
Tessera, Inc.	Components with posts and pads	8046912	01-Nov-2011
Tessera, Inc.	Method of forming a wafer level package	8053281	08-Nov-2011
Tessera, Inc.	Microelectronic packages and methods therefor	8058101	15-Nov-2011
Tessera, Inc.	Microelectronic assemblies having very fine pitch stacking	8067267	29-Nov-2011
Tessera, Inc.	Substrate for a microelectronic package and method of fabricating thereof	8071424	06-Dec-2011
Tessera, Inc.	Off-chip vias in stacked chips	8076788	13-Dec-2011
Tessera, Inc.	Microelectronic packages and methods therefor	8093697	10-Jan-2012
Tessera, Inc.	Microelectronic assemblies having compliancy and methods therefor	8115308	14-Feb-2012
Tessera, Inc.	Wafer level chip package and a method of fabricating thereof	8133808	13-Mar-2012

Tessera, Inc.	Sequential fabrication of vertical conductive interconnects in capped chips	8143095	27-Mar-2012
Tessera, Inc.	Wearable ultra-thin miniaturized mobile communications	8155663	10-Apr-2012
Tessera, Inc.	Micro pin grid array with wiping action	8207604	26-Jun-2012
Tessera, Inc.	METAL CAN IMPEDANCE CONTROL STRUCTURE	8222725	17-Jul-2012
Tessera, Inc.	Microelectronic packages fabricated at the wafer level and methods therefor	8241959	14-Aug-2012
Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH IMPEDANCE CONTROLLED WIREBOND AND REFERENCE WIREBOND	8253259	28-Aug-2012
Tessera, Inc.	Collective and synergistic mram shields	8269319	18-Sep-2012
Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH IMPEDANCE CONTROLLED WIREBOND AND CONDUCTIVE REFERENCE ELEMENT	8269357	18-Sep-2012
Tessera, Inc.	Package stacking through rotation	8294284	23-Oct-2012
Tessera, Inc.	Microelectronic package	8299626	30-Oct-2012
Tessera, Inc.	Flip-chip, face-up and face-down wirebond combination package	8304881	06-Nov-2012

Tessera, Inc.	Microelectronic packages and methods therefor	8329581	11-Dec-2012
Tessera, Inc.	Microelectronic packages with dual or multiple-etched flip-chip connectors	8330272	11-Dec-2012
Tessera, Inc.	MICROELECTRONIC ASSEMBLIES HAVING COMPLIANT LAYERS	8338925	25-Dec-2012
Tessera, Inc.	Multiple die face-down stacking for two or more die	8338963	25-Dec-2012
Tessera, Inc.	Stacked packages with bridging traces	8349654	08-Jan-2013
Tessera, Inc.	Enhanced stacked microelectronic assemblies with central contacts and vias connected to the central contacts	8378478	19-Feb-2013
Tessera, Inc.	Wafer level chip package and a method of fabricating thereof	8378487	19-Feb-2013
Tessera, Inc.	Impact sensing switch	8387531	05-Mar-2013
Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH JOINED BOND ELEMENTS HAVING LOWERED INDUCTANCE	8410618	2-Apr-2013
Tessera, Inc.	Edge connect wafer level stacking	8426957	23-Apr-2013
Tessera, Inc.	Edge connect wafer level stacking	8431435	30-Apr-2013
Tessera, Inc.	Conductive pads defined by embedded traces	8432045	30-Apr-2013
Tessera, Inc.	FLIP-CHIP, FACE-UP AND FACE-DOWN WIREBOND COMBINATION PACKAGE	8436458	7-May-2013

Tessera, Inc.	Reconstituted wafer stack packaging with after applied pad extensions	8461672	11-Jun-2013
Tessera, Inc.	Edge connect wafer level stacking	8461673	11-Jun-2013
Tessera, Inc.	Stacked microelectronic assemblies having vias extending through bond pads	8466542	18-Jun-2013
Tessera, Inc.	ENHANCED STACKED MICROELECTRONIC ASSEMBLIES WITH CENTRAL CONTACTS AND IMPROVED GROUND OR POWER DISTRIBUTION	8466564	18-Jun-2013
Tessera, Inc.	Off-chip vias in stacked chips	8476774	02-Jul-2013
Tessera, Inc.	Stackable molded microelectronic packages	8482111	09-Jul-2013
Tessera, Inc.	Simultaneous wafer bonding and interconnect joining	8486758	16-Jul-2013
Tessera, Inc.	Microelectronic package with stacked microelectronic elements and method for manufacture thereof	8487421	16-Jul-2013
Tessera, Inc.	High density three-dimensional integrated capacitors	8502340	06-Aug-2013
Tessera, Inc.	De-skewed multi-die packages	8502390	06-Aug-2013
Tessera, Inc.	Method of fabricating an interconnection element having conductive posts	8505199	13-Aug-2013
Tessera, Inc.	Ultra-thin near-hermetic package based on rainier	8508036	13-Aug-2013

Tessera, Inc.	Dual wafer spin coating	8512491	20-Aug-2013
Tessera, Inc.	Edge connect wafer level stacking with leads extending along edges	8513789	20-Aug-2013
Tessera, Inc.	Stacked assembly including plurality of stacked microelectronic elements	8513794	20-Aug-2013
Tessera, Inc.	Flip-chip qfn structure using etched lead frame	8525309	03-Sep-2013
Tessera, Inc.	Area array quad flat no-lead (qfn) package	8525312	03-Sep-2013
Tessera, Inc.	Stacked packaging improvements	8525314	03-Sep-2013
Tessera, Inc.	Chip with sintered connections to package	8525338	03-Sep-2013
Tessera, Inc.	Stacked packaging improvements	8531020	10-Sep-2013
Tessera, Inc.	Micro pin grid array with pin motion isolation	8531039	10-Sep-2013
Tessera, Inc.	Microelectronic packages having cavities for receiving microelectronic elements	8541873	24-Sep-2013
Tessera, Inc.	Stack packages using reconstituted wafers	8551815	08-Oct-2013
Tessera, Inc.	Enhanced stacked microelectronic assemblies with central contacts and improved thermal characteristics	8553420	08-Oct-2013
Tessera, Inc.	Flip chip interconnection with double post	8558379	15-Oct-2013
Tessera, Inc.	Methods of making compliant semiconductor chip packages	8558386	15-Oct-2013

Tessera, Inc.	Packaged semiconductor chips with array	8569876	29-Oct-2013
Tessera, Inc.	Multiple die in a face down package	8569884	29-Oct-2013
Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH IMPEDANCE CONTROLLED WIREBOND AND CONDUCTIVE REFERENCE ELEMENT	8575766	5-Nov-2013
Tessera, Inc.	Microelectronic packages with nanoparticle joining	8580607	12-Nov-2013
Tessera, Inc.	Tsop with impedance control	8581377	12-Nov-2013
Tessera, Inc.	Stacked microelectronic assembly with tsvs formed in stages with plural active chips	8587126	19-Nov-2013
Tessera, Inc.	Active chip on carrier or laminated chip having microelectronic element embedded therein	8598695	03-Dec-2013
Tessera, Inc.	Method of making a connection component with posts and pads	8604348	10-Dec-2013
Tessera, Inc.	Reliable packaging and interconnect structures	8609540	17-Dec-2013
Tessera, Inc.	Multi-function and shielded 3d interconnects	8610259	17-Dec-2013
Tessera, Inc.	Compliant interconnects in wafers	8610264	17-Dec-2013
Tessera, Inc.	Packaged microelectronic elements having blind vias for heat dissipation	8618647	31-Dec-2013

Tessera, Inc.	Package-on-package assembly with wire bonds to encapsulation surface	8618659	31-Dec-2013
Tessera, Inc.	Microelectronic package with terminals on dielectric mass	8623706	07-Jan-2014
Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH IMPEDANCE CONTROLLED WIREBOND AND REFERENCE WIREBOND	8624407	7-Jan-2014
Tessera, Inc.	Wearable ultra-thin miniaturized mobile communications	8630658	14-Jan-2014
Tessera, Inc.	Stacked chip-on-board module with edge connector	8633576	21-Jan-2014
Tessera, Inc.	Stacked microelectronic assembly having interposer connecting active chips	8637968	28-Jan-2014
Tessera, Inc.	Microelectronic package with terminals on dielectric mass	8637991	28-Jan-2014
Tessera, Inc.	Fine pitch microcontacts and method for forming thereof	8641913	04-Feb-2014
Tessera, Inc.	Void-free wafer bonding using channels	8652935	18-Feb-2014
Tessera, Inc.	Packaged semiconductor chips with array	8653644	18-Feb-2014
Tessera, Inc.	Microelectronic package with terminals on dielectric mass	8659164	25-Feb-2014

Tessera, Inc.	Wafer level edge stacking	8680662	25-Mar-2014
Tessera, Inc.	Chip assembly having via interconnects joined by plating	8685793	01-Apr-2014
Tessera, Inc.	Substrate for a microelectronic package and method of fabricating thereof	8686551	01-Apr-2014
Tessera, Inc.	Stacked chip assembly having vertical vias	8686565	01-Apr-2014
Tessera, Inc.	Reliable wire structure and method	8692118	08-Apr-2014
Tessera, Inc.	Power boosting circuit for semiconductor packaging	8692611	08-Apr-2014
Tessera, Inc.	No flow underfill	8697492	15-Apr-2014
Tessera, Inc.	Non-lithographic formation of three-dimensional conductive elements	8697569	15-Apr-2014
Tessera, Inc.	Dram security erase	8699263	15-Apr-2014
Tessera, Inc.	Packaged semiconductor chips	8704347	22-Apr-2014
Tessera, Inc.	Stacked microelectronic assemblies	8704351	22-Apr-2014
Tessera, Inc.	Simultaneous wafer bonding and interconnect joining	8709913	29-Apr-2014
Tessera, Inc.	Interposer having molded low cte dielectric	8709933	29-Apr-2014
Tessera, Inc.	Low-stress tsv design using conductive particles	8723049	13-May-2014
Tessera, Inc.	Microelectronic packages with dual or multiple-etched flip-chip connectors	8723318	13-May-2014

Tessera, Inc.	Microelectronic packages and methods therefor	8728865	20-May-2014
Tessera, Inc.	Systems and methods for producing flat surfaces in interconnect structures	8728934	20-May-2014
Tessera, Inc.	Stacked microelectronic assembly with tsvs formed in stages and carrier above chip	8736066	27-May-2014
Tessera, Inc.	System and method for testing fuse blow reliability for integrated circuits	8736278	27-May-2014
Tessera, Inc.	High density three-dimensional integrated capacitors	8742541	03-Jun-2014
Tessera, Inc.	Microelectronic assemblies having compliancy and methods therefor	8759973	24-Jun-2014
Tessera, Inc.	Deskewed multi-die packages	8759982	24-Jun-2014
Tessera, Inc.	Conductive pads defined by embedded traces	8772908	08-Jul-2014
Tessera, Inc.	Microelectronic package with stacked microelectronic elements and method for manufacture thereof	8786070	22-Jul-2014
Tessera, Inc.	IMPEDANCE CONTROLLED PACKAGES WITH METAL SHEET OR 2-LAYER RDL	8786083	22-Jul-2014
Tessera, Inc.	Enhanced stacked microelectronic assemblies with central contacts	8787032	22-Jul-2014

Tessera, Inc.	Microelectronic elements having metallic pads overlying vias	8791575	29-Jul-2014
Tessera, Inc.	Microelectronic elements with rear contacts connected with via first or via middle structures	8796135	05-Aug-2014
Tessera, Inc.	Compliant interconnects in wafers	8796828	05-Aug-2014
Tessera, Inc.	Tsop with impedance control	8802502	12-Aug-2014
Tessera, Inc.	Multi-function and shielded 3d interconnects	8809190	19-Aug-2014
Tessera, Inc.	Low stress vias	8816505	26-Aug-2014
Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH JOINED BOND ELEMENTS HAVING LOWERED INDUCTANCE	8816514	26-Aug-2014
Tessera, Inc.	Reliable packaging and interconnect structures	8829680	09-Sep-2014
Tessera, Inc.	Chip assembly having via interconnects joined by plating	8835223	16-Sep-2014
Tessera, Inc.	Three-dimensional system-in-a-package	8841763	23-Sep-2014
Tessera, Inc.	Multi-chip module with stacked face-down connected dies	8841765	23-Sep-2014
Tessera, Inc.	Microelectronic elements with post-assembly planarization	8847376	30-Sep-2014
Tessera, Inc.	Staged via formation from both sides of chip	8847380	30-Sep-2014
Tessera, Inc.	Interconnect structure	8853558	07-Oct-2014

Tessera, Inc.	STACKED MULTI-DIE PACKAGES WITH IMPEDANCE CONTROL	8853708	7-Oct-2014
Tessera, Inc.	Through interposer wire bond using low cte interposer with coarse slot apertures	8872318	28-Oct-2014
Tessera, Inc.	Reconstituted wafer stack packaging with after-applied pad extensions	8883562	11-Nov-2014
Tessera, Inc.	Substrate and assembly thereof with dielectric removal for increased post height	8884432	11-Nov-2014
Tessera, Inc.	Flip chip interconnection with double post	8884448	11-Nov-2014
Tessera, Inc.	Enhanced stacked microelectronic assemblies with central contacts and improved ground or power distribution	8885356	11-Nov-2014
Tessera, Inc.	FAN-OUT MICROELECTRONIC UNIT WLP HAVING INTERCONNECTS COMPRISING A MATRIX OF A HIGH MELTING POINT, A LOW MELTING POINT AND A POLYMER MATERIAL	8890304	18-Nov-2014
Tessera, Inc.	Stacked microelectronic packages having at least two stacked microelectronic elements adjacent one another	8890327	18-Nov-2014
Tessera, Inc.	Stackable molded microelectronic packages	8907466	09-Dec-2014

Tessera, Inc.	Stacked packaging improvements	8927337	06-Jan-2015
Tessera, Inc.	Flip-chip, face-up and face-down centerbond memory wirebond assemblies	8928153	06-Jan-2015
Tessera, Inc.	Enhanced stacked microelectronic assemblies with central contacts and improved thermal characteristics	8941999	27-Jan-2015
Tessera, Inc.	Multiple die stacking for two or more die	8952516	10-Feb-2015
Tessera, Inc.	Multi-chip module with stacked face-down connected dies	8956916	17-Feb-2015
Tessera, Inc.	Semiconductor chip package assembly and method for making same	8957520	17-Feb-2015
Tessera, Inc.	Microelectronic package with terminals on dielectric mass	8957527	17-Feb-2015
Tessera, Inc.	Low cost hybrid high density package	8963310	24-Feb-2015
Tessera, Inc.	Embedded passive integration	8970003	03-Mar-2015
Tessera, Inc.	Vias in porous substrates	8975751	10-Mar-2015
Tessera, Inc.	Dram security erase	8976572	10-Mar-2015
Tessera, Inc.	IMPEDANCE CONTROLLED PACKAGES WITH METAL SHEET OR 2-LAYER RDL	8981579	17-Mar-2015
Tessera, Inc.	Interconnection elements with encased interconnects	8988895	24-Mar-2015

Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH IMPEDANCE CONTROLLED WIREBOND AND CONDUCTIVE REFERENCE ELEMENT	8994195	31-Mar-2015
Tessera, Inc.	Method of making a stacked microelectronic package	8999810	07-Apr-2015
Tessera, Inc.	Multiple die in a face down package	9000583	07-Apr-2015
Tessera, Inc.	Multiple die face-down stacking for two or more die	9013033	21-Apr-2015
Tessera, Inc.	Non-lithographic formation of three-dimensional conductive elements	9018769	28-Apr-2015
Tessera, Inc.	Microelectronic packages with nanoparticle joining	9030001	12-May-2015
Tessera, Inc.	MICROELECTRONIC ASSEMBLY WITH IMPEDANCE CONTROLLED WIREBOND AND REFERENCE WIREBOND	9030031	12-May-2015
Tessera, Inc.	Off-chip vias in stacked chips	9048234	02-Jun-2015
Tessera, Inc.	Packaged semiconductor chips with array	9070678	30-Jun-2015
Tessera, Inc.	Flip-chip, face-up and face-down wirebond combination package	9093291	28-Jul-2015
Tessera, Inc.	Package-on-package assembly with wire bonds to encapsulation surface	9093435	28-Jul-2015

Tessera, Inc.	Stacked microelectronic assembly with tsvs formed in stages with plural active chips	9099296	04-Aug-2015
Tessera, Inc.	Carrier structures for microelectronic elements	9099479	04-Aug-2015
Tessera, Inc.	Microelectronic packages having cavities for receiving microelectronic elements	9105612	11-Aug-2015
Tessera, Inc.	Flip chip assembly and process with sintering material on metal bumps	9117811	25-Aug-2015
Tessera, Inc.	Stackable molded microelectronic packages	9123664	01-Sep-2015
Tessera, Inc.	Systems and methods for producing flat surfaces in interconnect structures	9123703	01-Sep-2015
Tessera, Inc.	Lead structures with vertical offsets	9123713	01-Sep-2015
Tessera, Inc.	Electrical barrier layers	9125333	01-Sep-2015
Tessera, Inc.	IMPEDENCE CONTROLLED PACKAGES WITH METAL SHEET OR 2-LAYER RDL	9136197	15-Sep-2015
Tessera, Inc.	Semiconductor chip assembly and method for making same	9137903	15-Sep-2015
Tessera, Inc.	Single exposure in multi-damascene process	9142508	22-Sep-2015
Tessera, Inc.	Stacked packaging improvements	9153562	06-Oct-2015

Tessera, Inc.	Power boosting circuit for semiconductor packaging	9158352	13-Oct-2015
Tessera, Inc.	Stackable molded microelectronic packages with area array unit connectors	9159708	13-Oct-2015
Tessera, Inc.	High density three-dimensional integrated capacitors	9190463	17-Nov-2015
Tessera, Inc.	Flow underfill for microelectronic packages	9196581	24-Nov-2015
Tessera, Inc.	Low stress vias	9214425	15-Dec-2015
Tessera, Inc.	Microelectronic packages and methods therefor	9218988	22-Dec-2015
Tessera, Inc.	Compliant interconnects in wafers	9224649	29-Dec-2015
Tessera, Inc.	Package-on-package assembly with wire bonds to encapsulation surface	9224717	29-Dec-2015
Tessera, Inc.	Reliable wire structure and method	9245670	26-Jan-2016
Tessera, Inc.	Stacked microelectronic assembly with TSVs formed in stages and carrier above chip	9269692	23-Feb-2016
Tessera, Inc.	Stacked chip-on-board module with edge connector	9281266	08-Mar-2016
Tessera, Inc.	Interconnection element with posts formed by plating	9282640	08-Mar-2016
Tessera, Inc.	Single exposure in multi-damascene process	9287164	15-Mar-2016
Tessera, Inc.	Dram security erase	9299417	29-Mar-2016

Tessera, Inc.	Enhanced stacked microelectronic assemblies with central contacts and improved thermal characteristics	9312239	12-Apr-2016
Tessera, Inc.	Multiple die stacking for two or more die	9312244	12-Apr-2016
Tessera, Inc.	Systems and methods for producing flat surfaces in interconnect structures	9318385	19-Apr-2016
Tessera, Inc.	Substrate and assembly thereof with dielectric removal for increased post height	9318460	19-Apr-2016
Tessera, Inc.	Wearable ultra-thin miniaturized mobile communications	9319499	19-Apr-2016
Tessera, Inc.	Pin attachment	9324681	26-Apr-2016
Tessera, Inc.	Method for manufacturing a fan-out WLP with package	9337165	10-May-2016
Tessera, Inc.	Microelectronic package	9349672	24-May-2016
Tessera, Inc.	Non-lithographic formation of three-dimensional conductive elements	9355901	31-May-2016
Tessera, Inc.	Multi-function and shielded 3d interconnects	9355948	31-May-2016
Tessera, Inc.	Active chip on carrier or laminated chip having microelectronic element embedded therein	9355959	31-May-2016
Tessera, Inc.	Staged via formation from both sides of chip	9362203	07-Jun-2016

Tessera, Inc.	Stacked microelectronic assembly with tsvs formed in stages with plural active chips	9368476	14-Jun-2016
Tessera, Inc.	Method of making a stacked microelectronic package	9378967	28-Jun-2016
Tessera, Inc.	Reliable packaging and interconnect structures	9385036	05-Jul-2016
Tessera, Inc.	Microelectronic packages with nanoparticle joining	9397063	19-Jul-2016
Tessera, Inc.	Interposer having molded low cte dielectric	9406532	02-Aug-2016
Tessera, Inc.	High density three-dimensional integrated capacitors	9431475	30-Aug-2016
Tessera, Inc.	Low-stress tsv design using conductive particles	9433100	30-Aug-2016
Tessera, Inc.	High density three-dimensional integrated capacitors	9437557	06-Sep-2016
Tessera, Inc.	Multiple die face-down stacking for two or more die	9437579	06-Sep-2016
Tessera, Inc.	Stacked microelectronic assemblies	9437582	06-Sep-2016
Tessera, Inc.	Flip chip assembly and process with sintering material on metal bumps	9443822	13-Sep-2016
Tessera, Inc.	Vias in porous substrates	9455181	27-Sep-2016
Tessera, Inc.	Enhanced stacked microelectronic assemblies with central contacts	9461015	04-Oct-2016
Tessera, Inc.	Interconnect structure	9466582	11-Oct-2016

Tessera, Inc.	Multiple die in a face down package	9466587	11-Oct-2016
Tessera, Inc.	INTERCONNECT STRUCTURE	9496236	15-Nov-2016
Tessera, Inc.	Stacked microelectronic assemblies with central contacts	RE45463	14-Apr-2015
The Board of Trustees of the University of Arkansas; Invensas Corporation	Infinitely stackable interconnect device and method	7897503	01-Mar-2011
Ziptronix, Inc.	Self-aligned symmetric intrinsic device	6242794	05-Jun-2001
Ziptronix, Inc.	Self aligned symmetric intrinsic process and device	6368930	09-Apr-2002
Ziptronix, Inc.	Three dimensional device integration method and integrated device	6500694	31-Dec-2002
Ziptronix, Inc.	Method of epitaxial-like wafer bonding at low temperature and bonded structure	6563133	13-May-2003
Ziptronix, Inc.	Three dimensional device integration method and integrated device	6627531	30-Sep-2003
Ziptronix, Inc.	Self aligned symmetric intrinsic process and device	6740909	25-May-2004
Ziptronix, Inc.	Self aligned symmetric intrinsic process and device	6756281	29-Jun-2004
Ziptronix, Inc.	Wafer bonding hermetic encapsulation	6822326	23-Nov-2004
Ziptronix, Inc.	Three dimensional device integration method and integrated device	6864585	08-Mar-2005
Ziptronix, Inc.	Single mask via method and device	6867073	15-Mar-2005

Ziptronix, Inc.	Method for low temperature bonding and bonded structure	6902987	07-Jun-2005
Ziptronix, Inc.	Three dimensional integrated device	6905557	14-Jun-2005
Ziptronix, Inc.	Method for room temperature metal direct bonding	6962835	08-Nov-2005
Ziptronix, Inc.	Three dimensional device integration method and integrated device	6984571	10-Jan-2006
Ziptronix, Inc.	Three dimensional device integration method and integrated device	7037755	02-May-2006
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	7041178	09-May-2006
Ziptronix, Inc.	Method of room temperature covalent bonding	7109092	19-Sep-2006
Ziptronix, Inc.	Three dimensional device integration method and integrated device	7126212	24-Oct-2006
Ziptronix, Inc.	Method of epitaxial-like wafer bonding at low temperature and bonded structure	7332410	19-Feb-2008
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	7335572	26-Feb-2008
Ziptronix, Inc.	Method of room temperature covalent bonding	7335996	26-Feb-2008
Ziptronix, Inc.	Single mask via method and device	7341938	11-Mar-2008
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	7387944	17-Jun-2008

Ziptronix, Inc.	Method of detachable direct bonding at low temperatures	7462552	09-Dec-2008
Ziptronix, Inc.	3D IC method and device	7485968	03-Feb-2009
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	7553744	30-Jun-2009
Ziptronix, Inc.	Room temperature metal direct bonding	7602070	13-Oct-2009
Ziptronix, Inc.	Wafer bonding hermetic encapsulation	7622324	24-Nov-2009
Ziptronix, Inc.	Single mask via method and device	7714446	11-May-2010
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	7807549	05-Oct-2010
Ziptronix, Inc.	Room temperature metal direct bonding	7842540	30-Nov-2010
Ziptronix, Inc.	Method of room temperature covalent bonding	7862885	04-Jan-2011
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	7871898	18-Jan-2011
Ziptronix, Inc.	Wafer scale die handling	7956447	07-Jun-2011
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	8053329	08-Nov-2011
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	8153505	10-Apr-2012
Ziptronix, Inc.	Method of room temperature covalent bonding	8163373	24-Apr-2012
Ziptronix, Inc.	3D IC method and device	8389378	05-Mar-2013
Ziptronix, Inc.	Room temperature metal direct bonding	8524533	03-Sep-2013

Ziptronix, Inc.	3D IC method and device	8709938	29-Apr-2014
Ziptronix, Inc.	Heterogeneous annealing method and device	8735219	27-May-2014
Ziptronix, Inc.	Method of room temperature covalent bonding	8841002	23-Sep-2014
Ziptronix, Inc.	Room temperature metal direct bonding	8846450	30-Sep-2014
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	9082627	14-Jul-2015
Ziptronix, Inc.	3D IC method and device	9171756	27-Oct-2015
Ziptronix, Inc.	Heterogeneous annealing method and device	9184125	10-Nov-2015
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	9331149	03-May-2016
Ziptronix, Inc.	Room temperature metal direct bonding	9385024	05-Jul-2016
Ziptronix, Inc.	Method for low temperature bonding and bonded structure	9391143	12-Jul-2016
Ziptronix, Inc.	Three dimensional device integration method and integrated device	9431368	30-Aug-2016

Owner	Description
Digitaloptics Corporation	Integrated lens barrel, actuator, and mems snubber systems and methods
Digitaloptics Corporation	Mems electrical contact systems and methods
Digitaloptics Corporation	Auto-focus camera module with mems capacitance estimator
Digitaloptics Corporation	Dual lens digital zoom
DigitalOptics Corporation	MEMS auto focus miniature camera module with fixed and movable lens groups
Digitaloptics Corporation MEMS	Motion controlled actuator
Digitaloptics Corporation MEMS	Mems-based optical image stabilization
Digitaloptics Corporation MEMS	Actuator inside of motion control
Digitaloptics Corporation MEMS	Miniature mems actuator assemblies
Digitaloptics Corporation MEMS	Linearly deployed actuators
Digitaloptics Corporation MEMS	Row and column actuator control
Digitaloptics Corporation MEMS	Autofocus camera systems and methods
Digitaloptics Corporation MEMS	MEMS isolation structures
Digitaloptics Corporation MEMS	MEMS fast focus camera module
DTS LLC	HEAD END LOUDNESS MANAGEMENT SYSTEM
DTS LLC	AUDIO ADJUSTMENT SYSTEM
DTS LLC	SYSTEM FOR INCREASING PERCEIVED LOUDNESS OF SPEAKERS
DTS LLC	SYSTEM AND METHODS FOR PROCESSING STEREO AUDIO CONTENT
DTS LLC	IMMERSIVE AUDIO RENDERING SYSTEM
DTS LLC	SYSTEM FOR DYNAMICALLY CREATING AND RENDERING AUDIO OBJECTS
DTS LLC	BASS ENHANCEMENT SYSTEM
DTS, Inc.	MULTIMODE SYNCHRONIOUS RENDERING OF AUDIO AND VIDEO
DTS, Inc.	SCALABLE CODE EXCITED LINEAR PREDICTION BITSREAM
DTS, Inc.	LOUDNESS CONTROL WITH NOISE DETECTION
DTS, Inc.	SYSTEM AND METHOD FOR GENERATING MULTIMEDIA ACCOMPANIMENTS TO BROADCAST DATA
DTS, Inc.	ENCODING AND REPRODUCTION OF THREE DIMENSIONAL AUDIO SOUNDTRACKS
DTS, Inc.	POST-ENCODING BITRATE REDUCTION OF MULTIPLE OBJECT AUDIO
DTS, Inc.	AUTOMATIC MULTI-CHANNEL MUSIC MIX FROM MULTIPLE AUDIO STEMS
DTS, Inc.	LAYERED AUDIO CODING AND TRANSMISSION
DTS, Inc.	LAYERED AUDIO CODING AND TRANSMISSION
DTS, Inc.	DIGITAL AUDIO FILTERS FOR VARIABLE SAMPLE RATES

DTS, Inc.	MULTIPLER-BASED MATRIX MIXING FOR HIGH-CHANNEL COUNT MULTICHANNEL AUDIO
DTS, Inc.	RESIDUAL ENCODING IN AN OBJECT-BASED AUDIO SYSTEM
DTS, Inc.	OBJECT-BASED AUDIO LOUDNESS MANAGEMENT
DTS, Inc.	ROOM CHARACTERIZATION AND CORRECTION FOR MULTI-CHANNEL AUDIO
DTS, Inc.	SPATIAL AUDIO ENCODING AND REPRODUCTION
DTS, Inc.	SYSTEM AND METHOD FOR TRANSMITTING DIGITAL MULTIMEDIA DATA WITH ANALOG BROADCAST DATA
DTS, Inc.	MULTI-RATE SYSTEM FOR ARBITRARY AUDIO PROCESSING
DTS, Inc.	METHOD AND SYSTEM FOR AUDIO PROCESSING OF DIALOG, MUSIC, EFFECT AND HEIGHT OBJECTS
DTS, Inc.	POST-ENCODING BITRATE REDUCTION OF MULTIPLE OBJECT AUDIO
DTS, Inc.	SYSTEM AND METHOD FOR CAPTURING, ENCODING, DISTRIBUTING, AND DECODING IMMERSIVE AUDIO
DTS, Inc.	INTERACTIVE AUDIO METADATA HANDLING
DTS, Inc.	MATRIX DECODER WITH CONSTANT-POWER PAIRWISE PANNING
DTS, Inc.	BASS MANAGEMENT FOR OBJECT-BASED AUDIO
DTS, Inc.	METHOD AND APPARATUS FOR PERSONALIZED AUDIO VIRTUALIZATION
DTS, Inc.	A MULTI-SPEAKER METHOD AND APPARATUS FOR LEAKAGE CANCELLATION
DTS, Inc.	TRANSFORM-BASED AUDIO CODEC AND METHOD WITH SUBBAND ENERGY SMOOTHING
DTS, Inc.	GAIN PHASE EQUALIZATION (GPEQ) FILTER AND TUNING METHODS FOR ASYMMETRIC TRANSAURAL AUDIO REPRODUCTION
DTS, Inc.	AUGMENTED REALITY HEADPHONE REVERBERATION
DTS, Inc.	SYSTEM AND METHOD FOR IMMERSIVE AUDIO REPRODUCTION
DTS, Inc.	SYSTEMS AND METHODS FOR DISTANCE PANNING USING NEAR AND FAR FIELD RENDERING
DTS, Inc.	VARIABLE LENGTH CODING OF INDICES AND BIT SCHEDULING IN A PYRAMID VECTOR QUANTIZER
DTS, Inc.	A METHOD AND SYSTEM FOR LONG TERM PREDICTION IN AUDIO CODECS
DTS, Inc.	AUGMENTED REALITY HEADPHONE REVERBERATION

DTS, Inc.	DEVICE OPTIMIZATION WITH DISTORTION-AWARE BASS ENHANCEMENT, MULTIBAND LIMITING WITH ADAPTIVE BALLISTICS, AND DISTORTION SENSING AND REDUCTION USING DYNAMIC, MULTI-FEATURE ANALYSIS AND MULTIBAND ATTENUATION
iBiquity Digital Corporation	Method For Streaming Through A Data Service Over A Radio Link Subsystem
iBiquity Digital Corporation	ITERATIVE FORWARD ERROR CORRECTION DECODING FOR FM IN-BAND ON-CHANNEL RADIO BROADCASTING SYSTEMS
iBiquity Digital Corporation	Systems and Methods for Digital Radio Broadcast with Cross Platform Reception
iBiquity Digital Corporation	Method and Apparatus for Analog and Digital Audio Blend for HD Radio Receivers
iBiquity Digital Corporation	METHOD AND APPARATUS FOR TRANSMISSION AND RECEPTION OF IN-BAND ON-CHANNEL RADIO SIGNALS INCLUDING COMPLEMENTARY LOW DENSITY PARITY CHECK CODING
iBiquity Digital Corporation	METHOD AND APPARATUS FOR IMPLEMENTING SIGNAL QUALITY METRICS AND ANTENNA DIVERSITY SWITCHING CONTROL
iBiquity Digital Corporation	FM ANALOG DEMODULATOR COMPATIBLE WITH IBOC SIGNALS
iBiquity Digital Corporation	Systems, Methods, and Computer Readable Media for Digital Radio Broadcast Receiver Memory and Power Reduction
iBiquity Digital Corporation	Systems and Methods for Emergency Vehicle Proximity Warnings Using Digital Radio Broadcast
Invensas Corporation	Bva interposer
Invensas Corporation	Micro mechanical anchor for 3d architecture
Invensas Corporation	Microelectronic package with integrated bearing surfaces
Invensas Corporation	Ultra high performance interposer
Invensas Corporation	MICROELECTRONIC ELEMENT WITH BOND ELEMENTS TO ENCAPSULATION SURFACE
Invensas Corporation	Interconnections for a substrate associated with a backside reveal
Invensas Corporation	Chip-size double side connection package and method for manufacturing the same
Invensas Corporation	INTEGRATED CIRCUIT DEVICE
Invensas Corporation	Carrier-less silicon interposer using photo patterned polymer as substrate
Invensas Corporation	Microelectronic assembly with multi-layer support structure
Invensas Corporation	Fine pitch bva using reconstituted wafer for area array at the top for testing
Invensas Corporation	Via Structure for Signal Equalization
Invensas Corporation	INTEGRATED CIRCUITS PROTECTED BY SUBSTRATES WITH CAVITIES, AND METHODS OF MANUFACTURE

Invensas Corporation	MULTILAYER WIRING BOARD FOR AN ELECTRONIC DEVICE
Invensas Corporation	Conductive connections, structures with such connections, and methods of manufacture
Invensas Corporation	Structure and method for integrated circuits packaging with increased density
Invensas Corporation	Low cte component with wire bond interconnects
Invensas Corporation	Back-end-of-line stack for a stacked device
Invensas Corporation	Light emitting diode device with reconstituted led components on substrate
Invensas Corporation	High yield substrate assembly
Invensas Corporation	High performance light emitting diode with vias
Invensas Corporation	Semiconductor die having fine pitch electrical interconnects
Invensas Corporation	Paddle for materials processing
Invensas Corporation	Use of underfill tape in microelectronic components, and microelectronic components with cavities coupled to through-substrate vias
Invensas Corporation	Compact microelectronic assembly having reduced spacing between controller and memory packages
Invensas Corporation	Thin wafer handling and known good die test method
Invensas Corporation	Microelectronic assembly with thermally and electrically conductive underfill
Invensas Corporation	Low cte interposer without tsv structure and method
Invensas Corporation	Device and method for an integrated ultra-high density device
Invensas Corporation	Substrates and methods of manufacture
Invensas Corporation	Holding of interposers and other microelectronic workpieces in position during assembly and other processing
Invensas Corporation	Microelectronic interconnect element with decreased conductor spacing
Invensas Corporation	Rear-face illuminated solid state image sensors
Invensas Corporation	Bond via array for thermal conductivity
Invensas Corporation	Front facing piggyback wafer assembly
Invensas Corporation	Cavities containing multi-wiring structures and devices
Invensas Corporation	Integrated interposer solutions for 2D and 3D IC packaging
Invensas Corporation	Heat spreading substrate with embedded interconnects
Invensas Corporation	Interposers and fabrication methods that use nanoparticle inks and magnetic fields
Invensas Corporation	Microelectronic assemblies formed using metal silicide, and methods of fabrication

Invensas Corporation	Quantum efficiency of multiple quantum wells
Invensas Corporation	Pressing of wire bond wire tips to provide bent-over tips
Invensas Corporation	Embedded graphite heat spreader for 3DIC
Invensas Corporation	Reduced load memory module
Invensas Corporation	Stackable microelectronic package structures
Invensas Corporation	Substrates with through vias with conductive features for connection to integrated circuit elements, and methods for forming through vias in substrates
Invensas Corporation	Advanced device assembly structures and methods
Invensas Corporation	Integrated circuit assemblies with rigid layers used for protection against mechanical thinning and for other purposes, and methods of fabricating such assemblies
Invensas Corporation	Package-on-package assembly with wire bond vias
Invensas Corporation	Optical enhancement of light emitting devices
Invensas Corporation	Method and structures for via substrate repair and assembly
Invensas Corporation	Capacitors using porous alumina structures
Invensas Corporation	Wafer-leveled chip packaging structure and method thereof
Invensas Corporation	Reconfigurable pop
Invensas Corporation	Multichip modules and methods of fabrication
Invensas Corporation	Structure for microelectronic packaging with bond elements to encapsulation surface
Invensas Corporation	Method and structures for heat dissipating interposers
Invensas Corporation	Structures with through vias passing through a substrate comprising a planar insulating layer between semiconductor layers
Invensas Corporation	On-chip impedance network with digital coarse and analog fine tuning
Invensas Corporation	Making electrical components in handle wafers of integrated circuit packages
Invensas Corporation	Multiple bond via arrays of different wire heights on a same substrate
Invensas Corporation	Microelectronic package having wire bond vias and stiffening layer
Invensas Corporation	Electronic structures strengthened by porous and non-porous layers, and methods of fabrication
Invensas Corporation	Selective die electrical insulation by additive process
Invensas Corporation	Embedded packaging with preformed vias
Invensas Corporation	Electrical connector between die pad and z-interconnect for stacked die assemblies

Invensas Corporation	Microelectronic package with stacked microelectronic units and method for manufacture thereof
Invensas Corporation	Porous alumina templates for electronic packages
Invensas Corporation	Multiple bond via arrays of different wire heights on a same substrate
Invensas Corporation	Contact structures with porous networks for solder connections, and methods of fabricating same
Invensas Corporation	Image sensor device
Invensas Corporation	Carrier-less silicon interposer
Invensas Corporation	Bva interposer
Invensas Corporation	Stub minimization using duplicate sets of signal terminals
Invensas Corporation	Semiconductor die mount by conformal die coating
Invensas Corporation	Methods of forming 3-d circuits with integrated passive devices
Invensas Corporation	Microelectronic assemblies with integrated circuits and interposers with cavities, and methods of manufacture
Invensas Corporation	Microelectronic assemblies with stack terminals coupled by connectors extending through encapsulation
Invensas Corporation	Interposers with circuit modules encapsulated by moldable material in a cavity, and methods of fabrication
Invensas Corporation	Compact semiconductor package and related methods
Invensas Corporation	Substrate-less stackable package with wire-bond interconnect
Invensas Corporation	Memory module in a package
Invensas Corporation	Stub minimization using duplicate sets of signal terminals in assemblies without wirebonds to package substrate
Invensas Corporation	Retention optimized memory device using predictive data inversion
Invensas Corporation	Thermal vias disposed in a substrate without a liner layer
Invensas Corporation	Stub minimization using duplicate sets of terminals for wirebond assemblies without windows
Invensas Corporation	Inverted optical device
Invensas Corporation	Support mounted electrically interconnected die assembly
Invensas Corporation	Off substrate kinking of bond wire
Invensas Corporation	Multi-die wirebond packages with elongated windows
Invensas Corporation	Substrate-to-carrier adhesion without mechanical adhesion between abutting surfaces thereof
Invensas Corporation	Localized sealing of interconnect structures in small gaps
Invensas Corporation	Device and method for localized underfill
Invensas Corporation	Batch process for package-on-package

Invensas Corporation	Microelectronic package with consolidated chip structures
Invensas Corporation	Polymer member based interconnect
Invensas Corporation	Method for package-on-package assembly with wire bonds to encapsulation surface
Invensas Corporation	Stub minimization for assemblies without wirebonds to package substrate
Invensas Corporation	Integrated circuit assemblies with reinforcement frames, and methods of manufacture
Invensas Corporation	Stub minimization for wirebond assemblies without windows
Invensas Corporation	Tunable composite interposer
Invensas Corporation	Thermal vias disposed in a substrate proximate to a well thereof
Invensas Corporation	WARPAGE REDUCTION IN STRUCTURES WITH ELECTRICAL CIRCUITRY
Invensas Corporation	CIRCUIT ASSEMBLIES WITH MULTIPLE INTERPOSER SUBSTRATES, AND METHODS OF FABRICATION
Tessera Advanced Technologies	Electronic device, assembly and methods of manufacturing an electronic device
Tessera Advanced Technologies	Method for providing and obtaining content
Tessera Advanced Technologies	Control device, storage device, and storage control method
Tessera Advanced Technologies	Method of forming a cmos structure having gate insulation films of different thicknesses
Tessera Advanced Technologies	Method for providing and obtaining content
Tessera Advanced Technologies	Using biometric user-specific attributes
Tessera Advanced Technologies	Semiconductor device and method of manufacturing same
Tessera, Inc.	Wet etch process and composition for forming openings in a polymer substrate
Tessera, Inc.	Robust multi-layer wiring elements and assemblies with embedded microelectronic elements
Tessera, Inc.	Methods of forming semiconductor elements using micro-abrasive particle stream
Tessera, Inc.	Connector structures and methods
Tessera, Inc.	Stack packages using reconstituted wafers
Tessera, Inc.	Packaged microelectronic elements having blind vias for heat dissipation
Tessera, Inc.	Fine pitch microcontacts and method for forming thereof
Tessera, Inc.	System and method for testing fuse blow reliability for integrated circuits
Tessera, Inc.	THREE-DIMENSIONAL SYSTEM-IN-A-PACKAGE
Tessera, Inc.	Enhanced stacked microelectronic assemblies with central contacts and improved ground or power distribution

Tessera, Inc.	Stacked microelectronic packages having at least two stacked microelectronic elements adjacent one another
Tessera, Inc.	Flip chip interconnection with double post
Tessera, Inc.	Flip-chip, face-up and face-down centerbond memory wirebond assemblies
Tessera, Inc.	Multi-chip module with stacked face-down connected dies
Tessera, Inc.	Low cost hybrid high density package
Tessera, Inc.	Microelectronic elements with post-assembly planarization
Tessera, Inc.	Off-chip vias in stacked chips
Tessera, Inc.	Packaged semiconductor chips with array
Tessera, Inc.	Low-stress vias
Tessera, Inc.	Electrical barrier layers
Tessera, Inc.	Microelectronic packages having cavities for receiving microelectronic elements
Tessera, Inc.	Stackable molded microelectronic packages
Tessera, Inc.	Semiconductor chip assembly and method for making same
Tessera, Inc.	Stacked packaging improvements
Tessera, Inc.	Stackable molded microelectronic packages with area array unit connectors
Tessera, Inc.	Microelectronic packages and methods therefor
Tessera, Inc.	Package-on-package assembly with wire bonds to encapsulation surface
Tessera, Inc.	Stacked microelectronic assembly with TSVs formed in stages and carrier above chip
Tessera, Inc.	Stacked chip-on-board module with edge connector
Tessera, Inc.	Systems and methods for producing flat surfaces in interconnect structures
Tessera, Inc.	DRAM security erase
Tessera, Inc.	Multiple die stacking for two or more die
Tessera, Inc.	Substrate and assembly thereof with dielectric removal for increased post height
Tessera, Inc.	Active chip on carrier or laminated chip having microelectronic element embedded therein
Tessera, Inc.	Fan-out WLP with package
Tessera, Inc.	Staged via formation from both sides of chip
Ziptronix, Inc.	Method of room temperature covalent bonding
Ziptronix, Inc.	Three dimensional device integration method and integrated device
Ziptronix, Inc.	3D IC method and device
Ziptronix, Inc.	Heterogeneous annealing method and device
Ziptronix, Inc.	Room temperature metal direct bonding

Application Number	Application Date
14/327,490	09-Jul-2014
14/585,172	29-Dec-2014
14/798,200	13-Jul-2015
15/060,650	04-Mar-2016
15/076,467	21-Mar-2016
14/101,287	09-Dec-2013
14/507,722	06-Oct-2014
14/733,780	08-Jun-2015
14/746,724	22-Jun-2015
14/887,054	19-Oct-2015
15/063,217	07-Mar-2016
15/076,383	21-Mar-2016
15/166,019	26-May-2016
15/166,920	27-May-2016
13/452494	20-Apr-2012
13/592,182	22-Aug-2012
14/010,405	26-Aug-2013
14/201,655	7-Mar-2014
14/801,652	16-Jul-2015
14/844,994	3-Sep-2015
14/992,938	11-Jan-2016
15,265,609	14-Sep-2016
13/606,918	7-Sep-2012
13/838,697	15-Mar-2013
13/862,036	12-Apr-2013
14/026,984	6-Dec-2013
14/199,706	6-Mar-2014
14/206,868	12-Mar-2014
14/245,882	4-Apr-2014
14/245,903	4-Apr-2014
14/506,187	3-Oct-2014

14/555,324	26-Nov-2014
14/620,544	12-Feb-2015
14/632,997	26-Feb-2015
14/690,935	20-Apr-2015
14/720,605	22-May-2015
14/749,757	25-Jun-2015
14/824,998	12-Aug-2015
14/874,095	2-Oct-2015
14/970,320	15-Dec-2015
15/011,320	29-Jan-2016
15/078,945	23-Mar-2016
15/149,458	9-May-2016
15/236,416	13-Aug-2016
15/242,141	19-Aug-2016
15/242,396	19-Aug-2016
15/253,646	31-Aug-2016
15/290,392	11-Oct-2016
62/290,394	2-Feb-2016
62/332,872	6-May-2016
62/351,585	17-Jun-2016
62/381,479	30-Aug-2016
62/385,879	9-Sep-2016
62/395,882	16-Sep-2016

62/411,415	21-Oct-2016
11/958783	18-Dec-2007
14/266907	1-May-2014
14/580920	23-Dec-2014
14/622260	13-Feb-2015
14/817423	4-Aug-2015
14/920684	22-Oct-2015
14/920720	22-Oct-2015
14/939863	12-Nov-2015
14/957797	3-Dec-2015
13/795,756	12-Mar-2013
13/961,217	07-Aug-2013
13/962,332	08-Aug-2013
13/962,349	08-Aug-2013
14/027571	19-Mar-2015
14/050,215	09-Oct-2013
14/053,481	14-Oct-2013
14/089539	20-Mar-2014
14/096,387	04-Dec-2013
14/096,906	04-Dec-2013
14/157,790	17-Jan-2014
14/206,756	12-Mar-2014
14/214365	17-Sep-2015

14/271959	28-Aug-2014
14/275,519	12-May-2014
14/289,483	28-May-2014
14/289,860	29-May-2014
14/309,703	19-Jun-2014
14/338,327	22-Jul-2014
14/466,992	23-Aug-2014
14/466,993	23-Aug-2014
14/480,373	08-Sep-2014
14/482,981	10-Sep-2014
14/488,187	16-Sep-2014
14/496,159	25-Sep-2014
14/500,858	29-Sep-2014
14/500,874	29-Sep-2014
14/524,280	27-Oct-2014
14/532,806	04-Nov-2014
14/533,728	05-Nov-2014
14/535,159	06-Nov-2014
14/557,120	01-Dec-2014
14/557,562	02-Dec-2014
14/567,918	11-Dec-2014
14/570,570	15-Dec-2014
14/573,461	17-Dec-2014
14/586,580	30-Dec-2014
14/600,595	20-Jan-2015
14/602,984	22-Jan-2015
14/629,271	23-Feb-2015

14/629,487	23-Feb-2015
14/639,789	05-Mar-2015
14/639,942	05-Mar-2015
14/645,811	12-Mar-2015
14/658,763	16-Mar-2015
14/697,460	27-Apr-2015
14/700,780	30-Apr-2015
14/704,714	05-May-2015
14/718,719	21-May-2015
14/727,810	01-Jun-2015
14/729,729	03-Jun-2015
14/733,269	08-Jun-2015
14/740,184	15-Jun-2015
14/775,119	11-Sep-2015
14/809,036	24-Jul-2015
14/809,570	27-Jul-2015
14/815,282	31-Jul-2015
14/824,520	12-Aug-2015
14/829,511	18-Aug-2015
14/833,979	24-Aug-2015
14/841,381	31-Aug-2015
14/850,500	10-Sep-2015
14/852,855	14-Sep-2015
14/868,090	28-Sep-2015
14/870,823	30-Sep-2015
14/871,185	30-Sep-2015

14/883,977	15-Oct-2015
14/887,674	15-Oct-2015
14/925,807	28-Oct-2015
14/942,781	16-Nov-2015
14/945,292	18-Nov-2015
14/950,180	24-Nov-2015
14/952,064	25-Nov-2015
14/962,734	08-Dec-2015
14/969,779	15-Dec-2015
14/977,214	21-Dec-2015
14/980,996	28-Dec-2015
14/995,726	14-Jan-2016
15/005,220	25-Jan-2016
15/017,897	08-Feb-2016
15/042,034	11-Feb-2016
15/050,070	22-Feb-2016
15/060,240	03-Mar-2016
15/065,378	09-Mar-2016
15/066,983	10-Mar-2016
15/069,131	14-Mar-2016
15/075,899	21-Mar-2016
15/086,693	31-Mar-2016
15/096,588	12-Apr-2016
15/131,522	18-Apr-2016
15/143,077	29-Apr-2016
15/144,108	02-May-2016
15/151,176	10-May-2016
15/153,188	12-May-2016

15/156,667	17-May-2016
15/158,963	19-May-2016
15/159,287	19-May-2016
15/165,323	26-May-2016
15/165,837	26-May-2016
15/168,789	31-May-2016
15/171,604	02-Jun-2016
15/174,338	06-Jun-2016
15/181861	6-Oct-2016
15/181872	6-Oct-2016
10/560,717	15-Dec-2005
13/449,640	18-Apr-2012
13/867,770	22-Apr-2013
14/828,281	17-Aug-2015
14/829,218	18-Aug-2015
14/843,726	02-Sep-2015
15/061,444	04-Mar-2016
09/920499	4-Jul-2002
12/287380	7-May-2009
12/842,612	23-Jul-2010
13/183,920	15-Jul-2011
14/036,684	25-Sep-2013
14/145,288	31-Dec-2013
14/168,386	30-Jan-2014
14/286,159	23-May-2014
14/492964	19-Mar-2015
14/523,245	24-Oct-2014

14/529,279	31-Oct-2014
14/532,396	04-Nov-2014
14/589,578	05-Jan-2015
14/623,161	16-Feb-2015
14/628,894	23-Feb-2015
14/708,989	11-May-2015
14/725,975	29-May-2015
14/753,895	29-Jun-2015
14/801,259	16-Jul-2015
14/809,117	24-Jul-2015
14/814,781	31-Jul-2015
14/834,803	25-Aug-2015
14/851,925	11-Sep-2015
14/870,827	30-Sep-2015
14/878,548	08-Oct-2015
14/933,225	05-Nov-2015
14/979,053	22-Dec-2015
15/047,295	18-Feb-2016
15/061,149	04-Mar-2016
15/066,238	10-Mar-2016
15/082,951	28-Mar-2016
15/094,087	08-Apr-2016
15/099,690	15-Apr-2016
15/131,966	18-Apr-2016
15/150,295	09-May-2016
15/174983	29-Sep-2016
14/474,501	02-Sep-2014
14/746,425	22-Jun-2015
14/813,972	30-Jul-2015
14/879,800	09-Oct-2015
14/959,204	04-Dec-2015